NOTE: Dev board has CH32V307VCT6

CH32V20x_30x Datasheet

FOR CH32V203/303/305/307/208xx V2.1

Overview

The CH32Vx series are industrial-grade general-purpose microcontrollers based on Qingke 32-bit RISC-V architecture. All CH32Vx series are equipped with a hardware stack area and fast interrupt entry, which greatly improves the interrupt response speed on the basis of standard RISC-V. CH32V208x is integrated with V4C core, adding memory protection function, and reducing the hardware division cycle at the same time. CH32V303/305/307 is integrated with V4F core, adding single-precision floating-point instruction set, expanding hardware stack area, and having higher computing performance. Product resources: the clock speed can be 144MHz, independent GPIO power supply. It has up to 8 extended USARTs/UARTs, 4 motor timers, and it provides a 32-bit general-purpose timer. The CH32Vx contains USB2.0 high-speed interface (480Mbps) and built-in PHY transceiver. Its Ethernet MAC upgrades to Gigabit and is integrated with 10M-PHY module. It also supports BLE5.3 and so on.

Features

- **Core:**
  - Qingke 32-bit RISC-V core, support multiple instruction set
  - Fast programmable interrupt controller + hardware interrupt stack
  - Branch prediction, conflict handling
  - Single cycle multiplication, hardware division, hardware FPU
  - 144MHz clock speed
- **Memory:**
  - Max 128KB volatile memory SRAM
  - 480KB CodeFlash (zero wait application area + non-zero wait data area)
  - 28KB BootLoader
  - 128B non-volatile system configuration memory
  - 128B user-defined memory
- **Power management and low-power mode:**
  - System power supply V_{DD}: 3.3V (rated)
  - Independent power supply for GPIO unit V_{IO}: 3.3V (rated)
  - Low-power mode: sleep, stop, standby
  - V_{BAT} independently powers RTC and backup register
- **Clock & Reset**
  - Built-in factory-calibrated 8MHz RC oscillator
  - Built-in 40 KHz RC oscillator
  - Built-in PLL, optional CPU clock up to 144MHz
  - External support 3~25MHz high-speed oscillator
  - External support 32.768 KHz low-speed oscillator
  - Power on/down reset, programmable voltage detector
- **Real-time clock (RTC):** 32-bit independent RTC timer
- **2 groups of 18-channel general purpose DMA controllers**
  - 18 channels, support ring buffer
  - Support TIMx/ADC/DAC/USART/I2C/SPI/I2S/SDIO
- **4 groups of OPAs and comparators:** connected with ADC and TIMx
- **12-bit DAC × 2**
- **12-bit ADC × 2**
  - Analog input range: V_{SSA}~V_{DDA}
  - 16 external signals + 2 internal signals
  - On-chip temperature sensor
  - Dual ADC conversion mode
- **16-channels TouchKey detection**
- **Timers**
  - 4 16-bit advanced-control timers, with dead zone control and emergency brake; can offer PWM complementary output for motor control
  - 3 16-bit general-purpose timers, provide input capture/output comparison/PWM/pulse counting/incremental encoder input
  - Single 32-bit or 16-bit general-purpose timer
  - 2 basic timers
  - 2 watchdog timers (independent watchdog and window watchdog)
  - SysTick: 64-bit counter

- **Communication interfaces**:
  - 8 × USART interfaces (including 5 UARTs)
  - 2 × I²C interfaces (support SMBus/PMBus)
  - 3 × SPI interfaces (SPI2, SPI3 for I²S2, I²S3)
  - USB2.0 full-speed device interface (full-speed and low-speed)
  - USB2.0 full-speed host/device interface
  - USB2.0 full-speed OTG interface
  - USB2.0 high-speed host/device interface (built-in PHY)
  - 2 CAN interfaces (2.0B active)
  - SDIO host interface (MMC, SD/SDIO, CE-ATA)
  - FSMC memory interface
  - Digital video port (DVP)
  - Gigabit Ethernet controller MAC, 10M PHY transceiver
  - Bluetooth Low Energy (BLE) 5.3
- **Fast GPIO port**
  - 80 GPIO ports, with 16 external interrupts
- **Security features:** CRC unit, 96-bit unique chip ID
- **Debug mode:** serial 2-wire debug interface
- **Package:** LQFP or QFN

Chapter 1 Series product description

CH32Vx series products are industrial-grade general-purpose enhanced MCUs based on 32-bit RISC-V instruction set and architecture. Its products are divided by function resources into categories such as general purpose, connectivity, and wireless communication. They are extended to each other in terms of package types, peripheral resources and quantities, pin numbers, and device characteristics, but they are compatible with each other in software, functions, and hardware pin configurations. The product iterations and rapid applications provide freedom and convenience for users in product development.

For the features of this series of products, please refer to the datasheet "CH32V20x_30xDS0".

For the peripheral function description, usage and register configuration, please refer to "CH32FV2x_V3xRM".

The data manuals and reference manuals can be downloaded on the official website of WCH: http://www.wch.cn/

Information about the RISC-V instruction set architecture can be downloaded from: https://riscv.org/

This datasheet is the datasheet of CH32V20x and CH32V30x series.

Table 1-1 Series overview

Low-and-medium-density general-purpose device (V203)		High-density general-purpose device (V303)		Connectivity device (V305)	Interconnectivity device (V307)	Wireless device (V208)
Qingke V4B		Qingke V4F				Qingke V4C
32K Flash	64K Flash	128K Flash	256K Flash	128K Flash	256K Flash	128K Flash
10K SRAM	20K SRAM	32K SRAM	64K SRAM	32K SRAM	64K SRAM	64K SRAM
2*ADC(TKey) ADTM 2*GPTM 2*USART SPI I2C USBD USBHD CAN RTC 2*WDG 2*OPA	2*ADC(TKey) ADTM 3*GPTM 4*USART 2*SPI 2*I2C USBD USBHD CAN RTC 2*WDG 2*OPA	2*ADC(TKey) 2*DAC ADTM 3*GPTM 3*USART 2*SPI 2*I2C USBHD CAN RTC 2*WDG 4*OPA	2*ADC(TKey) 2*DAC 4*ADTM 4*GPTM 2*BCTM 8*USART/UART 3*SPI(2*I2S) 2*I2C USBHD CAN RTC 2*WDG 4*OPA TRNG SDIO FSMC	2*ADC(TKey) 2*DAC 4*ADTM 4*GPTM 2*BCTM 5*USART/UART 3*SPI(2*I2S) 2*I2C USB-OTG USBHS(+PHY) 2*CAN RTC 2*WDG 4*OPA TRNG SDIO	2*ADC(TKey) 2*DAC 4*ADTM 4*GPTM 2*BCTM 8*USART/UART 3*SPI(2*I2S) 2*I2C USB-OTG USBHS(+PHY) 2*CAN RTC 2*WDG 4*OPA TRNG SDIO FSMC DVP ETH-1000MAC 10M-PHY	ADC(TKey) ADTM 3*GPTM GPTM (32) 4*USART/UART 2*SPI 2*I2C USBD USBHD CAN RTC 2*WDG 2*OPA ETH-10M(+PHY) BLE5.3

Note: The number or functions of some peripherals of the same type of product may be restricted by the package. Please confirm the package when selecting.

Abbreviations

ADTM: Advanced Timer
GPTM: General Purpose Timer
GPTM (32): 32-bit General Purpose Timer
BCTM: Basic Timer
TKey: Touch Key
OPA: Operational Amplifier, Comparator
TRNG: True Random Number Generator
USBD: Universal Serial Bus Full-speed Device
USBHD: Universal Serial Bus Full-speed Host/Device
USBHS: Universal Serial Bus High-speed Host/Device

Table 1-2 Overview of Cores

Core \ Feature	Instruction Set	Hardware Stack Level	Interrupt Nesting Level	Number of Fast Interrupt Channels	Integer Division Period	Vector table mode	Extended instruction	Memory protection
V4B	IMAC	2	2	4	9	Address or instruction	Support	No
V4C	IMAC	2	2	4	5	Address or instruction	Support	Standard
V4F	IMAFC	3	8	4	5	Address or instruction	Support	Standard

Chapter 2 Specification

The CH32Vx series is a 32-bit RISC MCU based on the RISC-V instruction set architecture (ISA), with a clock speed of 144MHz, and built-in high-speed memory. It has multiple buses working synchronously, and provides a wealth of peripheral functions and enhanced I/O ports. This series of products has built-in 2 12-bit ADC modules, 2 12-bit DAC modules, multiple timers, multi-channel capacitance touch key detection (TKey) and other functions. It

also contains standard and dedicated communication interfaces: I²C, I²S, SPI, USART, SDIO, CAN controller, USB2.0 full-speed host/device controller, USB2.0 high-speed host/device controller (built-in PHY transceiver), digital image interface, Gigabit Ethernet controller, Bluetooth Low Energy (BLE), etc..

The rated working voltage of the product is 3.3V, and the working temperature range is -40℃～85℃ in industrial grade. It supports a variety of power-saving operating modes to meet the product's low-power application requirements.

Various models in the series are different in terms of resource allocation, number of peripherals, peripheral functions, etc., and can be selected as needed.

Available in LQFP48/QFN48/LQFP64M/LQFP100 packages. CH32Vx series can be widely used in motor drive and application control, medical and handheld devices, PC game peripherals, GPS platforms, programmable controllers, inverters, printers, scanners, alarm systems, video intercoms, heating, ventilation and air conditioning systems, etc.

2.1 Model comparison

Table 2-1 CH32V low-and-medium-density general-purpose products resource allocation

Part No. / Differences		CH32V203x						
		F6	G6	K6	K8	C6	C8	RB
Pin count		20	28	32	32	48	48	64
Flash (bytes) (1)		32K	32K	32K	64K	32K	64K	128K(2)
SRAM (bytes)		10K	10K	10K	20K	10K	20K	64K
GPIO port count		16	24	26	26	37	37	51
Timer	Advanced control (16 bits)	1(3)	1(3)	1	1	1	1	1
	General purpose (16 bits)	2(3)	2(3)	2	3	2	3	3
	Watchdog	2 (WWDG + IWDG)						
	SysTick (64 bits)	supported						
RTC		supported						
ADC/TKey (channel@unit count)		9@2	10@2	10@2	10@2	10@2	10@2	16@1
OPA		1	2	2	2	2	2	2

Communication interfaces	USART/UART		1	2	2	2	2	4	4
	SPI		1	1	1	1	1	2	2
	I2C		0	1	1	1	1	2	2
	CAN		1						
	USB (FS)	USBD	1	1	1	1	1	1	1
		USBHD	-				1	1	1
	Ethernet		-						10M
CPU clock speed			Max: 144MHz						
Rated voltage			3.3V						
Operating temperature			Industrial-grade: -40°C~85°C						
Package			TSSOP20	QFN28	LQFP32		LQFP48	LQFP/ QFN48	LQFP64M

Note: 1. Flash bytes represent zero wait run area R_{0WAIT}. For the V203 series, non-zero wait area is (224K-R_{0WAIT}).

2. The 303 series with 128K FLASH and 64K SRAM supports user select word to be configured as one of the following combinations: (128K FLASH+64K SRAM), (144K FLASH+48K SRAM), and (160K FLASH+32K SRAM).

3. In actual application, please confirm the pinouts of the selected device first before using the functions involving pin signals such as PWM and capture in the timer. Devices in some packages may not have the corresponding function pins and such functions cannot be used.

Table 2-2 CH32V high-density general-purpose/connectivity/interconnectivity products resource allocation

Part No. / Differences		CH32V303x				CH32V305		CH32V307		
		CB	RB	RC	VC	FB	RB	RC	WC	VC
Pin count		48	64	64	100	20	64	64	68	100
Flash (bytes) (1)		128K	128K	256K(2)	256K(2	128K	128K	256K(2	256K(2	256K(2
SRAM (bytes)		32K	32K	64K	64K	32K	32K	64K(2	64K(2	64K(2
GPIO port count		37	51	51	80	17	51	51	54	80
GPIO power supply		Shared		Independent supply V_{IO}		Shared	Independent supply V_{IO}			
Timer	Advanced control (16 bits)	1	1	4	4	4(3)	4	4	4	4
	General purpose (16 bits)	3	3	4	4	4(3)	4	4	4	4
	Basic (16 bits)	-	-	2	2	2	2	2	2	2
	Watchdog	2 (WWDG + IWDG)								
	SysTick (24 bits)	supported								
RTC		supported								
ADC/TKey (channel@unit count)		10@2	16@2	16@2	16@2	1@2	16@2	16@2	16@2	16@2
DAC (unit)		2	2	2	2	1	2	2	2	2
OPA		4	4	4	4	-	4	4	4	4

TRNG			-	-	1	1	1	1	1	1	1
Communication interfaces	USART/UART		3	3	8	8	2	5	8	8	8
	SPI		2	2	3	3	1	3	3	3	3
	I2S		-	-	2	2	1	2	2	2	2
	I2C		2	2	2	2	2	2	2	2	2
	CAN		1	1	1	1	1	2	2	2	2
	SDIO		-	-	1	1	-	1	1	1	1
	USB (FS)	USBD	-								
		USBHD	1	1	1	1	-	1	1	1	1
	USB(HS+PHY)		-				1	1	1	1	1
	Ethernet		-						1G MAC+10M PHY		
	DVP		-								1
	FSMC		-			1	-				1
CPU clock speed			Max: 144MHz								
Rated voltage			3.3V								
Operating temperature			Industrial-grade: -40°C~85°C								
Package			LQFP48	LQFP64M		LQFP100	TSSOP20	LQFP64M	LQFP64M	QFN68	LQFP100

Note: 1. Flash bytes represent zero wait run area R_{0WAIT}. For the V303/V305/V307 series, non-zero wait area is (480K-R_{0WAIT}).

2. The products with 256K FLASH+64K SRAM support user select word to be configured as one of several combinations of (192K FLASH+128K SRAM), (224K FLASH+96K SRAM), (256K FLASH+64K SRAM), (288K FLASH+32K SRAM).

3. In actual application, please confirm the pinouts of the selected device first before using the functions involving pin signals such as PWM and capture in the timer. Devices in some packages may not have the corresponding function pins and such functions cannot be used.

Table 2-3 CH32V wireless products resource allocation

Differences \ Part No.		CH32V208			
		GB	CB	RB	WB
Pin count		28	48	64	68
Flash (bytes) (1)		128K(2)	128K(2)	128K(2)	128K(2)
SRAM (bytes)		64K(2)	64K(2)	64K(2)	64K(2)
GPIO port count		21	37	49	53
GPIO power supply		Shared with V_{DD}			Independent V_{IO}
Timer	Advanced control (16 bits)	1	1	1	1
	General purpose (16 bits)	3	3	3	3
	General purpose (32 bits)	1	1	1	1
	Watchdog	2	2	2	2
	SysTick (24 bits)	supported			
RTC		supported			

ADC/TKey (channel@ unit count)			8@1	16@1	16@1	16@1
OPA			1	2	2	2
Communication interfaces	USART/UART		2	4	4	4
	SPI		1	2	2	2
	I2C		1	2	2	2
	CAN		1	1	1	1
	USB (FS)	USBD	1	1	1	1
		USBHD	1	1	1	1
	Ethernet		10M	-	10M	
	BLE 5.3		supported			
CPU clock speed			Max: 144MHz			
Rated voltage			3.3V			
Operating temperature			Industrial-grade: -40℃~85℃			
Package			QFN28	QFN48	LQFP64M	QFN68

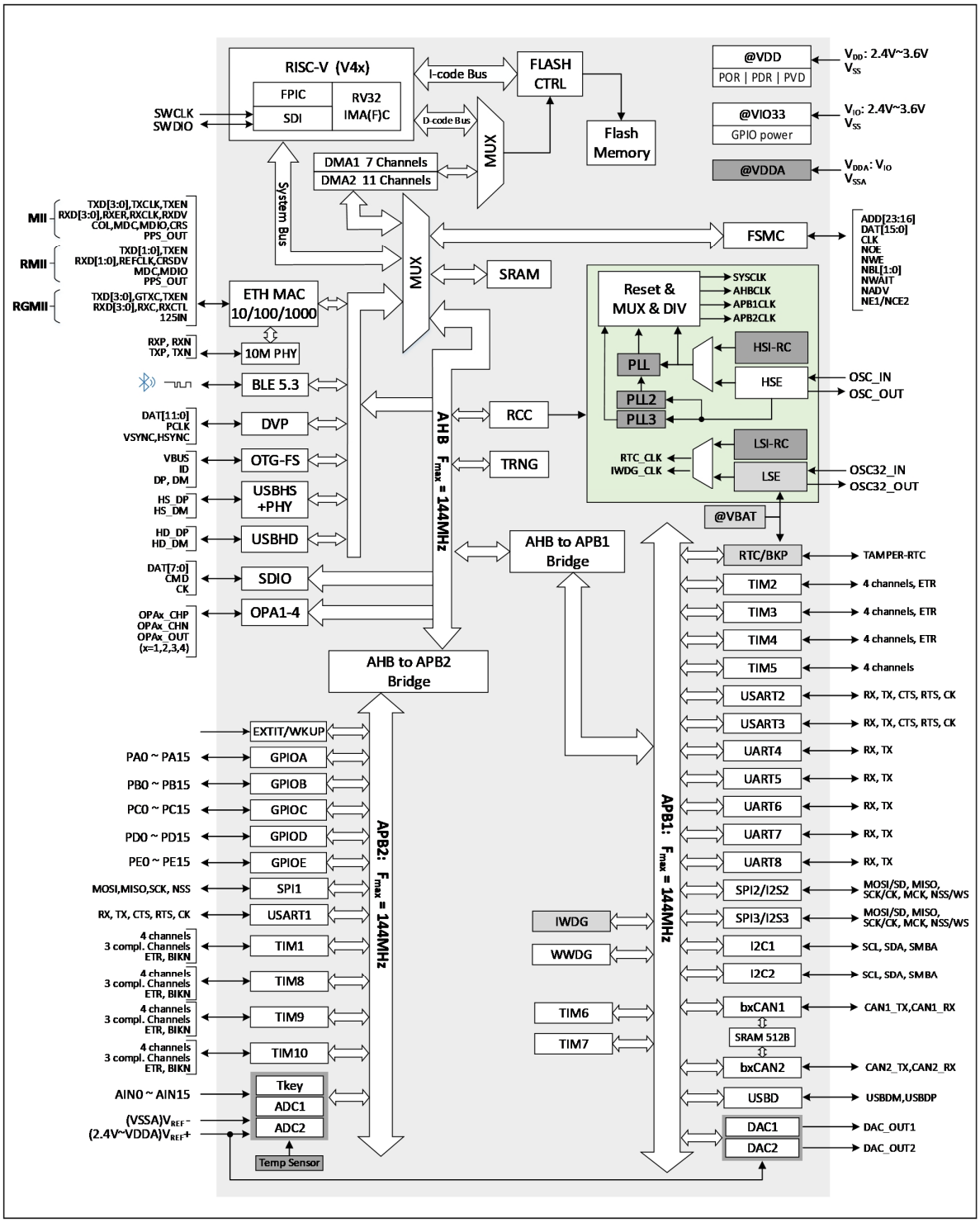
Note: 1. Flash bytes represent zero wait run area R_{0WAIT}. For the V208 series, non-zero wait area is (480K-R_{0WAIT}).

2. The 208 series with 128K FLASH+64K SRAM support user select word to be configured as one of several combinations of (128K FLASH+64K SRAM), (144K FLASH+48K SRAM), and (160K FLASH+32K SRAM).

2.2 System architecture

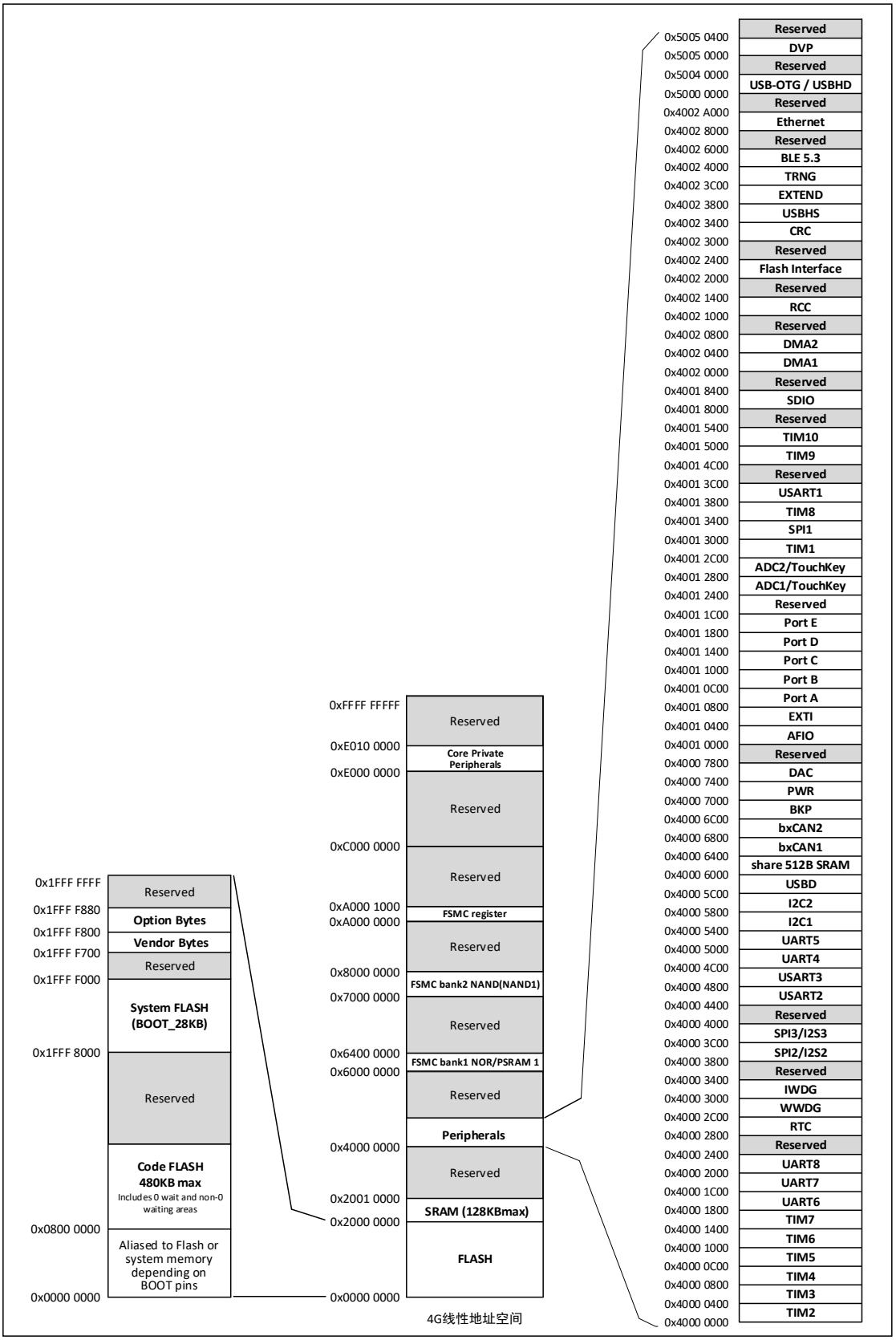
The microcontroller is based on the RISC-V instruction set architecture (ISA) in which the core, arbitration unit, DMA module, SRAM storage and other parts are interacted through multiple sets of buses. A general-purpose DMA controller is integrated in the chip to reduce the burden on the CPU and improve access efficiency. The application of a multi-level clock management mechanism reduces the operating power consumption of peripherals. At the same time, it has a data protection mechanism and measures such as automatic clock switching protection to increase system stability. The following figure is a block diagram of the overall internal structure of the series of products.

Figure 2-1 System block diagram



2.3 Memory map

Figure 2-2 Memory address map



2.4 Clock tree

Four groups of clock sources are introduced into the system: internal high-frequency RC oscillator (HSI), internal low-frequency RC oscillator (LSI), external high-frequency oscillator (HSE), and external low-frequency oscillator (LSE). Among them, the low-frequency clock source provides the clock reference for RTC and independent watchdog. The high-frequency clock source is directly or indirectly multiplied by the PLL and output as the system clock (SYSCLK). The system clock is then provided by each prescaler to provide the AHB domain, APB1 domain, APB2 domain peripheral control clock and sampling or output clock. Some modules need to be directly provided by the PLL clock.

Figure 2-3 CH32V305/307 clock tree block diagram

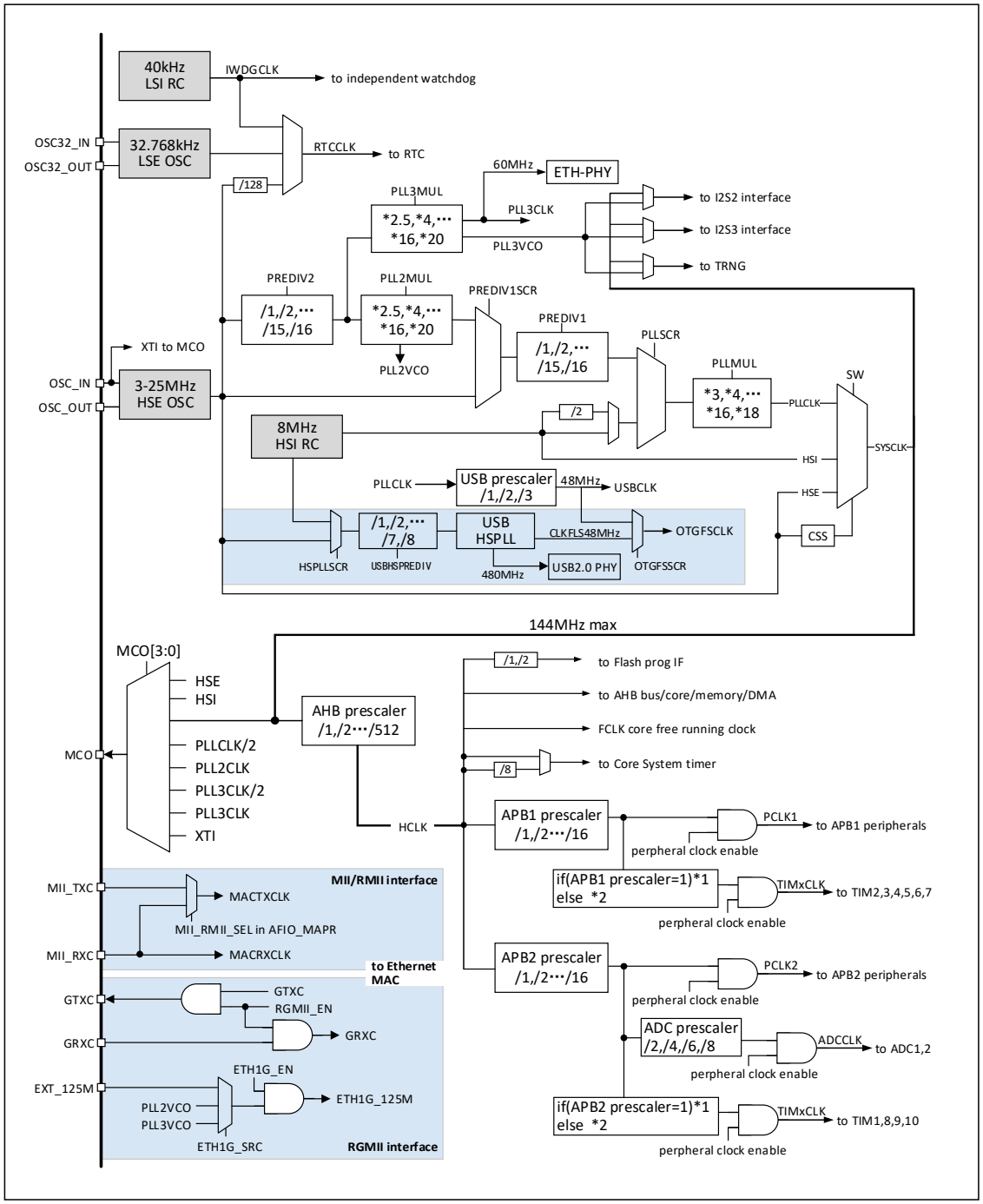
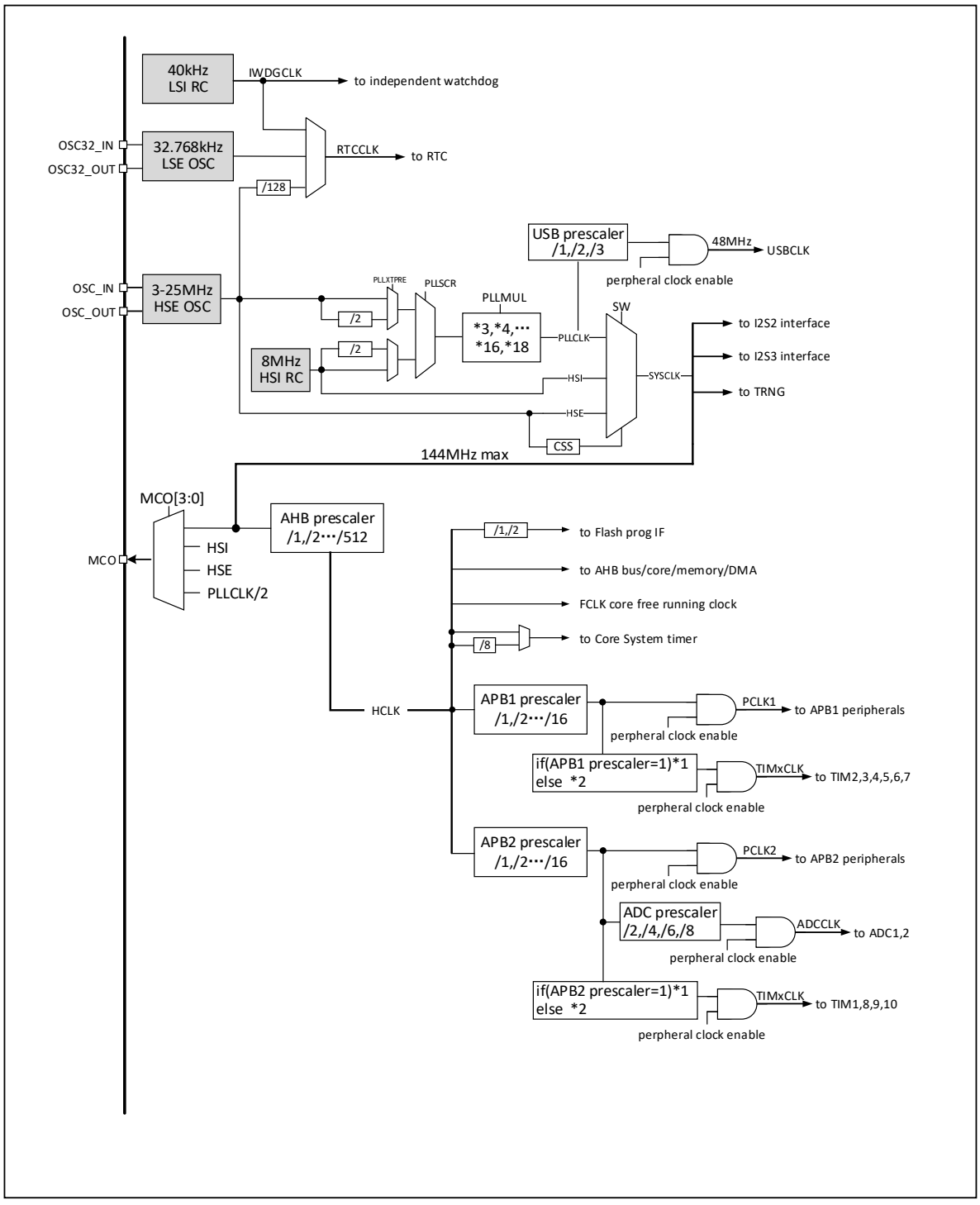


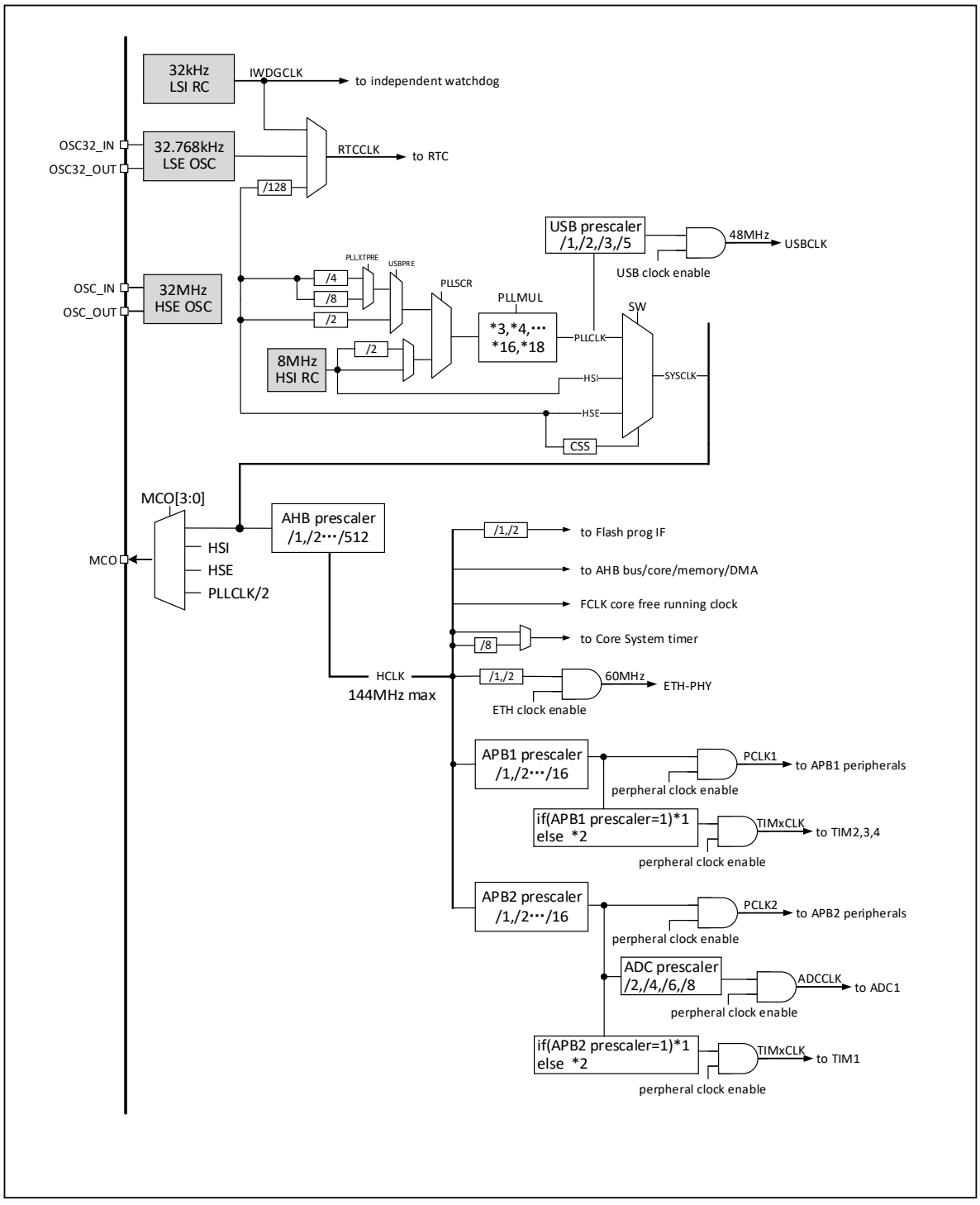
Figure 2-4 CH32V303/203 clock tree block diagram



Note: 1. When using USB, the CPU clock speed must be 48MHz or 96MHz or 144MHz. When system wakes up from stop mode or standby mode, the system will automatically select HSI as the system clock frequency.

2. For the CH32V2030RBT6, the external crystal or clock (HSE) is 32M, and no load capacitor is needed when using the external crystal as it is built in.

Figure 2-5 CH32V208 clock tree block diagram



Note: 1. When using USB, the CPU clock speed must be 48MHz or 96MHz or 144MHz. When the system wakes up from stop mode or standby mode, the system will automatically select HSI as the system clock frequency. If USB and ETH both are enabled, configure PLLCKR=SYSCLK to be 240M.

2. For the CH32V208, the external crystal or clock (HSE) is 32M, and no load capacitor is needed when using the external crystal as it is built in.

2.5 Functional description

2.5.1 RISC-V4B/4C/4F processor

The product is designed based on the RISC-V organization specification for cores V4B, V4C, V4F. V4B and V4C support the RISC-V instruction set IMAC subset, and V4F supports the RISC-V instruction set IMAFC subset, which increases the single-precision floating-point operation. The processor internals are managed in a modular way and contain a Fast Programmable Interrupt Controller (FPIC), memory protection, branch prediction mode, extended instruction support and other units. The external multiple sets of buses are connected with the external unit modules to implement the interaction between the external function modules and the core. Externally, the processor has multiple sets of buses connected to peripherals for interaction.

The processor can be flexibly applied in different scenarios, such as small-area low-power embedded scenarios, high-performance application operating system scenarios, etc., due to its minimal instruction set, multiple working modes, and modular customization extensions.

- Support machine and user privilege mode
- Fast Programmable Interrupt Controller (FPIC)
- Multi-level hardware interrupt stack
- Serial 2-wire debugging interface
- Standard memory protection design
- Static or dynamic branch prediction, efficient jump, conflict detection
- Custom extended instructions

2.5.2 On-chip memory and boot mode

Up to 128K bytes of built-in SRAM area, used to store data, data will be lost after power failure. The specific capacity depends on the corresponding chip model.

Up to 480K bytes of built-in program Flash memory (Code FLASH), used for user application and constant data storage, including zero wait program run area and non-zero wait area. The specific size depends on the corresponding chip model.

Built-in 28K byte system memory (System FLASH), used for system boot program storage (manufacturer curing boot loader).

128 bytes are used for system non-volatile configuration word storage, and 128 bytes are used for user selection word storage.

At startup, one of 3 boot modes can be selected through the boot pins (BOOT0 and BOOT1):

- Boot from program flash
- Boot from system memory
- Boot from internal SRAM

The bootloader is stored in the system memory, and the contents of the program Flash can be reprogrammed through the USART1 and USB interface.

2.5.3 Power supply scheme

- V_{DD} = 2.4～3.6V: Power supply for some I/O pins and internal voltage regulator.
- V_{IO} = 2.4～3.6V: It supplies power to most of the I/O pins and the Ethernet module, which determines the pin output high voltage amplitude. Normal work during operation, the V_{IO} voltage cannot be higher than the V_{DD} voltage.

- V_{DDA} = 2.4～3.6V: It supplies power to the analog part of the high-frequency RC oscillator, ADC, temperature sensor, DAC and PLL. The V_{DDA} voltage must be the same as the V_{IO} voltage (If V_{DD} is powered down and V_{IO} is live, Then V_{DDA} must be live and consistent with VIO). When using ADC, V_{DDA} must not be less than 2.4V.
- V_{BAT} = 1.8～3.6V: When V_{DD} is turned off, (through the internal power switch) independently powers the RTC, external low-frequency oscillator and backup registers. (Pay attention to V_{BAT} power supply)

2.5.4 Power supply monitor

This product integrates a power-on reset (POR)/power-down reset (PDR) circuit, which is always in working condition to ensure that the system is in supply. It works when the power exceeds 2.4V; when V_{DD} is lower than the set threshold ($V_{POR/PDR}$), the device is placed in the reset state without using an external reset circuit.

In addition, the system is equipped with a programmable voltage monitor (PVD), which needs to be turned on by software to compare the voltage of V_{DD} power supply with the set threshold V_{PVD}

Turn on the corresponding edge interrupt of PVD, and you can receive interrupt notification when V_{DD} drops to the PVD threshold or rises to the PVD threshold. Refer to Chapter 4 for the values of $V_{POR/PDR}$ and V_{PVD}.

2.5.5 Voltage regulator

After reset, the regulator is automatically turned on, and there are 3 operation modes according to the application mode.

- ON mode: normal operation, providing stable core power.
- Low-power mode: When the CPU enters Stop mode, the regulator can be selected to run with low power consumption.
- OFF mode: When the CPU enters Standby mode, it automatically switches the regulator to this mode, the voltage regulator output is in high impedance, and the core power.

The voltage regulator is always ON after reset. It is OFF in Standby mode, and the regulator output is in high impedance.

2.5.6 Low-power mode

The system supports 3 low-power modes, which can be selected for low power consumption, short start-up time and multiple wake-up events to achieve the best balance.

- Sleep mode

In sleep mode, only the CPU clock is stopped, but all peripheral clocks are powered normally and the peripherals are in a working state. This mode is the shallowest Low power mode, but it is the fastest mode to wake-up the system.
Exit condition: any interrupt or wake-up event.

- Stop mode

In this mode, the FLASH enters low power mode, and the PLL, HSI RC oscillator and HSE crystal oscillator are turned off. In the case of keeping the contents of SRAM and registers not lost, the stop mode can achieve the lowest power consumption.
Exit conditions: any external interrupt/event (EXTI signal), external reset signal on NRST,
IWDG reset, among which EXTI signal includes one of 16 external I/O ports, PVD output, RTC alarm clock, Ethernet wake-up signal or USB wake-up signal.

- Standby mode

In this mode, the main LDO of the system is turned off, the low-power LDO supplies power to the wake-up circuit, all other digital circuits are powered off, and the FLASH is powered off. The system wakes up from standby mode will generate a reset, and SBF (PWR_CSR) will be set at the same time. After waking up, check the SBF status to know the low-power mode before waking up. SBF is cleared by the CSBF (PWR_CR) bit. In the standby mode, the contents of 32KB of SRAM can be kept (depending on the planning and configuration before going to bed), and the contents of the backup registers are kept.
Exit conditions: any external interrupt/event (EXTI signal), external reset signal on NRST, IWDG reset, a rising edge on the WKUP pin, where EXTI signal includes one of 16 external I/O ports, RTC alarm clock, Ethernet Wake-up signal, USB.

2.5.7 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit uses a fixed polynomial generator to generate a CRC code from a 32-bit data word. In many applications, CRC-based technology is used to verify the consistency of data transmission or storage. Within the scope of the EN/IEC 60335-1 standard, a means of detecting flash errors is provided. The CRC calculation unit can be used to calculate the signature of the software in real time and compare it with the signature generated when the software is linked and generated.

2.5.8 Fast programmable interrupt controller (FPIC)

The product has a built-in Fast Programmable Interrupt Controller (FPIC), which supports up to 255 interrupt vectors, and provides flexible interrupt management functions with minimal interrupt latency. The current product manages 8 core private interrupts and 88 peripheral interrupt management, and other interrupt sources are reserved. FPIC registers can be accessed in user and machine privileged modes.

- 88+3 individual maskable interrupts
- a non-maskable interrupt NMI
- Support hardware interrupt stack (HPE) without instruction overhead
- 4-channel vector table free interrupts (VTF)
- Support vector table mode of address or instruction module
- Configurable interrupt nesting depth, up to 8 levels
- Support interrupt tail-chaining

2.5.9 External interrupt/event controller (EXTI)

The external interrupt/event controller contains a total of 19 edge detectors for generating interrupt/event requests. Each interrupt line can independently configure its trigger event (rising edge or falling edge or both edges), and can be individually masked; the suspend register maintains all interrupt request states. EXTI can detect that the pulse width is smaller than the clock period of the internal APB2. Up to 80 general-purpose I/O ports can be connected to 16 external interrupt lines.

2.5.10 General DMA controller

The system has built-in 2 groups of general-purpose DMA controllers, manages 18 channels in total, and flexibly handles high-speed data transmission from memory to memory, peripherals to memory, and memory to peripherals, and supports ring buffer mode. Each channel has a dedicated hardware DMA request logic to support one or more peripherals' access requests to the memory. The access priority, transfer length, source address and destination address of the transfer can be configured.

The main peripherals used by DMA include: general/advanced/basic timers TIMx, ADC, DAC, I²S, USART, I²C, SPI, and SDIO.

Note: DMA1, DMA2 and CPU access the system SRAM after arbitration by the arbiter.

2.5.11 Clock and Boot

The system clock source HSI is turned on by default. After the clock is not configured or reset, the internal 8MHz RC oscillator is used as the default CPU clock, and then an external 3～25MHz clock or PLL clock can be additionally selected. When the clock security mode is turned on, if the HSE is used as the system clock (directly or indirectly), the system clock will automatically switch to the internal RC oscillator when the external clock is detected to be invalid, and the HSE and PLL will be automatically turned off at the same time; In power consumption mode, the system will automatically switch to the internal RC oscillator after waking up. If the clock interrupt is enabled, the software can receive the corresponding interrupt.

Multiple prescalers are used to configure the frequency of AHB. The high-speed APB (APB2) and low-speed APB (APB1) regions provide peripheral clocks with a maximum frequency of 144MHz. Refer to the clock tree block diagram in Figure 2-3. The clock source of the I²S unit is another dedicated PLL (PLL3), so that the I²S master clock can generate all standard sampling frequencies between 8 kHz and 192 kHz.

2.5.12 Real time clock (RTC) and backup registers

The RTC and the backup register are in the backup power supply area inside the system. When V_{DD} is valid, it is powered by V_{DD}, and when V_{DD} is invalid, the internal power is automatically switched to the V_{BAT} pin.

The RTC real-time clock is a set of 32-bit programmable counters, and the time base supports 20-bit prescaler for measurement in a longer period of time. The clock reference source is a high-speed external clock divided by 128 (HSE/128), external crystal low-frequency oscillator (LSE) or internal low-power RC oscillator (LSI). The LSE also has a backup power supply area, so when the LSE is selected as the RTC time base, the RTC setting and time can remain unchanged after the system resets or wakes up from standby mode.

The backup register contains up to 42 16-bit registers, which can be used to store 84 bytes of user application data. This data can continue to be maintained after wake-up from standby, or system reset or power reset. When the intrusion detection function is turned on, once the intrusion detection signal is valid, all contents in the backup register will be cleared.

2.5.13 Analog-to-digital converter (ADC) and touch key capacitance detection (TKey)

The product is embedded with 2 12-bit analog/digital converters (ADC), sharing up to 16 external channels and 2 internal channels for sampling. The programmable channel sampling time can realize single, continuous, scanning or discontinuous conversion. And supports dual ADC conversion mode. The analog watchdog function is provided to allow very precise monitoring of one or more selected channels for monitoring the signal voltage of the channel. It supports external event trigger conversion, the trigger source includes the internal signal and external pin of the on-chip timer; it also supports the use of DMA operations.

ADC internal channel sampling includes 1 channel of built-in temperature sensor sampling and 1 channel of internal reference power sampling. The temperature sensor generates a voltage that varies linearly with temperature. The temperature sensor is internally connected to the IN16 input channel, which is used to convert the output of the sensor to a digital value.

The capacitance touch key detection unit provides up to 16 detection channels, multiplexing the external channels of the ADC module. The detection result is converted and output by the ADC module, and the state of the touch key is recognized by the user software.

2.5.14 Digital-to-analog converter (DAC)

The product is embedded with 2 12-bit voltage output digital/analog converters (DAC), converts 2 digital signals into 2 analog voltage signals and outputs them, supports dual DAC channel independent or synchronous conversion, supports external event trigger conversion, trigger sources include Internal signals and external pins of the on-chip timer (EXTI line 9). Triangular wave and noise generation can be realized. It supports the use of DMA operations.

2.5.15 Timer and watchdog

The timers in the system include advanced timers, general timers, basic timers, watchdog timers, and system time base timers. The number of timers included in different products in the series is different, please refer to Table 2-2 for details.

Table 2-2 Timer comparison

Timer		Resolution	Count Type	Time Base	DMA	Function
Advanced control timer	TIM1	16 bits	Up Down Up/down	APB2 time domain 16-bit divider	Supported	PWM complementary output, single pulse output Input capture Output compare Timer count
	TIM8					
	TIM9					
	TIM10					
General purpose timer	TIM2	16 bits	Up Down Up/down	APB1 time domain 16-bit divider	Supported	Input capture Output compare Timer count
	TIM3					
	TIM4					
	TIM5(1)	16/32 bits				
Basic timer	TIM6	16 bits	Up	APB1 time domain 16-bit divider	Supported	Timing count
	TIM7					
Window watchdog		7 bits	Down	APB1 time domain 4 types of frequency division	Not supported	Timing Reset the system (normal work)
Independent watchdog		12 bits	Down	APB1 time domain 7 types of frequency division	Not supported	Timing Reset the system (normal work + low-power work)
SysTick Timer		64 bits	Up/down	SYSCLK or SYSCLK/8	Not supported	Timing

Note 1: TIM5 in CH32V208 (wireless type) is a 32-bit general-purpose timer.

- Advanced control timer

The advanced control timer is a 16-bit auto-loading up/down counter with a 16-bit programmable prescaler. In addition to the complete general-purpose timer function, it can be regarded as a three-phase PWM generator distributed to 6 channels, with a complementary PWM output function with dead zone insertion, allowing the timer to be updated after a specified number of counter cycles to repeat Counting cycle, braking

function, etc. Many functions of the advanced control timer are the same as the general timer, and the internal structure is also the same. Therefore, the advanced control timer can cooperate with other TIM timers through the timer link function to provide synchronization or event link functions.

- General purpose timer

The general timer is a 16-bit or 32-bit auto-loading up/down counter with a programmable 16-bit prescaler and 4 independent channels. Each channel supports input capture, output comparison, and PWM generation and single pulse mode output. It can also work with advanced control timers through the timer link function to provide synchronization or event link functions. In debug mode, the counter can be frozen while the PWM outputs are disabled, thereby cutting off the switches controlled by these outputs. Any general-purpose timer can be used to generate PWM output. Each timer has an independent DMA request mechanism. These timers can also process signals from incremental encoders, as well as digital outputs from 1 to 3 Hall sensors.

- Basic timer

The basic timer is a 16-bit auto-load counter that supports a 16-bit programmable prescaler. Digital-to-analog conversion (DAC) can provide a clock and trigger the synchronization circuit of the DAC. The basic timers are independent of each other and do not share any resources with each other.

- Independent watchdog

The independent watchdog is a configurable 12-bit down counter that supports 7 frequency division factors. The clock is provided by an internal independent 40 kHz RC oscillator (LSI); because the LSI is independent of the main clock, it can run in stop and standby modes. IWDG is outside the main program and can work completely independently. Therefore, it is used to reset the entire system when a problem occurs, or as a free timer to provide timeout management for the application. It can be configured as software or hardware to start the watchdog through the option byte. In debug mode, the counter can be frozen.

- Window Watchdog

The window watchdog is a 7-bit down counter and can be set to free-running. It can be used to reset the entire system when a problem occurs. It is driven by the main clock and has an early warning interrupt function; in the debug mode, the counter can be frozen.

- SysTick Timer

This is a 64-bit optional increment or decrement counter that comes with the core controller. It is used to generate SYSTICK anomalies (exception number: 15). It can be dedicated to the real-time operating system (RTOS) to provide a "heartbeat" tick for the system, or it can be used as a standard 64-bit counter. It has an automatic reload function and a programmable clock source.

2.5.16 Communication interface

2.5.16.1 Universal Synchronous/Asynchronous Receiver Transmitter (USART)

The product provides 3 groups of Universal Synchronous/Asynchronous Receiver Transmitters (USART1, USART2, USART3), and 5 groups of Universal Asynchronous Receiver Transmitters (UART4, UART5, UART6, UART7, UART8). It supports full-duplex asynchronous communication, synchronous one-way communication and half-duplex single-wire communication. It also supports LIN (Local Interconnect Network), compatible with ISO7816 smart card protocol and IrDA SIR ENDEC transmission codec specification, and modem (CTS/RTS hardware flow control) operation. It also allows multi-processor communication. It uses a fractional baud rate generator system and supports DMA operation continuous

communication.

2.5.16.2 Serial Peripheral Interface (SPI)

Up to 3 groups of serial peripherals interface (SPI) provide master or slave operation, dynamic switching. Support multi-master mode, full-duplex or half-duplex synchronous transmission, support basic SD card and MMC mode. Programmable clock polarity and phase, data bit width provides 8 or 16-bit selection, reliable communication hardware CRC generation/check, and supports DMA operation continuous communication.

2.5.16.3 I2S (audio) port

The highest 2 standard I²S interfaces (multiplexed with SPI2 and SPI3) work in master or slave mode. The software can be configured as a 16/32-bit data packet transmission frame, supports audio sampling frequencies from 8kHz to 192kHz, and supports 4 audio standards. In master mode, its master clock can be output to an external DAC or CODEC (decoder) at a fixed 256 times audio sampling frequency, and supports DMA.

2.5.16.4 I2C bus

Up to 2 I²C bus interfaces can work in multi-master mode or slave mode, perform all I²C Bus specific timing, protocol, arbitration, etc. It supports both standard and fast speed, and is compatible with SMBus2.0.

The I²C interface provides 7-bit or 10-bit addressing, and supports dual slave addressing in 7-bit slave mode. It integrates built-in hardware CRC generator/checker. It also supports DMA operation and supports SMBus bus version 2.0 / PMBus bus.

2.5.16.5 Controller Area Network (CAN)

The CAN interface is compatible with specifications 2.0A and 2.0B (active), the baud rate is up to 1Mbits/s, and it supports time-triggered communication. It can receive and send standard frames with 11-bit identifiers, as well as extended frames with 29-bit identifiers. It has 3 sending mailboxes and 2 3-level deep receiving FIFOs.

Products with 2 CAN controllers share 28 configurable filters and 512 bytes of SRAM memory resources.

With 1 set of CAN controller products, there are only 14 configurable filters, and share a dedicated 512-byte SRAM memory with the USBD module for data transmission and reception. When USBD and CAN are used at the same time, in order to prevent access to SRAM conflicts, USBD can only use the lower 384 bytes.

2.5.16.6 Universal Serial Bus device (USBD)

The product is embedded with a USB2.0 full-speed controller, which complies with the USB2.0 Fullspeed standard. USBD provides 16 configurable USB device endpoints, supports low-speed devices and full-speed devices, supports control/batch/synchronization/interrupt transmission, double buffer mechanism, USB suspend/resume operations, and has standby/wake-up functions. The USB dedicated 48MHz clock is directly generated by the internal main PLL frequency division.

2.5.16.7 Universal Serial Bus USB2.0 full-speed Host/Device controller (USBHD)

The USB2.0 full-speed host controller and device controller (USBHD) follow the USB2.0 Fullspeed standard. It provides 16 configurable USB device endpoints and a set of host endpoints. Support control/batch/synchronization/interrupt transmission, double buffer mechanism, USB bus suspend/resume operation, and provide standby/wake-up functions. The 48MHz clock dedicated to the USBHD module is

directly generated by the internal main PLL frequency division (the PLL must be 144MHz or 96MHz or 48MHz).

2.5.16.8 Universal Serial Bus USB2.0 full-speed OTG (OTG-FS)

OTG_FS is a dual-role USB controller that supports the functions of the host side and the device side, and is compatible with the On-The-Go Supplement to the USB2.0 specification. At the same time, the controller can also be configured as a controller that only supports host-side or device-side functions, and is compatible with the USB2.0 full-speed specification. The controller uses a 48MHz clock derived from the PLL frequency division. The main features include:

- Support (the physical layer of the OTG_FS controller) USB On-The-Go Supplement, defined as an optional item OTG protocol in the Revision1.3 specification
- Configure USB full-speed host, USB full-speed/low-speed device, USB dual-role device through software
- Provide power saving function
- Support control transmission, batch transmission, interrupt transmission, real-time/synchronous transmission
- Provide bus reset, suspend, wake up and resume functions

2.5.16.9 Universal serial bus USB2.0 high-speed host/device controller (USBHS)

The USB2.0 high-speed controller has the dual roles of a host controller and a device controller, and has an embedded USB-PHY transceiver unit. When used as a host controller, it can support low-speed, full-speed, and high-speed USB devices. When used as a device controller, it can be flexibly set to low-speed, full-speed or high-speed mode to adapt to various applications. The main features include:

- Support for USB 2.0, USB 1.1, USB 1.0 protocol specifications
- Support for control transmission, batch transmission, interrupt transmission, real-time/synchronous transmission
- bus reset, suspend, wake up and resume functions
- Support for high-speed HUB
- 8 groups of upper and lower transmission channels in device mode, and support the configuration of 16 endpoint numbers
- Except for device endpoint 0, all other endpoints support data packets up to 1024 bytes, and double buffering can be used

2.5.16.10 Digital video port (DVP)

DVP (Digital Video Port) is used to connect the camera module to receive the image data stream. It provides 8/10/12bit parallel interface communication. It supports image data organized in original line and frame formats, such as YUV, RGB, etc., and also supports compressed image data streams such as JPEG format. When receiving, it mainly relies on VSYNC and HSYNC signal synchronization. It also supports image cropping.

2.5.16.11 SDIO host controller

The SDIO host interface provides operation interfaces for multimedia cards (MMC), SD memory cards, SDIO cards, and CE-ATA devices. It supports 3 different data bus modes: 1-bit (default), 4-bit and 8-bit. In 8-bit mode, the interface can make the data transfer rate up to 48MHz. This interface is fully compatible with Multimedia Card System Specification 4.2 (forward compatible), SD I/O Card Specification 2.0, SD Memory Card Specification 2.0, and CE-ATA Digital Protocol Specification 1.1.

2.5.16.12 Flexible static memory controller (FSMC)

The FSMC interface mainly provides a synchronous or asynchronous memory interface, and supports devices such as SRAM, PSRAM, NOR, and NAND. The internal AHB transmission signal is converted into a suitable external communication protocol, allowing continuous access to 8/16/32-bit data. And the sampling delay time can be flexibly configured to meet the timing of different devices.

In addition, FSMC can also be used for most graphics LCD controller interfaces. It supports Intel 8080 and Motorola 6800 modes, making it easy to build a simple graphics application environment or a high-performance solution for dedicated acceleration controllers.

2.5.16.13 Gigabit Ethernet controller (MAC, +10M PHY)

The product provides a Gigabit Ethernet Media Access Controller (MAC) that meets the IEEE 802.3-2002 standard, which acts as the data link layer. Its Link supports up to 1Gbps, and provides MII/RMII/RGMII interfaces to connect to external PHY (Gigabit /100M/speed self-adaptive, built-in 10M PHY transceiver). The application is combined with TCP/IP protocol stack interface to realize the development of network products. The main features include:

- Complying with IEEE.802.3 standard
- RGMII, RMII, MII interface, connect external Ethernet PHY transceiver
- Support for full-duplex operation, support 10/100/1000Mbps data transmission rate
- The hardware automatically completes IPv4 and IPv6 packet integrity check, IP/ICMP/UDP/TCP packet check and computer frame length filling
- Multiple MAC address filtering modes
- SMI configuring and managing external PHY

2.5.17 General-purpose input and output (GPIO)

The system provides 5 groups of GPIO ports with a total of 80 GPIO pins. Each pin can be configured by software as output (push-pull or open-drain), input (with or without pull-up or pull-down) or multiplexed peripheral function port. Most GPIO pins are shared with digital or analog multiplexed peripherals. Except for ports with analog input functions, all GPIO pins have high current passing capabilities. A locking mechanism is provided to freeze the IO configuration to avoid accidental writing to the I/O register.

Most of the IO pins in the system are provided by V_{IO}. Changing the V_{IO} power supply will change the high value of the IO pin output level to adapt to the external communication interface level. Please refer to the pin description for specific pins.

2.5.18 True random number generator (TRNG)

The product is integrated with a true random number generator, which provides a 32-bit true random number through the internal analog circuit.

2.5.19 Operational amplifier/comparator (OPA)

The product has built-in 4 groups of operational amplifiers/comparators, and the internal selection is linked to the ADC and TIMx peripherals. Its input and output can be selected by changing the configuration to select multiple channels. It supports to amplify the external analog small signal and send it to the ADC to realize the small signal ADC conversion. It can also complete the signal comparator function. The comparison result is output by GPIO or directly connected to the input channel of TIMx.

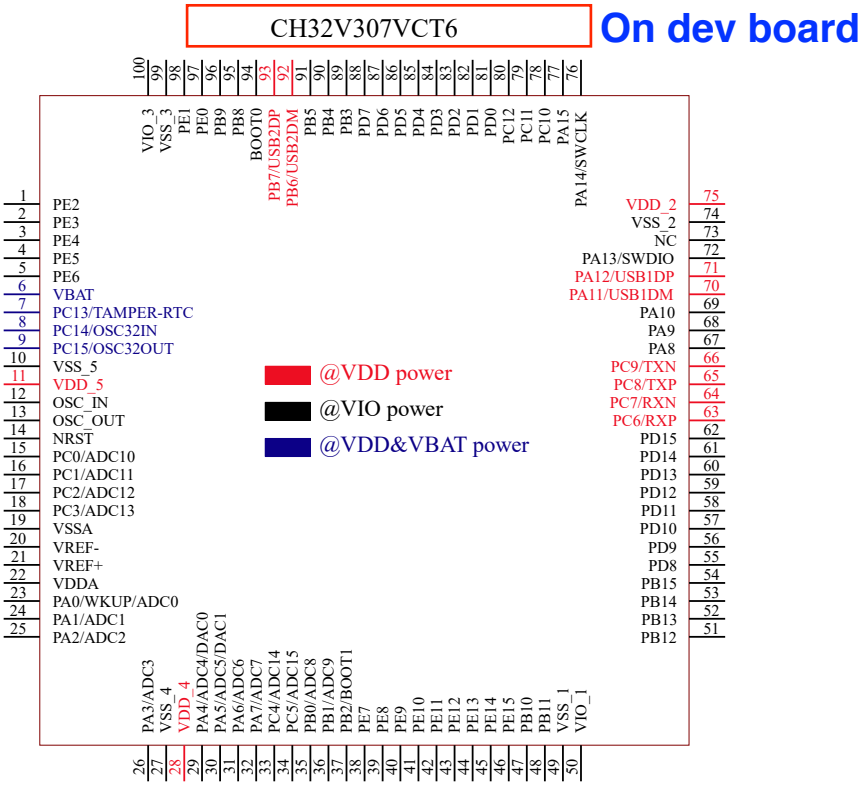
2.5.20 Serial debug interface (SDI)

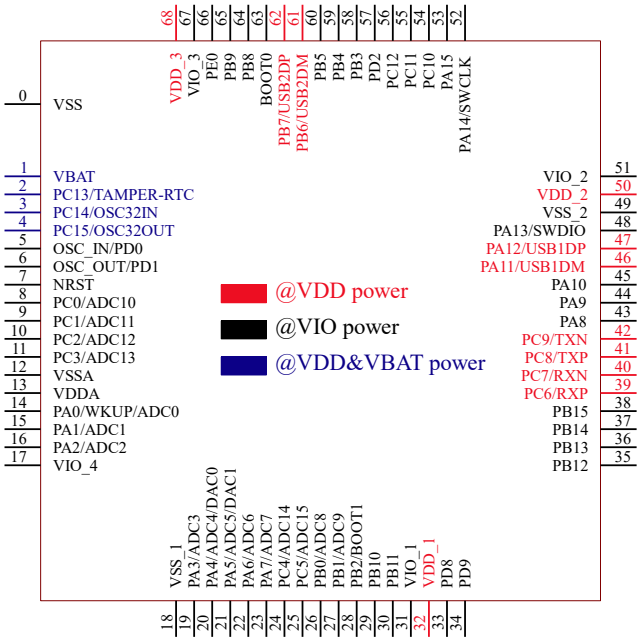
The core comes with a serial 2-wire debug interface, including SWDIO and SWCLK pins. After the system is powered on or reset, the debug interface pin function is enabled by default.

Chapter 3 Pinouts and pin definitions

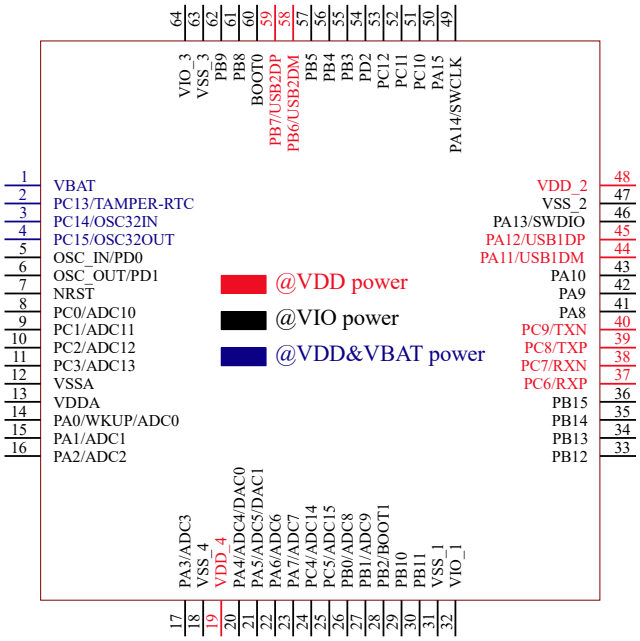
3.1 Pinouts

3.1.1 Interconnectivity device V307



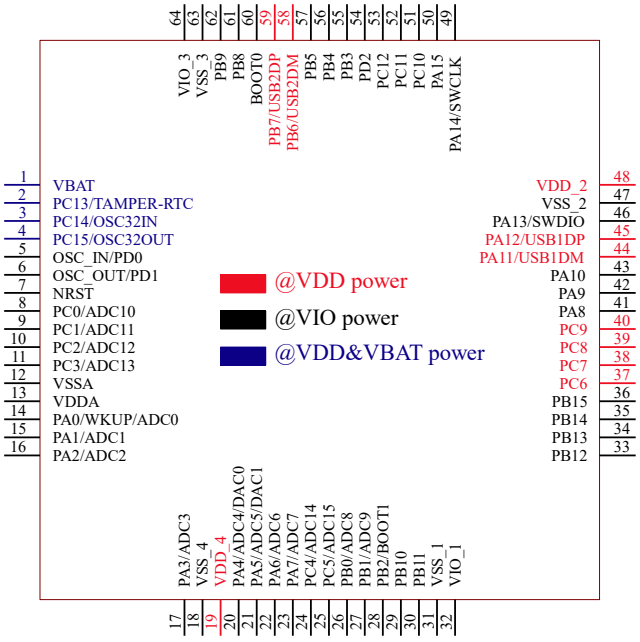


CH32V307RCT6

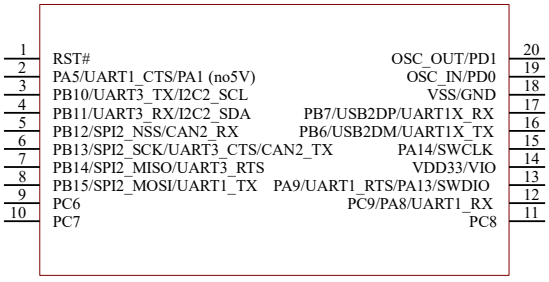


3.1.2 Connectivity device V305

CH32V305RBT6

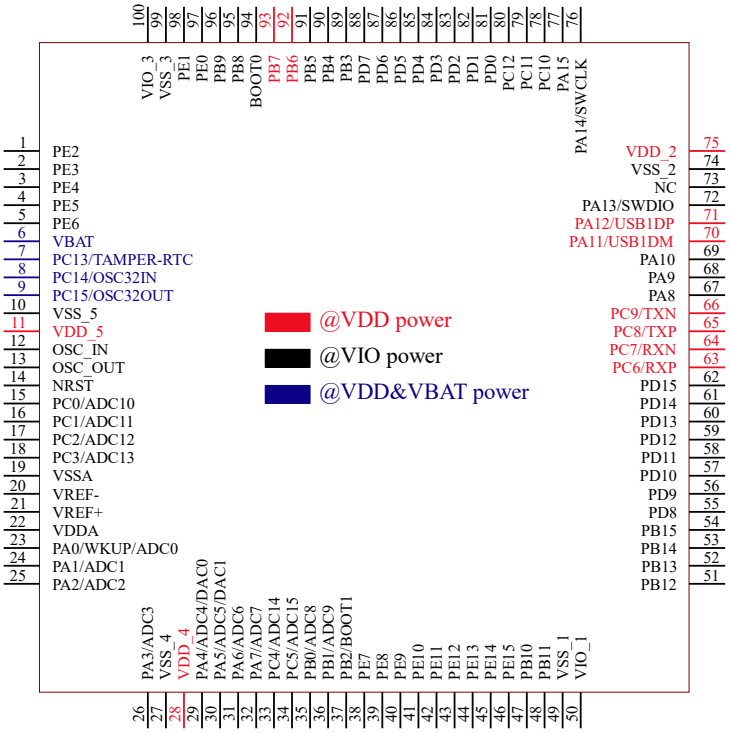


CH32V305FBP6

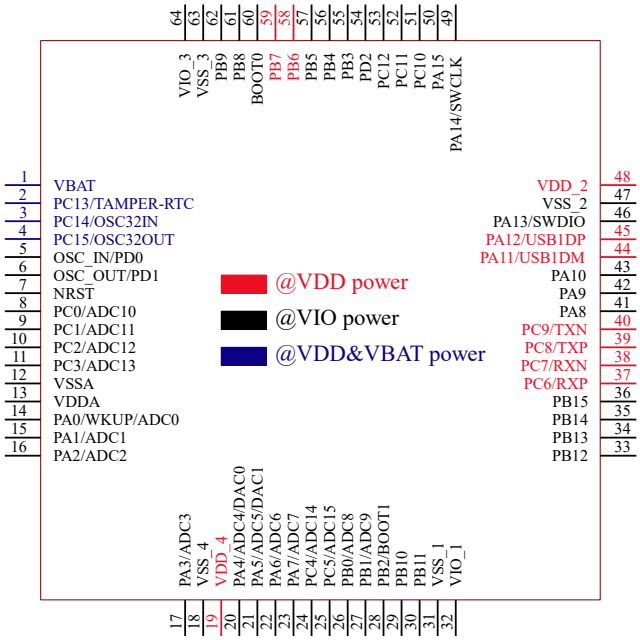


3.1.3 High-density general-purpose device V303

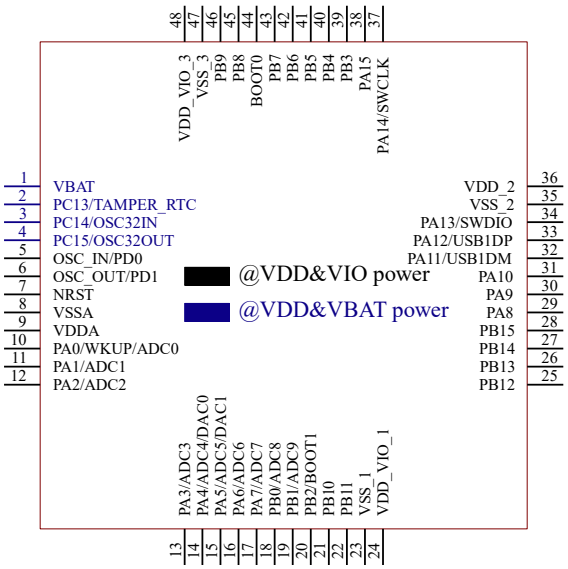
CH32V303VCT6



CH32V303RxT6

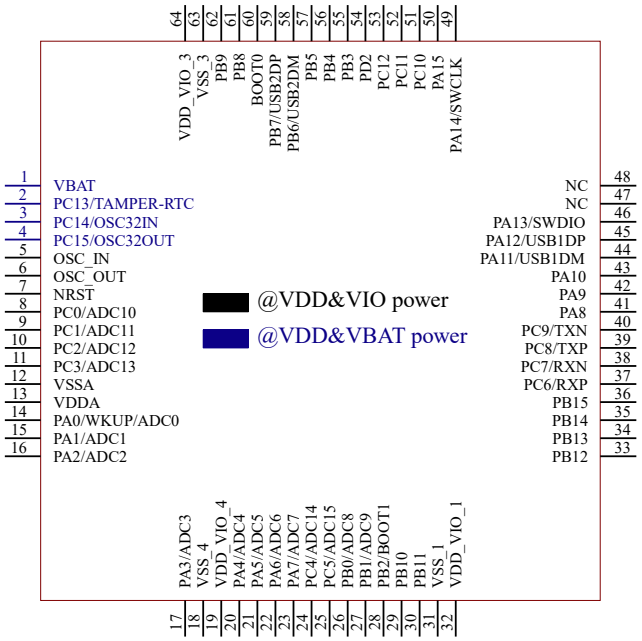


CH32V303CBT6

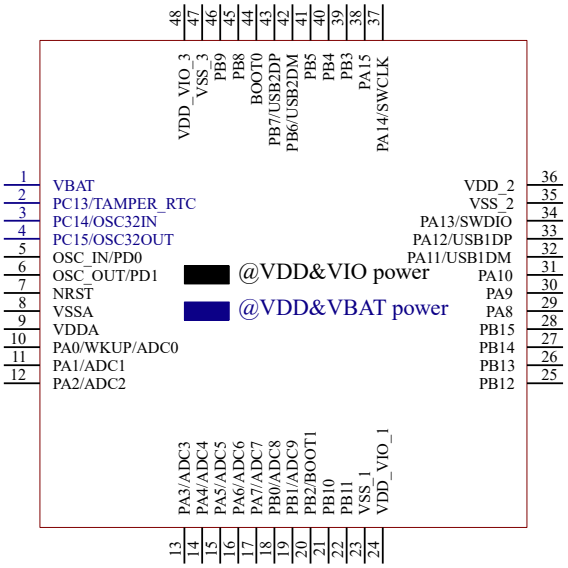


3.1.4 Low-and-medium-density general-purpose device V203

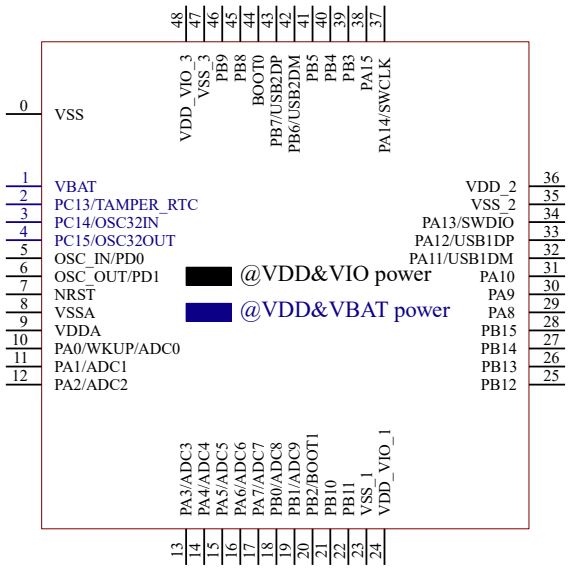
CH32V203RBT6



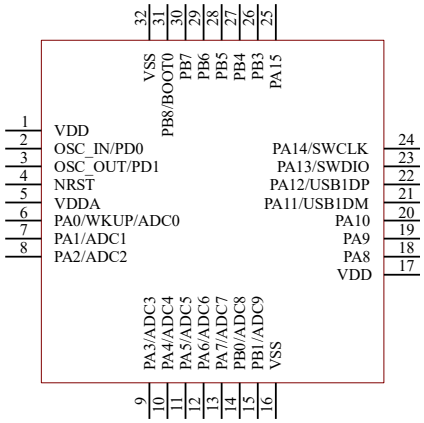
CH32V203CxT6



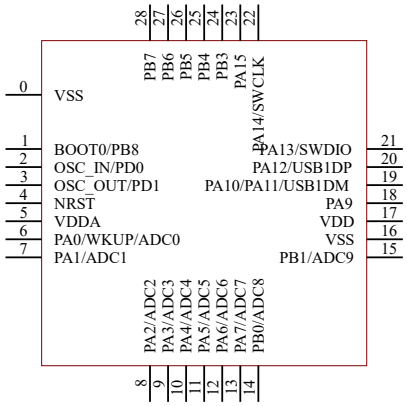
CH32V203CxU6



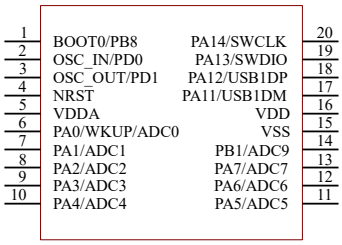
CH32V203KxT6



CH32V203G6U6

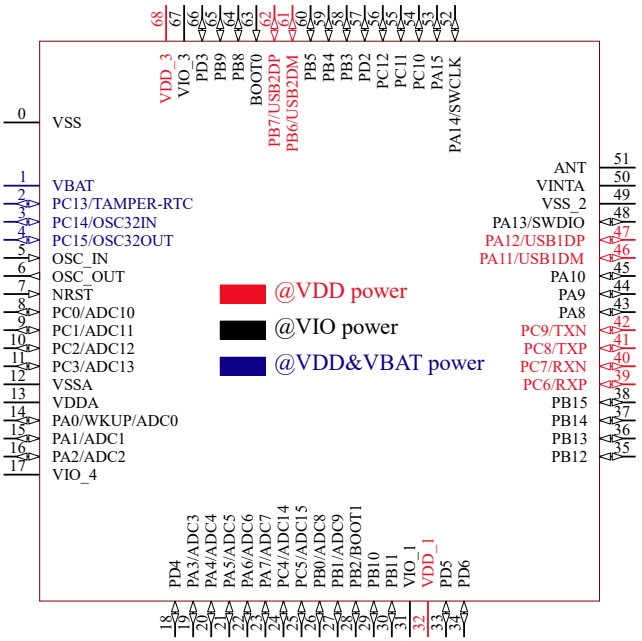


CH32V203F6P6

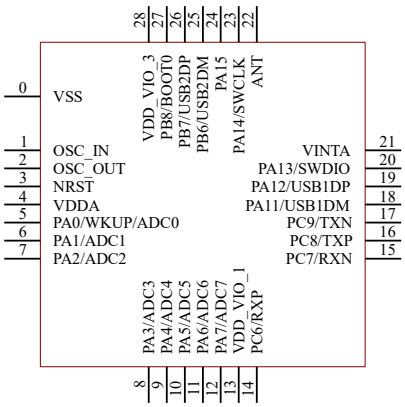


3.1.5 Wireless device V208

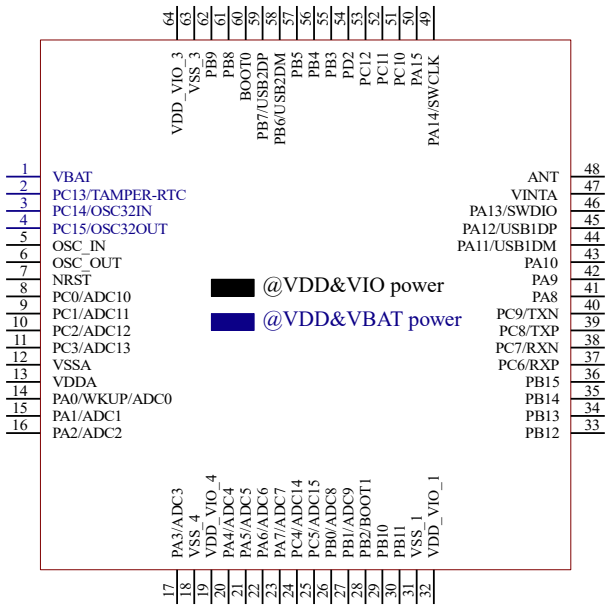
CH32V208WBU6



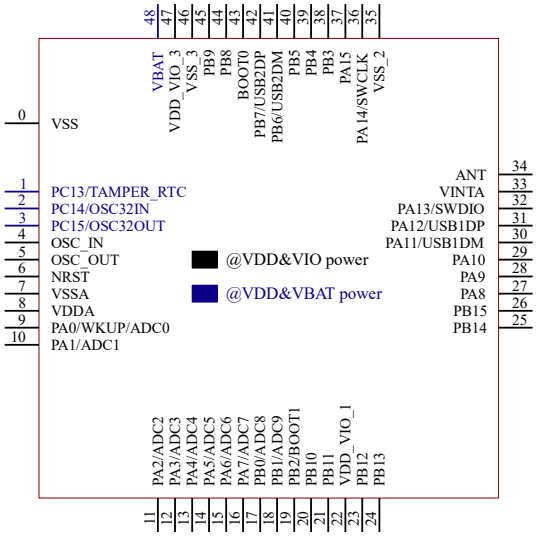
CH32V208GBU6



CH32V208RBT6



CH32V208CBU6



3.2 Pin definitions

Table 3-1 CH32V303_305_307xx pin definitions

Note: The pin function in the table below refer to all functions and do not involve specific model(s). There are differences in peripheral resources between different models. Please confirm whether this function is available according to the particular model's resource table before viewing this table.

Pin No.					Pin name	Pin type (1)	I/O voltage level	Main function (After reset)	Default alternate function	Remapping function
TSSOP20	LQFP48	LQFP64M	QFN68	LQFP100						
-	-	-	-	1	PE2	I/O	FT	PE2	FSMC_A23	TIM10_BKIN_2
-	-	-	-	2	PE3	I/O	FT	PE3	FSMC_A19	TIM10_CH1N_2
-	-	-	-	3	PE4	I/O	FT	PE4	FSMC_A20	TIM10_CH2N_2
-	-	-	-	4	PE5	I/O	FT	PE5	FSMC_A21	TIM10_CH3N_2
-	-	-	-	5	PE6	I/O	FT	PE5	FSMC_A22	
-	1	1	1	6	V_{BAT}	P	-	V_{BAT}		
-	2	2	2	7	PC13-TAMPER-RTC(2)	I/O	-	PC13(3)	TAMPER-RTC	TIM8_CH4_1
-	3	3	3	8	PC14-OSC32_IN(2)	I/O/A	-	PC14(3)	OSC32_IN	TIM9_CH4_1
-	4	4	4	9	PC15-OSC32_OUT(2)	I/O/A	-	PC15(3)	OSC32_OUT	TIM10_CH4_1
18	-	-	-	10	V_{SS_5}	P	-	V_{SS_5}		
14	-	-	-	11	V_{DD_5}	P	-	V_{DD_5}		
19	5	5	5	12	OSC_IN	I/A	-	OSC_IN		PD0(4)
20	6	6	6	13	OSC_OUT	O/A	-	OSC_OUT		PD1(4)
1	7	7	7	14	NRST	I	-	NRST		
-	-	8	8	15	PC0	I/O/A	-	PC0	ADC_IN10 TIM9_CH1N UART6_TX ETH_RGMII_RXC	
-	-	9	9	16	PC1	I/O/A	-	PC1	ADC_IN11 TIM9_CH2N UART6_RX ETH_MII_MDC ETH_RMII_MDC ETH_RGMII_RXCTL	
-	-	10	10	17	PC2	I/O/A	-	PC2	ADC_IN12 TIM9_CH3N UART7_TX OPA3_CH1N ETH_MII_TXD2 ETH_RGMII_RXD0	

	-	11	11	18	PC3	I/O/A	-	PC3	ADC_IN13 TIM10_CH3 UART7_RX OPA4_CH1N ETH_MII_TX_CLK ETH_RGMII_RXD1	
-	8	12	12	19	V_{SSA}	P	-	V_{SSA}		
-	-	-	-	20	V_{REF-}	P	-	V_{REF-}		
-	-	-	-	21	V_{REF+}	P	-	V_{REF+}		
-	9	13	13	22	V_{DDA}	P	-	V_{DDA}		
-	10	14	14	23	PA0-WKUP	I/O/A	-	PA0	WKUP USART2_CTS ADC_IN0 TIM2_CH1_ETR TIM5_CH1 TIM8_ETR OPA4_OUT0 ETH_MII_CRS_WKUP ETH_RGMII_RXD2	TIM2_CH1_ETR_2 TIM8_ETR_1
2	11	15	15	24	PA1	I/O/A	-	PA1	USART2_RTS ADC_IN1 TIM5_CH2 TIM2_CH2 OPA3_OUT0 ETH_MII_RX_CLK ETH_RMII_REF_CLK ETH_RGMII_RXD3	TIM2_CH2_2 TIM9_BKIN_1
-	12	16	16	25	PA2	I/O/A	-	PA2	USART2_TX TIM5_CH3 ADC_IN2 TIM2_CH3 TIM9_CH1_ETR OPA2_OUT0 ETH_MII_MDIO ETH_RMII_MDIO ETH_RGMII_GTXC	TIM2_CH3_1 TIM9_CH1_ETR _1
-	-	-	17	-	V_{IO_4}	P	-	V_{SS_4}		
-	13	17	19	26	PA3	I/O/A	-	PA3	USART2_RX TIM5_CH4 ADC_IN3 TIM2_CH4 TIM9_CH2 OPA1_OUT0 ETH_MII_COL ETH_RGMII_TXEN	TIM2_CH4_1 TIM9_CH2_1

-	-	18	-	27	V_{SS_4}	P	-	V_{SS_4}		
-	-	19	-	28	V_{DD_4}	P	-	V_{DD_4}		
-	14	20	20	29	PA4	I/O/A	-	PA4	SPI1_NSS USART2_CK ADC_IN4 DAC_OUT1 TIM9_CH3 DVP_HSYNC	SPI3_NSS I2S3_WS TIM9_CH3_1
2	15	21	21	30	PA5	I/O/A	-	PA5	SPI1_SCK ADC_IN5 DAC_OUT2 OPA2_CH1N DVP_VSYNC	TIM10_CH1N_1 USART1_CTS_2 USART1_CK_3
-	16	22	22	31	PA6	I/O/A	-	PA6	SPI1_MISO TIM8_BKIN ADC_IN6 TIM3_CH1 OPA1_CH1N DVP_PCLK	TIM1_BKIN_1 USART1_TX_3 UART7_TX_1 TIM10_CH2N_1
-	17	23	23	32	PA7	I/O/A	-	PA7	SPI1_MOSI TIM8_CH1N ADC_IN7 TIM3_CH2 OPA2_CH1P ETH_MII_RX_DV ETH_RMII_CRS_DV ETH_RGMII_TXD0	TIM1_CH1N_1 USART1_RX_3 UART7_RX_1 TIM10_CH3N_1
-	-	24	24	33	PC4	I/O/A	-	PC4	ADC_IN14 TIM9_CH4 UART8_TX OPA4_CH1P ETH_MII_RXD0 ETH_RMII_RXD0 ETH_RGMII_TXD1	USART1_CTS_3
-	-	25	25	34	PC5	I/O/A	-	PC5	ADC_IN15 TIM9_BKIN UART8_RX OPA3_CH1P ETH_MII_RXD1 ETH_RMII_RXD1 ETH_RGMII_TXD2	USART1_RTS_3
-	18	26	26	35	PB0	I/O/A	-	PB0	ADC_IN8 TIM3_CH3 TIM8_CH2N OPA1_CH1P	TIM1_CH2N_1 TIM3_CH3_2 TIM9_CH1N_1 UART4_TX_1

									ETH_MII_RXD2 ETH_RGMII_TXD3	
-	19	27	27	36	PB1	I/O/A	-	PB1	ADC_IN9 TIM3_CH4 TIM8_CH3N OPA4_CH0N ETH_MII_RXD3 ETH_RGMII_125IN	TIM1_CH3N_1 TIM3_CH4_2 TIM9_CH2N_1 UART4_RX_1
-	20	28	28	37	PB2(5)	I/O	FT	PB2 BOOT1(5)	OPA3_CH0N	TIM9_CH3N_1
-	-	-	-	38	PE7	I/O/A	FT	PE7	FSMC_D4 OPA3_OUT1	TIM1_ETR_3
-	-	-	-	39	PE8	I/O/A	FT	PE8	FSMC_D5 OPA4_OUT1	TIM1_CH1N_3 UART5_TX_2
-	-	-	-	40	PE9	I/O	FT	PE9	FSMC_D6	TIM1_CH1_3 UART5_RX_2
-	-	-	-	41	PE10	I/O	FT	PE10	FSMC_D7	TIM1_CH2N_3 UART6_TX_2
-	-	-	-	42	PE11	I/O	FT	PE11	FSMC_D8	TIM1_CH2_3 UART6_RX_2
-	-	-	-	43	PE12	I/O	FT	PE12	FSMC_D9	TIM1_CH3N_3 UART7_TX_2
-	-	-	-	44	PE13	I/O	FT	PE13	FSMC_D10	TIM1_CH3_3 UART7_RX_2
-	-	-	-	45	PE14	I/O/A	FT	PE14	FSMC_D11 OPA2_OUT1	TIM1_CH4_3 UART8_TX_2
-	-	-	-	46	PE15	I/O/A	FT	PE15	FSMC_D12 OPA1_OUT1	TIM1_BKIN_3 UART8_RX_2
3	21	29	29	47	PB10	I/O/A	FT	PB10	I2C2_SCL USART3_TX OPA2_CH0N ETH_MII_RX_ER	TIM2_CH3_2 TIM2_CH3_3 TIM10_BKIN_1
4	22	30	30	48	PB11	I/O/A	FT	PB11	I2C2_SDA USART3_RX OPA1_CH0N ETH_MII_TX_EN ETH_RMII_TX_EN	TIM2_CH4_2 TIM2_CH4_3 TIM10_ETR_1
-	23	31	18	49	V_{SS_1}	P		V_{SS_1}		
-	-	32	31	50	V_{IO_1}	P		V_{IO_1}		
-	24	-	-	-	$V_{DD\_IO\_1}$	P		$V_{DD\_IO\_1}$		
-	-	-	32	-	V_{DD_1}	P		V_{DD_1}		
5	25	33	35	51	PB12	I/O/A	FT	PB12	SPI2_NSS I2S2_WS I2C2_SMBA	

									USART3_CK TIM1_BKIN OPA4_CH0P CAN2_RX ETH_MII_TXD0 ETH_RMII_TXD0	
6	26	34	36	52	PB13	I/O/A	FT	PB13	SPI2_SCK I2S2_CK USART3_CTS TIM1_CH1N OPA3_CH0P CAN2_TX ETH_MII_TXD1 ETH_RMII_TXD1	USART3_CTS_1
7	27	35	37	53	PB14	I/O/A	FT	PB14	SPI2_MISO TIM1_CH2N USART3_RTS OPA2_CH0P	USART3_RTS_1
8	28	36	38	54	PB15	I/O/A	FT	PB15	SPI2_MOSI I2S2_SD TIM1_CH3N OPA1_CH0P	USART1_TX_2
-	-	-	33	55	PD8	I/O	FT	PD8	FSMC_D13	USART3_TX_3 TIM9_CH1N_2 ETH_MII_RX_DV ETH_RMII_CRS _DV
-	-	-	34	56	PD9	I/O	FT	PD9	FSMC_D14	USART3_RX_3 TIM9_CH1_ETR_2 ETH_MII_RXD0 ETH_RMII_RXD0
-	-	-	-	57	PD10	I/O	FT	PD10	FSMC_D15	USART3_CK_3 TIM9_CH2N_2 ETH_MII_RXD1 ETH_RMII_RXD1
-	-	-	-	58	PD11	I/O	FT	PD11	FSMC_A16	USART3_CTS_3 TIM9_CH2_2 ETH_MII_RXD2
-	-	-	-	59	PD12	I/O	FT	PD12	FSMC_A17	TIM4_CH1_1 TIM9_CH3N_2 USART3_RTS_3 ETH_MII_RXD3
-	-	-	-	60	PD13	I/O	FT	PD13	FSMC_A18	TIM4_CH2_1 TIM9_CH3_2

-	-	-	-	61	PD14	I/O	FT	PD14	FSMC_D0	TIM4_CH3_1 TIM9_BKIN_2
-	-	-	-	62	PD15	I/O	FT	PD15	FSMC_D1	TIM4_CH4_1 TIM9_CH4_2
9	-	37	39	63	PC6	I/O	FT	PC6	I2S2_MCK TIM8_CH1 SDIO_D6 ETH_RXP	TIM3_CH1_3
10	-	38	40	64	PC7	I/O	FT	PC7	I2S3_MCK TIM8_CH2 SDIO_D7 ETH_RXN	TIM3_CH2_3
11	-	39	41	65	PC8	I/O	FT	PC8	TIM8_CH3 SDIO_D0 ETH_TXP DVP_D2	TIM3_CH3_3
12	-	40	42	66	PC9	I/O	FT	PC9	TIM8_CH4 SDIO_D1 ETH_TXN DVP_D3	TIM3_CH4_3
	29	41	43	67	PA8	I/O	FT	PA8	USART1_CK TIM1_CH1 MCO	USART1_CK_1 USART1_RX_2 TIM1_CH1_1
13	30	42	44	68	PA9	I/O	FT	PA9	USART1_TX TIM1_CH2 OTG_FS_VBUS DVP_D0	USART1_RTS_2 TIM1_CH2_1
-	31	43	45	69	PA10	I/O	FT	PA10	USART1_RX TIM1_CH3 OTG_FS_ID DVP_D1	USART1_CK_2 TIM1_CH3_1
-	32	44	46	70	PA11	I/O/A	FT	PA11	USART1_CTS USBDM CAN1_RX TIM1_CH4 OTG_FS_DM	USART1_CTS_1 TIM1_CH4_1
-	33	45	47	71	PA12	I/O/A	FT	PA12	USART1_RTS USBDP CAN1_TX TIM1_ETR TIM10_CH1N OTG_FS_DP	USART1_RTS_1 TIM1_ETR_1
13	34	46	48	72	PA13	I/O	FT	SWDIO	TIM10_CH2N	PA13 TIM8_CH1N_1
-	-	-	-	73	unused					

-	35	47	49	74	V_{SS_2}	P	-	V_{SS_2}		
-	36	48	50	75	V_{DD_2}	P	-	V_{DD_2}		
-	-	-	51	-	V_{IO_2}	P	-	V_{IO_2}		
15	37	49	52	76	PA14	I/O	FT	SWCLK	TIM10_CH3N	TIM8_CH2N_1 UART8_TX_1 PA14
-	38	50	53	77	PA15	I/O	FT	PA15	SPI3_NSS I2S3_WS	TIM2_CH1_ETR_1 TIM2_CH1_ETR_3 SPI1_NSS TIM8_CH3N_1 UART8_RX_1
-	-	51	54	78	PC10	I/O	FT	PC10	UART4_TX SDIO_D2 TIM10_ETR DVP_D8	USART3_TX_1 SPI3_SCK I2S3_CK
-	-	52	55	79	PC11	I/O	FT	PC11	UART4_RX SDIO_D3 TIM10_CH4 DVP_D4	USART3_RX_1 SPI3_MISO
-	-	53	56	80	PC12	I/O	FT	PC12	UART5_TX SDIO_CK TIM10_BKIN DVP_D9	USART3_CK_1 SPI3_MOSI I2S3_SD
-	-	-	-	81	PD0	I/O/A	FT	PD0	FSMC_D2	CAN1_RX TIM10_ETR_2
-	-	-	-	82	PD1	I/O/A	FT	PD1	FSMC_D3	CAN1_TX TIM10_CH1_2
-	-	54	57	83	PD2	I/O	FT	PD2	TIM3_ETR UART5_RX SDIO_CMD DVP_D11	TIM3_ETR_2 TIM3_ETR_3
-	-	-	-	84	PD3	I/O	FT	PD3	FSMC_CLK	USART2_CTS_1 TIM10_CH2_2
-	-	-	-	85	PD4	I/O	FT	PD4	FSMC_NOE	USART2_RTS_1
-	-	-	-	86	PD5	I/O	FT	PD5	FSMC_NWE	USART2_TX_1 TIM10_CH3_2
-	-	-	-	87	PD6	I/O	FT	PD6	FSMC_NWAIT DVP_D10	USART2_RX_1
-	-	-	-	88	PD7	I/O	FT	PD7	FSMC_NE1 FSMC_NCE2	USART2_CK_1 TIM10_CH4_2
-	39	55	58	89	PB3	I/O	FT	PB3	SPI3_SCK I2S3_CK	TIM2_CH2_1 TIM2_CH2_3 SPI1_SCK TIM10_CH1_1

-	40	56	59	90	PB4	I/O	FT	PB4	SPI3_MISO	TIM3_CH1_2 SPI1_MISO UART5_TX_1 TIM10_CH2_1
-	41	57	60	91	PB5	I/O	FT	PB5	I2C1_SMBA SPI3_MOSI I2S3_SD ETH_MII_PPS_OUT ETH_RMII_PPS_OUT	TIM3_CH2_2 SPI1_MOSI CAN2_RX TIM10_CH3_1 UART5_RX_1
16	42	58	61	92	PB6	I/O	FT	PB6	I2C1_SCL TIM4_CH1 USBHD_DM DVP_D5 USBHS_DM	USART1_TX_1 CAN2_TX TIM8_CH1_1
17	43	59	62	93	PB7	I/O	FT	PB7	I2C1_SDA FSMC_NADV TIM4_CH2 USBHD_DP USBHS_DP	USART1_RX_1 TIM8_CH2_1
-	44	60	63	94	BOOT0(5)	I	-	BOOT0(5)		
-	45	61	64	95	PB8	I/O/A	FT	PB8	TIM4_CH3 SDIO_D4 TIM10_CH1 DVP_D6 ETH_MII_TXD3	I2C1_SCL CAN1_RX UART6_TX_1 TIM8_CH3_1
-	46	62	65	96	PB9	I/O/A	FT	PB9	TIM4_CH4 SDIO_D5 TIM10_CH2 DVP_D7	I2C1_SDA CAN1_TX UART6_RX_1 TIM8_BKIN_1
-	-	-	66	97	PE0	I/O	FT	PE0	FSMC_NBL0	TIM4_ETR_1 UART4_TX_2
-	-	-	-	98	PE1	I/O	FT	PE1	FSMC_NBL1	UART4_RX_2
-	47	63	-	99	V_{SS_3}	P	-	V_{SS_3}		
-	-	64	67	100	V_{IO_3}	P	-	V_{IO_3}		
-	-	-	68	-	V_{DD_3}	P	-	V_{DD_3}		
-	48	-		-	$V_{DD\_IO\_3}$	P		$V_{DD\_IO\_3}$		

Table 3-2 CH32V203xx pin definitions

Note: The pin function in the table below refer to all functions and do not involve specific model(s). There are differences in peripheral resources between different models. Please confirm whether this function is available according to the particular model's resource table before viewing this table.

Pin No.					Pin name	Pin type (1)	I/O voltage level	Main function (After reset)	Default alternate function	Remapping function
TSSOP20	QFN28	LQFP32	LQFP48/QFN48	LQFP64M						
-	0	-	0	-	V_{SS}	P	-	V_{SS}		
-	-	-	1	1	V_{BAT}	P	-	V_{BAT}		
-	-	-	2	2	PC13-TAMPER-RTC(2)	I/O	-	PC13(3)	TAMPER-RTC	
-	-	-	3	3	PC14-OSC32_IN(2)	I/O/A	-	PC14(3)	OSC32_IN	
-	-	-	4	4	PC15-OSC32_OUT(2)	I/O/A	-	PC15(3)	OSC32_OUT	
2	2	2	5	-	OSC_IN	I/A	-	OSC_IN		PD0(4)
-	-	-	-	5						
3	3	3	6	-	OSC_OUT	O/A	-	OSC_OUT		PD1(4)
-	-	-	-	6						
4	4	4	7	7	NRST	I	-	NRST		
-	-	-	-	8	PC0	I/O/A	-	PC0	ADC_IN10	
-	-	-	-	9	PC1	I/O/A	-	PC1	ADC_IN11	
-	-	-	-	10	PC2	I/O/A	-	PC2	ADC_IN12	
-	-	-	-	11	PC3	I/O/A	-	PC3	ADC_IN13	
-	-	-	8	12	V_{SSA}	P	-	V_{SSA}		
5	5	5	9	13	V_{DDA}	P	-	V_{DDA}		
6	6	6	10	14	PA0-WKUP	I/O/A	-	PA0	WKUP USART2_CTS ADC_IN0 TIM2_CH1 TIM2_ETR TIM5_CH1	TIM2_CH1_ETR_2
7	7	7	11	15	PA1	I/O/A	-	PA1	USART2_RTS ADC_IN1 TIM2_CH2 TIM5_CH2	TIM2_CH2_2
8	8	8	12	16	PA2	I/O/A	-	PA2	USART2_TX ADC_IN2 TIM2_CH3 OPA2_OUT0 TIM5_CH3	TIM2_CH3_1

9	9	9	13	17	PA3	I/O/A	-	PA3	USART2_RX ADC_IN3 TIM2_CH4 OPA1_OUT0 TIM5_CH4	TIM2_CH4_1
-	-	-	-	18	V_{SS_4}	P	-	V_{SS_4}		
-	-	-	-	19	$V_{DD\_IO\_4}$	P	-	$V_{DD\_IO\_4}$		
10	10	10	14	20	PA4	I/O/A	-	PA4	SPI1_NSS USART2_CK ADC_IN4 OPA2_OUT1	
11	11	11	15	-	PA5	I/O/A	-	PA5	SPI1_SCK ADC_IN5 OPA2_CH1N	USART4_TX_1
-	-	-	-	21						USART1_CTS_2 USART1_CK_3
12	12	12	16	-	PA6	I/O/A	-	PA6	SPI1_MISO ADC_IN6 TIM3_CH1 OPA1_CH1N	TIM1_BKIN_1 USART4_CK_1
-	-	-	-	22						TIM1_BKIN_1 USART1_TX_3
13	13	13	17	-	PA7	I/O/A	-	PA7	SPI1_MOSI ADC_IN7 TIM3_CH2 OPA2_CH1P	TIM1_CH1N_1 USART4_CTS_1
-	-	-	-	23						TIM1_CH1N_1 USART1_RX_3
-	-	-	-	24	PC4	I/O/A		PC4	ADC_IN14	USART1_CTS_3
-	-	-	-	25	PC5	I/O/A		PC5	ADC_IN15	USART1_RTS_3
-	14	14	18	-	PB0	I/O/A	-	PB0	ADC_IN8 TIM3_CH3 OPA1_CH1P USART4_TX	TIM1_CH2N_1 TIM3_CH3_2
-	-	-	-	26					ADC_IN8 TIM3_CH3 OPA1_CH1P	TIM1_CH2N_1 TIM3_CH3_2 UART4_TX_1
14	15	15	19	-	PB1	I/O/A	-	PB1	ADC_IN9 TIM3_CH4 OPA1_OUT1 USART4_RX	TIM1_CH3N_1 TIM3_CH4_2
-	-	-	-	27					ADC_IN9 TIM3_CH4 OPA1_OUT1	TIM1_CH3N_1 TIM3_CH4_2 UART4_RX_1
-	-	-	20	-	PB2[5]	I/O	FT	PB2 BOOT1[5]	USART4_CK	
-	-	-	-	28						
-	-	-	21	29	PB10	I/O/A	FT	PB10	I2C2_SCL USART3_TX OPA2_CH0N	TIM2_CH3_2 TIM2_CH3_3

-	-	-	22	30	PB11	I/O/A	FT	PB11	I2C2_SDA USART3_RX OPA1_CH0N	TIM2_CH4_2 TIM2_CH4_3
15	16	16	23	31	V_{SS_1}	P		V_{SS_1}		
16	17	17	24	32	$V_{DD\_IO\_1}$	P		$V_{DD\_IO\_1}$		
-	-	-	25	33	PB12	I/O/A	FT	PB12	SPI2_NSS I2C2_SMBA USART3_CK TIM1_BKIN	
-	-	-	26	-	PB13	I/O/A	FT	PB13	SPI2_SCK USART3_CTS TIM1_CH1N	
-	-	-	-	34						USART3_CTS_1
-	-	-	27	-	PB14	I/O/A	FT	PB14	SPI2_MISO TIM1_CH2N USART3_RTS OPA2_CH0P	
-	-	-	-	35						USART3_RTS_1
-	-	-	28	-	PB15	I/O/A	FT	PB15	SPI2_MOSI TIM1_CH3N OPA1_CH0P	
-	-	-	-	36						USART1_TX_2
-	-	-	-	37	PC6	I/O/A	FT	PC6	ETH_RXP	TIM3_CH1_3
-	-	-	-	38	PC7	I/O/A	FT	PC7	ETH_RXN	TIM3_CH2_3
-	-	-	-	39	PC8	I/O/A	FT	PC8	ETH_TXP	TIM3_CH3_3
-	-	-	-	40	PC9	I/O/A	FT	PC9	ETH_TXN	TIM3_CH4_3
-	-	18	29	-	PA8	I/O	FT	PA8	USART1_CK TIM1_CH1 MCO	USART1_CK_1
-	-	-	-	41						
-	18	19	30	-	PA9	I/O	FT	PA9	USART1_TX TIM1_CH2	TIM1_CH1_1
-	-	-	-	42						USART1_CK_1 USART1_RX_2 TIM1_CH1_1
-	19	20	31	-	PA10	I/O	FT	PA10	USART1_RX TIM1_CH3	TIM1_CH2_1
-	-	-	-	43						USART1_RTS_2 TIM1_CH2_1
17	19	21	32	-	PA11	I/O/A	FT	PA11	USART1_CTS USBDM CAN1_RX TIM1_CH4	USART1_CTS_1 TIM1_CH3_1
-	-	-	-	44						USART1_CK_2 TIM1_CH3_1
18	20	22	33	-	PA12	I/O/A	FT	PA12	USART1_RTS USBDP CAN1_TX TIM1_ETR	USART1_RTS_1 TIM1_CH4_1
-	-	-	-	45						USART1_CTS_1 TIM1_CH4_1
19	21	23	34	46	PA13	I/O	FT	SWDIO		PA13
-	-	-	35	-	V_{SS_2}	P	-	V_{SS_2}		
-	-	-	36	-	V_{DD_2}	P	-	V_{DD_2}		

-	-	-	-	47	NC			NC		
-	-	-	-	48	NC			NC		
20	22	24	37	49	PA14	I/O	FT	SWCLK		PA14
-	23	25	38	-	PA15	I/O	FT	PA15		TIM2_CH1_ETR_1 TIM2_CH1_ETR_3 SPI1_NSS USART4_RTS_1
-	-	-	-	50						TIM2_CH1_ETR_1 TIM2_CH1_ETR_3 SPI1_NSS
-	-	-	-	51	PC10	I/O	FT	PC10	UART4_TX	USART3_TX_1
-	-	-	-	52	PC11	I/O	FT	PC11	UART4_RX	USART3_RX_1
-	-	-	-	53	PC12	I/O	FT	PC12		USART3_CK_1
-	-	-	-	54	PD2	I/O	FT	PD2	TIM3_ETR	TIM3_ETR_2 TIM3_ETR_3
-	24	26	39	-	PB3	I/O	FT	PB3	USART4_CTS	TIM2_CH2_1
-	-	-	-	55						TIM2_CH2_3 SPI1_SCK
-	25	27	40	-	PB4	I/O	FT	PB4	USART4_RTS	TIM3_CH1_2
-	-	-	-	56						SPI1_MISO
-	26	28	41	-	PB5	I/O	FT	PB5	I2C1_SMBA	TIM3_CH2_2 SPI1_MOSI USART4_RX_1
-	-	-	-	57						TIM3_CH2_2 SPI1_MOSI
-	27	29	42	58	PB6	I/O	FT	PB6	I2C1_SCL TIM4_CH1 USBHD_DM	USART1_TX_1
-	28	30	43	59	PB7	I/O	FT	PB7	I2C1_SDA TIM4_CH2 USBHD_DP	USART1_RX_1
1(6)	1(6)	31(6)	44	60	BOOT0	I	-	BOOT0		
			45	61	PB8	I/O/A	FT	PB8	TIM4_CH3	I2C1_SCL CAN1_RX
-	-	-	46	68	PB9	I/O/A	FT	PB9	TIM4_CH4	I2C1_SDA CAN1_TX
-	-	32	47	63	V_{SS_3}	P	-	V_{SS_3}		
-	-	1	48	64	$V_{DD\_IO\_3}$	P	-	$V_{DD\_IO\_3}$		

Table 3-3 CH32V208xx pin definitions

Note: The pin function in the table below refer to all functions and does not involve specific model(s). There are differences in peripheral resources between different models. Please confirm whether this function is available according to the particular model's resource table before viewing this table.

Pin No.				Pin name	Pin type (1)	I/O voltage level	Main function (After reset)	Default alternate function	Remapping function
QFN28	QFN48	LQFP64	QFN68						
0	0	-	0	V_{SS}	P	-	V_{SS}		
-	48	1	1	V_{BAT}	P	-	V_{BAT}		
-	1	2	2	PC13-TAMPER-RTC(2)	I/O	-	PC13(3)	TAMPER-RTC	
-	2	3	3	PC14-OSC32_IN(2)	I/O/A	-	PC14(3)	OSC32_IN	
-	3	4	4	PC15-OSC32_OUT(2)	I/O/A	-	PC15(3)	OSC32_OUT	
1	4	5	5	OSC_IN	I/A	-	OSC_IN		
2	5	6	6	OSC_OUT	O/A	-	OSC_OUT		
3	6	7	7	NRST	I	-	NRST		
-	-	8	8	PC0	I/O/A	-	PC0	ADC_IN10	
-	-	9	9	PC1	I/O/A	-	PC1	ADC_IN11	
-	-	10	10	PC2	I/O/A	-	PC2	ADC_IN12	
-	-	11	11	PC3	I/O/A	-	PC3	ADC_IN13	
-	7	12	12	V_{SSA}	P	-	V_{SSA}		
4	8	13	13	V_{DDA}	P	-	V_{DDA}		
5	9	14	14	PA0-WKUP	I/O/A	-	PA0	WKUP/USART2_CTS ADC_IN0/TIM2_CH1 TIM2_ETR/TIM5_CH1	TIM2_CH1_ETR_2
6	10	15	15	PA1	I/O/A	-	PA1	USART2_RTS/ADC_IN1 TIM5_CH2/TIM2_CH2	TIM2_CH2_2
7	11	16	16	PA2	I/O/A	-	PA2	USART2_TX/TIM5_CH3 ADC_IN2/TIM2_CH3 OPA2_OUT0	TIM2_CH3_1
-	-	-	17	V_{IO_4}	P	-	V_{IO_4}		
-	-	-	18	PD4	I/O	FT	PD4		
8	12	17	19	PA3	I/O/A	-	PA3	USART2_RX/TIM5_CH4 ADC_IN3/TIM2_CH4 OPA1_OUT0	TIM2_CH4_1
-	-	18		V_{SS_4}	P	-	V_{SS_4}		
-	-	19	-	$V_{DD\_IO\_4}$	P	-	$V_{DD\_IO\_4}$		

9	13	20	20	PA4	I/O/A	-	PA4	SPI1_NSS/USART2_CK ADC_IN4/OPA2_OUT1	
10	14	21	21	PA5	I/O/A	-	PA5	SPI1_SCK/ADC_IN5 OPA2_CH1N	USART1_CTS_2 USART1_CK_3
11	15	22	22	PA6	I/O/A	-	PA6	SPI1_MISO/ADC_IN6 TIM3_CH1/OPA1_CH1N	TIM1_BKIN_1 USART1_TX_3
12	16	23	23	PA7	I/O/A	-	PA7	SPI1_MOSI/ADC_IN7 TIM3_CH2/OPA2_CH1P	TIM1_CH1N_1 USART1_RX_3
-	-	24	24	PC4	I/O/A	-	PC4	ADC_IN14	USART1_CTS_3
-	-	25	25	PC5	I/O/A	-	PC5	ADC_IN15	USART1_RTS_3
-	17	26	26	PB0	I/O/A	-	PB0	ADC_IN8/TIM3_CH3 OPA1_CH1P	TIM1_CH2N_1 TIM3_CH3_2 UART4_TX_1
-	18	27	27	PB1	I/O/A	-	PB1	ADC_IN9/TIM3_CH4 OPA1_OUT1	TIM1_CH3N_1 TIM3_CH4_2 UART4_RX_1
-	19	28	28	PB2(5)	I/O	FT	PB2/BOOT1(5)		
-	20	29	29	PB10	I/O/A	FT	PB10	I2C2_SCL/USART3_TX OPA2_CH0N	TIM2_CH3_2 TIM2_CH3_3
-	21	30	30	PB11	I/O/A	FT	PB11	I2C2_SDA/USART3_RX OPA1_CH0N	TIM2_CH4_2 TIM2_CH4_3
-	-	31	-	V_{SS_1}	P		V_{SS_1}		
13	22	32	-	$V_{DD\_IO\_1}$	P		$V_{DD\_IO\_1}$		
-	-	-	31	V_{IO_1}	P		V_{IO_1}		
-	-	-	32	V_{DD_1}	P		V_{DD_1}		
-	-	-	33	PD5	I/O	FT	PD5		
-	-	-	34	PD6	I/O	FT	PD6		
-	23	33	35	PB12	I/O/A	FT	PB12	SPI2_NSS/I2C2_SMBA USART3_CK/TIM1_BKIN	
-	24	34	36	PB13	I/O/A	FT	PB13	SPI2_SCK/TIM1_CH1N USART3_CTS	USART3_CTS_1
-	25	35	37	PB14	I/O/A	FT	PB14	SPI2_MISO/TIM1_CH2N USART3_RTS/OPA2_CH0P	USART3_RTS_1
-	26	36	38	PB15	I/O/A	FT	PB15	SPI2_MOSI/TIM1_CH3N OPA1_CH0P	USART1_TX_2
14	-	37	39	PC6	I/O	FT	PC6	ETH_RXP	TIM3_CH1_3
15	-	38	40	PC7	I/O	FT	PC7	ETH_RXN	TIM3_CH2_3
16	-	39	41	PC8	I/O	FT	PC8	ETH_TXP	TIM3_CH3_3
17	-	40	42	PC9	I/O	FT	PC9	ETH_TXN	TIM3_CH4_3
-	27	41	43	PA8	I/O	FT	PA8	USART1_CK TIM1_CH1/MCO	

-	28	42	44	PA9	I/O	FT	PA9	USART1_TX TIM1_CH2	USART1_CK_1 USART1_RX_2 TIM1_CH1_1
-	29	43	45	PA10	I/O	FT	PA10	USART1_RX TIM1_CH3	USART1_RTS_2 TIM1_CH2_1
18	30	44	46	PA11	I/O/ A	FT	PA11	USART1_CTS/USBDM CAN1_RX/TIM1_CH4	USART1_CK_2 TIM1_CH3_1
19	31	45	47	PA12	I/O/ A	FT	PA12	USART1_RTS/USBDP CAN1_TX/TIM1_ETR	USART1_CTS_1 TIM1_CH4_1
20	32	46	48	PA13	I/O	FT	SWDIO		PA13
-	35	-	49	V_{SS_2}	P	-	V_{SS_2}		
21	33	47	50	V_{INTA}	P	-	V_{INTA}		
22	34	48	51	ANT	A	-	ANT		
23	36	49	52	PA14	I/O	FT	SWCLK		PA14
24	37	50	53	PA15	I/O	FT	PA15		TIM2_CH1_ETR_1 TIM2_CH1_ETR_3 SPI1_NSS
-	-	51	54	PC10	I/O	FT	PC10	UART4_TX	USART3_TX_1
-	-	52	55	PC11	I/O	FT	PC11	UART4_RX	USART3_RX_1
-	-	53	56	PC12	I/O	FT	PC12		USART3_CK_1
-	-	54	57	PD2	I/O	FT	PD2	TIM3_ETR	TIM3_ETR_2 TIM3_ETR_3
-	38	55	58	PB3	I/O	FT	PB3		TIM2_CH2_1 TIM2_CH2_3 SPI1_SCK
-	39	56	59	PB4	I/O	FT	PB4		TIM3_CH1_2 SPI1_MISO
-	40	57	60	PB5	I/O	FT	PB5	I2C1_SMBA	TIM3_CH2_2 SPI1_MOSI
25	41	58	61	PB6	I/O	FT	PB6	I2C1_SCL/TIM4_CH1 USBHD_DM	USART1_TX_1
26	42	59	62	PB7	I/O	FT	PB7	I2C1_SDA TIM4_CH2/USBHD_DP	USART1_RX_1
27[6]	43	60	63	BOOT0	I	-	BOOT0		
	44	61	64	PB8	I/O/ A	FT	PB8	TIM4_CH3	I2C1_SCL/CAN1_RX
-	45	62	65	PB9	I/O/ A	FT	PB9	TIM4_CH4	I2C1_SDA/CAN1_TX
-	-	-	66	PD3	I/O	FT	PD3		
-	46	63	-	V_{SS_3}	P	-	V_{SS_3}		
28	47	64	-	$V_{DD\_IO\_3}$	P	-	$V_{DD\_IO\_3}$		
-	-	-	67	V_{IO_3}	P	-	V_{IO_3}		
-	-	-	68	V_{DD_3}	P	-	V_{DD_3}		

Note 1: Abbreviations in the table

I = TTL/CMOS level Schmitt input;

O = CMOS level tri-state output;

A = analog signal input or output;

P = power supply;

FT = 5V tolerance;

ANT = RF signal input and output (antenna);

Note 2: The PC13, PC14 and PC15 pins are powered by the power's switch, and this power's switch can only absorb a limited current (3mA). Therefore, when these 3 pins are used as output pins, there are the following restrictions: only one pin can be used as an output at the same time. When used as an output pin, it can only work in 2MHz mode. The maximum drive load is 30pF and cannot be used as a current source (Such as driving LED).

Note 3: These pins are in the main function state when the backup area is powered on for the first time. Even after resetting, the state of these pins is controlled by the backup area registers (these registers will not be reset by the main reset system). For specific information on how to control these IO ports, please refer to the relevant chapters on the battery backup area and BKP register in the CH32FV2x_V3xRM datasheet.

Note 4: Pin 5 and pin 6 of those in LQFP64M package are configured as OSC_IN and OSC_OUT function pins by default after chip reset. Software can reconfigure these 2 pins as PD0 and PD1. But for those in LQFP100 package, since PD0 and PD1 are inherent functional pins, there is no need to re-image settings by software. For the CH32V203RBT6, the OSC_IN and OSC_OUT function pins have no alternate functions of PD0 and PD1. For more detailed information, please refer to the chapters on Alternate Function I/O and Debug Setting in the CH32FV2x_V3xRM datasheet.

Note 5: For devices without the BOOT0 pinout, they are pulled down to GND internally. For devices without the BOOT1/PB2 pinout, they are pulled down to GND internally. In this case, it is recommended that the BOOT1/PB2 pinout is set to input pull-down mode if a device goes into the low-power mode and configures IO port state, to avoid generating extra current.

Note 6: For a device whose BOOT0 and PB8 pinouts are shorted, it is recommended to be connected to an external 500K pull-down resistor, to ensure that the device is powered on stably and enters the mode of booting from program flash memory. After that, only the drive output function of the PB8 pin and its alternate function pin is used.

Chapter 4 Electrical characteristics

4.1 Test conditions

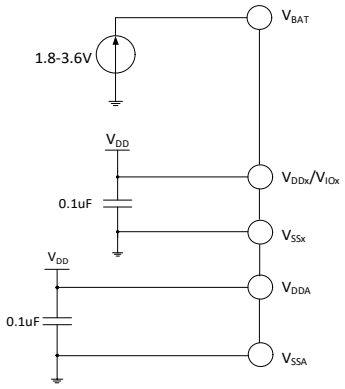
Unless otherwise specified and marked, all voltages are based on V_{SS}.

All minimum and maximum values will be guaranteed under the worst conditions of ambient temperature, supply voltage and clock frequency. Typical values are based on normal temperature (25℃) and V_{DD} = 3.3V environment, which can be used for design guidance.

The data obtained through comprehensive evaluation, design simulation or process characteristics will not be tested on the production line. On the basis of comprehensive evaluation, the minimum and maximum values are statistically obtained after sample testing. Unless were specifically explained that is a measured value, the characteristic parameters are guaranteed by comprehensive evaluation or design.

Power supply plan:

Figure 4-1 Typical circuit of power supply



4.2 Absolute maximum ratings

Operating in critical ratings or exceeding the absolute maximum ratings may cause the chip to work abnormally or even be damaged.

Table 4-1 Absolute maximum ratings

Symbol	Description	Min.	Max.	Unit
T_A	Ambient temperature during operation	-40	85	℃
T_S	Ambient temperature during storage	-40	125	℃
V_{DD}-V_{SS}	External main supply voltage (includingV_{DDA} and V_{DD})	-0.3	4.0	V
V_{IO}-V_{SS}	IO domain supply voltage	-0.3	4.0	V
V_{IN}	Input voltage on the FT (5V tolerant) pin	V_{SS}-0.3	5.5	V
	Input voltage on other pins	V_{SS}-0.3	V_{DD}+0.3	
$\|\triangle V_{DD\_x}\|$	Variations between different main power supply pins		50	mV
$\|\triangle V_{IO\_x}\|$	Variations between different IO power supply pins		50	mV
$\|\triangle V_{SS\_x}\|$	Variations between different ground pins		50	mV
$V_{ESD(HBM)}$	Electrostatic discharge voltage (human body model, non-contact)		4K	V

I_{VDD}	Total current into $V_{DD}/V_{DDA}/V_{IO}$ power lines (source)		150	mA
I_{Vss}	Total current out of V_{SS} ground lines (sink)		150	
I_{IO}	Sink current on any I/O and control pin		25	
	Output current on any I/O and control pin		-25	
$I_{INJ(PIN)}$	Injected current on NRST pin		+/-5	
	Injected current on HSE's OSC_IN pin and LSE's OSC_IN pin		+/-5	
	Injected current on other pins		+/-5	
$\sum I_{INJ(PIN)}$	Total injected current on all IOs and control pins		+/-25	

4.3 Electrical characteristics

4.3.1 Operating conditions

Table 4-2 General operating conditions

Symbol	Parameter	Condition	Min.	Max.	Unit
F_{HCLK}	Internal AHB clock frequency			144	MHz
F_{PCLK1}	Internal APB1 clock frequency			144	MHz
F_{PCLK2}	Internal APB2 clock frequency			144	MHz
V_{DD}	Standard operating voltage		2.4	3.6	V
		Use USB or ETH	3.0	3.6	
V_{IO}	Output voltage on most IO pins	V_{IO} cannot be more than V_{DD}	2.4	3.6	V
V_{DDA}	Analog operating voltage (ADC is not used)	V_{DDA} must be the same as V_{IO}, V_{REF+} cannot be higher than V_{DDA}, V_{REF-} is equal to V_{SS}.	2.4	3.6	V
	Analog operating voltage (ADC is used)				
V_{BAT}(1)	Backup operating voltage	Cannot be more than V_{DD}	1.8	3.6	V
T_A	Ambient temperature		-40	85	℃
T_J	Junction temperature range		-40	85	℃

Note: 1. The connection line from the battery to VBAT should be as short as possible.

Table 4-3 Power-on and power-down conditions

Symbol	Parameter	Condition	Min.	Max.	Unit
t_{VDD}	V_{DD} rise time rate		0	∞	us/V
	V_{DD} fall time rate		30	∞	

4.3.2 Embedded reset and power control block characteristics

Table 4-4 Reset and voltage monitor (For PDR, select high threshold gear)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{PVD}(1)	Programmable voltage detector level selection	PLS[2:0] = 000 (rising edge)		2.39		V
		PLS[2:0] = 000 (falling edge)		2.31		V
		PLS[2:0] = 001 (rising edge)		2.56		V
		PLS[2:0] = 001 (falling edge)		2.48		V
		PLS[2:0] = 010 (rising edge)		2.65		V

		PLS[2:0] = 010 (falling edge)		2.57		V
		PLS[2:0] = 011 (rising edge)		2.78		V
		PLS[2:0] = 011 (falling edge)		2.69		V
		PLS[2:0] = 100 (rising edge)		2.89		V
		PLS[2:0] = 100 (falling edge)		2.81		V
		PLS[2:0] = 101 (rising edge)		3.05		V
		PLS[2:0] = 101 (falling edge)		2.96		V
		PLS[2:0] = 110 (rising edge)		3.17		V
		PLS[2:0] = 110 (falling edge)		3.08		V
		PLS[2:0] = 111 (rising edge)		3.31		V
		PLS[2:0] = 111 (falling edge)		3.21		V
$V_{PVDhyst}$	PVD hysteresis			0.08		V
$V_{POR/PDR}$	Power-on/power-down reset threshold	Rising edge	1.9	2.2	2.4	V
		Falling edge	1.9	2.2	2.4	V
$V_{PDRhyst}$	PDR hysteresis			20		mV
$t_{RSTTEMPO}$	Power on reset		24	28	30	mS
	Other resets		8	10	30	

Note: 1. Normal temperature test value.

4.3.3 Embedded reference voltage

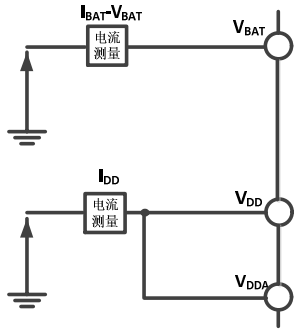
Table 4-5 Embedded reference voltage

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{REFINT}	Internal reference voltage	T_A = -40℃~85℃	1.17	1.2	1.23	V
$T_{S\_vrefint}$	ADC sampling time when reading the internal reference voltage				17.1	us

4.3.4 Supply current characteristics

Current consumption is a comprehensive index of a variety of parameters and factors. These parameters and factors include operating voltage, ambient temperature, I/O pin load, product software configuration, operating frequency, I/O pin flip rate, and program in memory The location in and the executed code, etc. The current consumption measurement method is as follows:

Figure 4-2 Current consumption measurement



The microcontroller is in the following conditions:
Under normal temperature conditions and when V_{DD} = 3.3V, all IO ports are configured with pull-up inputs, only one of HSE and HIS is enabled, HSE=8M (32M for the V208, V203RBT6), HIS=8M (calibrated), $F_{PLCK1}=F_{HCLK}/2$, $F_{PLCK2}=F_{HCLK}$, PLL is enabled when FHCLK>8MHz. Enable or disable the power consumption of all peripheral clocks.

Table 4-6-1 Typical current consumption in Run mode, the data processing code runs from the internal Flash (V30x)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Run mode	External clock	F_{HCLK} = 144MHz	31.2	19.3	mA
			F_{HCLK} = 72MHz	16.5	10.1	
			F_{HCLK} = 48MHz	12.0	7.2	
			F_{HCLK} = 36MHz	10.3	6.1	
			F_{HCLK} = 24MHz	7.7	4.4	
			F_{HCLK} = 16MHz	6.3	3.5	
			F_{HCLK} = 8MHz	4.4	1.8	
			F_{HCLK} = 4MHz	3.5	1.3	
			F_{HCLK} = 500kHz	2.8	0.8	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler to reduce the frequency	F_{HCLK} = 144MHz	31.3	19.7	
			F_{HCLK} = 72MHz	16.5	10.2	
			F_{HCLK} = 48MHz	11.9	7.2	
			F_{HCLK} = 36MHz	9.8	5.9	
			F_{HCLK} = 24MHz	7.3	4.4	
			F_{HCLK} = 16MHz	6.0	3.3	
			F_{HCLK} = 8MHz	4.1	1.8	
			F_{HCLK} = 4MHz	3.3	1.3	
			F_{HCLK} = 500kHz	2.6	0.8	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1 and GPIOA are not disabled when all peripheral clocks are disabled.

Table 4-6-2 Typical current consumption in Run mode, the data processing code runs from the internal Flash (V203)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Run mode	External clock	F_{HCLK} = 144MHz	12.08	8.24	mA
			F_{HCLK} = 72MHz	6.43	4.43	
			F_{HCLK} = 48MHz	4.51	3.18	
			F_{HCLK} = 36MHz	4.12	2.98	
			F_{HCLK} = 24MHz	2.72	1.95	
			F_{HCLK} = 16MHz	2.18	1.68	
			F_{HCLK} = 8MHz	1.21	0.99	

			F_{HCLK} = 4MHz	0.92	0.80	
			F_{HCLK} = 500kHz	0.65	0.64	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler to reduce the frequency	F_{HCLK} = 144MHz	11.72	7.44	
			F_{HCLK} = 72MHz	6.02	3.86	
			F_{HCLK} = 48MHz	4.13	2.69	
			F_{HCLK} = 36MHz	3.31	2.25	
			F_{HCLK} = 24MHz	2.23	1.53	
			F_{HCLK} = 16MHz	1.68	1.18	
			F_{HCLK} = 8MHz	0.86	0.63	
			F_{HCLK} = 4MHz	0.56	0.45	
			F_{HCLK} = 500kHz	0.31	0.29	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1 and GPIOA are not disabled when all peripheral clocks are disabled.

Table 4-6-2 Typical current consumption in Run mode, the data processing code runs from the internal Flash (V208, V203RBT6)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Run mode	External clock	F_{HCLK} = 144MHz	21.37	16.77	mA
			F_{HCLK} = 72MHz	10.91	8.73	
			F_{HCLK} = 48MHz	7.58	6.16	
			F_{HCLK} = 36MHz	6.49	5.29	
			F_{HCLK} = 24MHz	4.59	3.61	
			F_{HCLK} = 16MHz	3.13	2.59	
			F_{HCLK} = 8MHz	2.0	1.71	
			F_{HCLK} = 4MHz	1.42	1.28	
			F_{HCLK} = 500KHz	1.0	0.95	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler to reduce the frequency	F_{HCLK} = 144MHz	20.75	16.27	
			F_{HCLK} = 72MHz	10.74	8.53	
			F_{HCLK} = 48MHz	7.42	5.98	
			F_{HCLK} = 36MHz	5.96	5.05	
			F_{HCLK} = 24MHz	4.62	3.41	
			F_{HCLK} = 16MHz	3.03	2.49	
			F_{HCLK} = 8MHz	1.66	1.42	
			F_{HCLK} = 4MHz	1.11	1.0	
			F_{HCLK} = 500kHz	0.63	0.62	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1 and GPIOA are not disabled when all peripheral clocks are disabled.

Table 4-7-1 Typical current consumption in Sleep mode, data processing code runs from internal Flash or SRAM (V30x)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Sleep mode (In this case, peripheral power supply and clock are maintained)	External clock	F_{HCLK} = 144MHz	15.1	4.1	mA
			F_{HCLK} = 72MHz	8.9	2.4	
			F_{HCLK} = 48MHz	6.9	1.9	
			F_{HCLK} = 36MHz	6.5	2.1	
			F_{HCLK} = 24MHz	5.1	1.4	
			F_{HCLK} = 16MHz	4.6	1.39	
			F_{HCLK} = 8MHz	3.5	0.94	
			F_{HCLK} = 4MHz	3.1	0.87	
			F_{HCLK} = 500kHz	2.8	0.82	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler to reduce the frequency	F_{HCLK} = 144MHz	15.0	4.1	
			F_{HCLK} = 72MHz	8.7	2.4	
			F_{HCLK} = 48MHz	6.7	1.85	
			F_{HCLK} = 36MHz	5.9	1.74	
			F_{HCLK} = 24MHz	4.8	1.4	
			F_{HCLK} = 16MHz	4.2	1.3	
			F_{HCLK} = 8MHz	3.2	0.9	
			F_{HCLK} = 4MHz	2.8	0.84	
			F_{HCLK} = 500kHz	2.5	0.79	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1, GPIOA and power module are not disabled.

Table 4-7-2 Typical current consumption in Sleep mode, data processing code runs from internal Flash or SRAM (V203)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Sleep mode (In this case, peripheral power supply and clock are maintained)	External clock	F_{HCLK} = 144MHz	7.37	3.05	mA
			F_{HCLK} = 72MHz	4.0	1.88	
			F_{HCLK} = 48MHz	2.9	1.7	
			F_{HCLK} = 36MHz	2.9	1.48	
			F_{HCLK} = 24MHz	1.93	1.2	
			F_{HCLK} = 16MHz	1.64	1.0	
			F_{HCLK} = 8MHz	0.94	0.72	
			F_{HCLK} = 4MHz	0.78	0.66	
			F_{HCLK} = 500kHz	0.63	0.62	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler	F_{HCLK} = 144MHz	7.1	2.72	
			F_{HCLK} = 72MHz	3.65	1.56	
			F_{HCLK} = 48MHz	2.56	1.15	
			F_{HCLK} = 36MHz	2.17	1.06	

		to reduce the frequency	F_{HCLK} = 24MHz	1.46	0.76	
			F_{HCLK} = 16MHz	1.2	0.68	
			F_{HCLK} = 8MHz	0.6	0.4	
			F_{HCLK} = 4MHz	0.44	0.34	
			F_{HCLK} = 500kHz	0.3	0.28	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1, GPIOA and power module are not disabled.

Table 4-7-3 Typical current consumption in Sleep mode, data processing code runs from internal Flash or SRAM (V208, V203RBT6)

Symbol	Parameter	Condition		Typ.		Unit
				All peripherals enabled	All peripherals disabled(2)	
I_{DD}(1)	Supply current in Sleep mode (In this case, peripheral power supply and clock are maintained)	External clock	F_{HCLK} = 144MHz	8.17	3.69	mA
			F_{HCLK} = 72MHz	4.75	2.16	
			F_{HCLK} = 48MHz	3.35	1.69	
			F_{HCLK} = 36MHz	3.29	1.89	
			F_{HCLK} = 24MHz	2.18	1.26	
			F_{HCLK} = 16MHz	1.63	1.11	
			F_{HCLK} = 8MHz	1.23	0.98	
			F_{HCLK} = 4MHz	1.06	0.94	
			F_{HCLK} = 500kHz	0.97	0.91	
		Runs on the high-speed internal RC oscillator (HSI), using AHB prescaler to reduce the frequency	F_{HCLK} = 144MHz	7.65	3.44	
			F_{HCLK} = 72MHz	4.61	2.02	
			F_{HCLK} = 48MHz	3.22	1.55	
			F_{HCLK} = 36MHz	2.73	1.44	
			F_{HCLK} = 24MHz	1.9	1.1	
			F_{HCLK} = 16MHz	1.48	0.95	
			F_{HCLK} = 8MHz	0.93	0.69	
			F_{HCLK} = 4MHz	0.75	0.63	
			F_{HCLK} = 500kHz	0.58	0.56	

Note: 1. The above are measured parameters.

2. During the test, the clocks of USART1, GPIOA and power module are not disabled.

Table 4-8-1 Typical current consumption in Stop and Standby mode (V30x)

Symbol	Parameter	Condition	Typ.	Unit
I_{DD}	Supply current in Stop mode	The voltage regulator is in Run mode, and the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog)	110.5	uA

		The voltage regulator is in low power mode, the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog, PVD off)	34	
	Supply current in Standby mode	Low-speed internal RC oscillator and independent watchdog are on	1.91	
		The low-speed internal RC oscillator is on, and the independent watchdog is off	1.9	
		Low-speed internal RC oscillator and independent watchdog are off, low-speed external oscillator and RTC are off	1.18	
I_{DD_VBAT}	Backup domain supply current (Remove V_{DD} and V_{DDA}, only powered by V_{BAT}	Low-speed external oscillator and RTC are on	1.9	

Note: The above are measured parameters.

Table 4-8-2 Typical current consumption in Stop and Standby mode (V203)

Symbol	Parameter	Condition	Typ.	Unit
I_{DD}	Supply current in Stop mode	The voltage regulator is in Run mode, and the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog)	60	uA
		The voltage regulator is in low power mode, the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog, PVD off)	12	
	Supply current in Standby mode	Low-speed internal RC oscillator and independent watchdog are on	1.3	
		The low-speed internal RC oscillator is on, and the independent watchdog is off	1.3	
		Low-speed internal RC oscillator and independent watchdog are off, low-speed external oscillator and RTC are off	0.6	
I_{DD_VBAT}	Backup domain supply current (Remove V_{DD} and V_{DDA}, only powered by V_{BAT}	Low-speed external oscillator and RTC are on	1.3	

Note: The above are measured parameters.

Table 4-8-3 Typical current consumption in Stop and Standby mode (V208, V203RBT6)

Symbol	Parameter	Condition	Typ.	Unit
I_{DD}	Supply current in Stop mode	The voltage regulator is in Run mode, and the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog)	253.4	uA
		The voltage regulator is in low power mode, the low-speed and high-speed internal RC oscillators and external oscillators are off (no independent watchdog, PVD off)	19.5	
	Supply current in Standby mode	Low-speed internal RC oscillator and independent watchdog are on	1.21	
		The low-speed internal RC oscillator is on, and the independent watchdog is off	1.18	
		Low-speed internal RC oscillator and independent watchdog are off, low-speed external oscillator and RTC are off	0.6	
I_{DD_VBAT}	Backup domain supply current (Remove V_{DD} and V_{DDA}, only powered by V_{BAT}	Low-speed external oscillator and RTC are on	1.23	

Note: The above are measured parameters.

4.3.5 External clock source characteristics

Table 4-9 From external high-speed clock

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{HSE_ext}	External clock frequency		3	8	25	MHz
		applied for V208, V203RBT6		32		
V_{HSEH}(1)	OSC_IN input pin high level voltage		$0.8V_{IO}$		V_{IO}	V
V_{HSEL}(1)	OSC_IN input pin low-level voltage		0		$0.2V_{IO}$	V
$C_{in(HSE)}$	OSC_IN input capacitance			5		pF
$DuCy_{(HSE)}$	Duty cycle			50		%
I_L	OSC_IN input leakage current				±1	uA

Note: 1. Failure to meet this condition may cause level recognition error.

Figure 4-3 External high-frequency clock source circuit

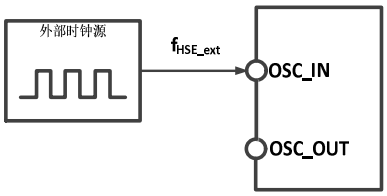


Table 4-10 From external low-speed clock

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{LSE_ext}	User external clock frequency			32.768	1000	kHz
V_{LSEH}	OSC32_IN input pin high level voltage		$0.8V_{DD}$		V_{DD}	V
V_{LSEL}	OSC32_IN input pin low voltage		0		$0.2V_{DD}$	V
$C_{in(LSE)}$	OSC32_IN input capacitance			5		pF
$DuCy_{(LSE)}$	Duty cycle			50		%
I_L	OSC32_IN input leakage current				±1	uA

Figure 4-4 External low-frequency clock source circuit

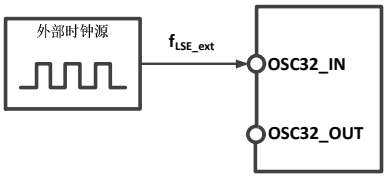


Table 4-11 High-speed external clock generated from a crystal/ceramic resonator

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{OSC_IN}	Resonator frequency		3	8	25	MHz
		applied for V208, V203RBT6		32(2)		
R_F	Feedback resistance			250		kΩ
C	Recommended load capacitance and corresponding crystal series impedance RS	R_S=60Ω(1)		20		pF
I_2	HSE drive current	V_{DD} = 3.3V，20p load		0.53		mA
g_m	Oscillator transconductance	Startup		17.5		mA/V
$t_{SU(HSE)}$	Startup time	V_{DD} is stable, 8M crystal		2.5		ms

Note 1: It is recommended that the ESR of 25M crystal should not exceed 60 Ω, and it can be relaxed if it is lower than 25M.

2. No external load capacitor is required.

Circuit reference design and requirements:

The load capacitance of the crystal is subject to the recommendation of the crystal manufacturer, C_{L1}=C_{L2}, generally 10～20pF is recommended.

For the CH32V208xx series and CH32V203RB, they are connected with external 32M crystals, and they have built-in load capacitor, so the external circuit is not necessary.

Figure 4-5 Typical circuit of external 8M crystal

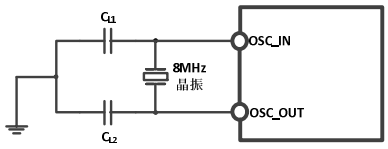


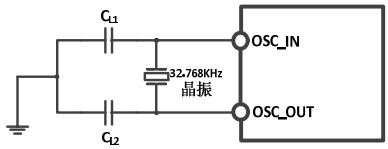
Table 4-12 Low-speed external clock generated by generated from a crystal/ceramic resonator (f_{LSE}=32.768kHz)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
R_F	Feedback resistance			5		MΩ
C	Recommended load capacitance and corresponding crystal serial impedance R_S	R_S<70kΩ			15	pF
i_2	LSE drive current	VDD = 3.3V		0.35		uA
g_m	Oscillator transconductance	Startup		25.3		uA/V
$t_{SU(LSE)}$	Startup time	VDD is stable		800		mS

Circuit reference design and requirements:

The load capacitance of the crystal is subject to the recommendation of the crystal manufacturer, C_{L1}=C_{L2}, generally 10～20pF is recommended.

Figure 4-6 Typical circuit of external 32.768K crystal



Note: The load capacitance C_L is calculated by the following formula: $C_L = C_{L1} \times C_{L2} / (C_{L1} + C_{L2}) + C_{stray}$. C_{stray} is the capacitance of the pin and the PCB board or PCB-related capacitance. Its typical value is between 2pF and 7pF.

4.3.6 Internal clock source characteristics

Table 4-13 Internal high-speed (HSI) RC oscillator characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{HSI}	Frequency (after calibration)			8		MHz
$DuCy_{HSI}$	Duty cycle		45	50	55	%
ACC_{HSI}	Accuracy of HSI oscillator (after calibration)	TA = 0℃～70℃	-1.0		1.6	%
		TA = -40℃～85℃	-2.2		2.2	%
$t_{SU(HSI)}$	HSI oscillator startup stabilization time			10		us
$I_{DD(HSI)}$	HSI oscillator power consumption		120	180	270	uA

Table 4-14 Internal low-speed (LSI) RC oscillator characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{LSI}	Frequency		25	39	60	kHz
		applied for V208,	25	32	45	

		V203RBT6				
$DuCy_{LSI}$	Duty cycle		45	50	55	%
ACC_{LSI}	Accuracy of LSI oscillator (after calibration)	applied for V208, constant temperature (±1℃), it is recommended to calibrate once every 10s		±500		ppm
$t_{SU(LSI)}$	LSI oscillator startup stabilization time			100		us
$I_{DD(LSI)}$	LSI oscillator power consumption			0.6		uA

4.3.7 PLL characteristics

Table 4-15 PLL characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{PLL_IN}	PLL input clock		3	8	25	MHz
		applied for V208, V203RBT6	4	8	25	
	PLL input clock duty cycle		40		60	%
F_{PLL_OUT}	PLL multiplier output clock		18		144(1)	MHz
		applied for V208, V203RBT6	40		240(1)	
t_{LOCK}	PLL lock time				200	us

Note 1: The frequency multiplier must be selected to meet the PLL output frequency range.

Table 4-16 PLL2 and PLL3 characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{PLL_IN}	PLL input clock		3		25	MHz
	PLL input clock duty cycle1		40		60	%
F_{PLL_OUT}	PLL multiplier output clock		30		75(1)	MHz
F_{VCO}	VCO output clock		60		150	MHz
t_{LOCK1}	PLL lock time				200	us

Note 1: The frequency multiplier must be selected to meet the PLL output frequency range.

4.3.8 Wakeup time from low power mode

Table 4-17-1 Wakeup time from low power mode(1) (V30x)

Symbol	Parameter	Condition	Typ.	Unit
$t_{wusleep}$	Wakeup from Sleep mode	Wake up using HSI RC clock	2.4	us
t_{wustop}	Wakeup from Stop mode (voltage regulator is in Run mode)	Wake on HSI RC clock	23.1	us
	Wakeup from Stop mode (voltage regulator is in low power mode)	Voltage regulator wake-up time from low power mode + HSI RC clock wake up	76.7	us
$t_{WUSTDBY}$	Wakeup from Standby mode	LDO stabilization time + HSI RC clock wake up + code load time(2)	8.9	ms

		(take 256K as example)		

Note: 1. The above parameters are measured parameters.

2. The code load time is calculated based on the current zero wait area capacity configured by the chip and the size of the loading configuration clock.

Table 4-17-2 Wakeup time from low power mode(1) (V208, V203RBT6)

Symbol	Parameter	Condition	Typ.	Unit
$t_{wusleep}$	Wakeup from Sleep mode	Wake up using HSI RC clock	2.6	us
t_{wustop}	Wakeup from Stop mode (voltage regulator is in Run mode)	Wake on HSI RC clock	23.1	us
	Wakeup from Stop mode (voltage regulator is in low power mode)	Voltage regulator wake-up time from low power mode + HSI RC clock wake up	299	us
$t_{WUSTDBY}$	Wakeup from Standby mode	LDO stabilization time + HSI RC clock wake up + code load time(2) (take 128K as example)	5.0	ms

Note: 1. The above parameters are measured parameters.

2. The code load time is calculated based on the current zero wait area capacity configured by the chip and the size of the loading configuration clock.

4.3.9 Memory characteristics

Table 4-18 Flash memory characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
F_{prog}	Programming frequency(1)	T_A = -40℃～85℃			72	MHz
t_{prog_page}	Page (256 bytes) programming time	T_A = -40℃～85℃		2		ms
t_{erase_page}	Page (256 bytes) erase time	T_A = -40℃～85℃		16		ms
t_{erase_sec}	Sector (4K bytes) erase time	T_A = -40℃～85℃		16		ms
V_{prog}	Programming voltage		2.4		3.6	V

Note: 1. For the programming frequency of flash, read operation, program operation and erase operation are included. The clock is from HCLK.

Table 4-19 Flash memory endurance and data retention

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
N_{END}	Endurance	T_A = 25℃	10K	80K(1)		times
t_{RET}	Data retention		20			year

Note: The endurance parameter is actual measured, which is not guaranteed.

4.3.10 I/O port characteristics

Table 4-20 General purpose I/O static characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{IH}	Standard I/O pin, input high level voltage		0.41*(V_{DD}-1.8)+1.3		V_{DD}+0.3	V

	FT IO pin, input high level voltage		0.42*(V_{DD}-1.8)+1		5.5	V
V_{IL}	Standard I/O pin, input low-level voltage		-0.3		0.28*(V_{DD}-1.8)+0.6	V
	FT IO pin, input low-level voltage		-0.3		0.32*(V_{DD}-1.8)+0.55	V
V_{hys}	Standard I/O pin Schmitt trigger voltage hysteresis		150			mV
	FT IO pin Schmitt trigger voltage hysteresis		90			
I_{lkg}	Input leakage current	Standard IO port			1	uA
		FT IO port			3	
R_{PU}	Weak pull-up equivalent resistance		30	40	50	kΩ
R_{PD}	Weak pull-down equivalent resistance		30	40	50	kΩ
C_{IO}	I/O pin capacitance			5		pF

Output drive current characteristics

GPIO (General Purpose Input/Output Port) can sink or output up to ±8mA current, and sink or output ±20mA current (not strictly to V_{OL}/V_{OH}). In user applications, the total driving current of all IO pins cannot exceed the absolute maximum ratings given in Section 4.2:

Table 4-21 Output voltage characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
V_{OL}	Output low level when 8 pins are sunk	TTL port, I_{IO} = +8mA		0.4	V
V_{OH}	Output high level when 8 pins are sourced	2.7V< V_{DD} <3.6V	V_{DD}-0.4		
V_{OL}	Output low level when 8 pins are sunk	CMOS port, I_{IO} = +8mA		0.4	V
V_{OH}	Output high level when 8 pins are sourced	2.7V< V_{DD} <3.6V	2.3		
V_{OL}	Output low level when 8 pins are sunk	I_{IO} = +20mA		1.3	V
V_{OH}	Output high level when 8 pins are sourced	2.7V< V_{DD} <3.6V	V_{DD}-1.3		
V_{OL}	Output low level when 8 pins are sunk	I_{IO} = +6mA		0.4	V
V_{OH}	Output high level when 8 pins are sourced	2.4V< V_{DD} <2.7V	V_{DD}-1.3		

Note: In the above conditions, if multiple IO pins are driven at the same time, the total current cannot exceed the absolute maximum ratings given in Table 4.2. In addition, when multiple IO pins are driven at the same time, the current on the power/ground point is very large, which will cause the voltage drop to make the internal IO voltage not reach the power supply voltage in the table, resulting in the drive current being less than the nominal value.

Table 4-22 Input/output AC characteristics

MODEx[1:0] configuration	Symbol	Parameter	Condition	Min.	Max.	Unit
10 （2MHz）	$F_{max(IO)out}$	Maximum frequency	CL=50pF,V_{DD}=2.7-3.6V		2	MHz
	$t_{f(IO)out}$	Output high to low fall time	CL=50pF,V_{DD}=2.7-3.6V		125	ns
	$t_{r(IO)out}$	Output low to high rise time			125	ns
01	$F_{max(IO)out}$	Maximum frequency	CL=50pF,V_{DD}=2.7-3.6V		10	MHz

（10MHz）	$t_{f(IO)out}$	Output high to low fall time	CL=50pF,V_{DD}=2.7-3.6V		25	ns
	$t_{r(IO)out}$	Output low to high rise time			25	ns
11 （50MHz）	$F_{max(IO)out}$	Maximum frequency	CL=30pF,V_{DD}=2.7-3.6V		50	MHz
			CL=50pF,V_{DD}=2.7-3.6V		30	MHz
	$t_{f(IO)out}$	Output high to low fall time	CL=30pF,V_{DD}=2.7-3.6V		20	ns
			CL=50pF,V_{DD}=2.7-3.6V		5	ns
	$t_{r(IO)out}$	Output low to high rise time	CL=30pF,V_{DD}=2.7-3.6V		8	ns
			CL=50pF,V_{DD}=2.7-3.6V		12	ns
	t_{EXTIpw}	The EXTI controller detects the pulse width of the external signal		10		ns

4.3.11 NRST pin characteristics

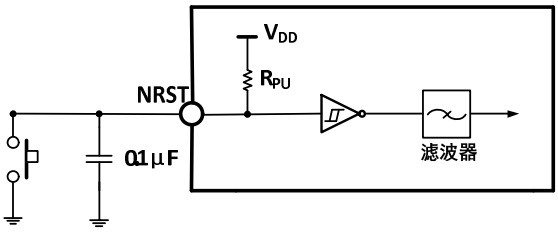
Table 4-24 External reset pin characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$V_{IL(NRST)}$	NRST input low-level voltage		-0.3		0.28*(V_{DD}-1.8)+0.6	V
$V_{IH(NRST)}$	NRST input high level voltage		0.41*(V_{DD}-1.8)+1.3		V_{DD}+0.3	V
$V_{hys(NRST)}$	NRST Schmitt trigger voltage hysteresis		150			mV
R_{PU}(1)	Weak pull-up equivalent resistance		30	40	50	kΩ
$V_{F(NRST)}$	NRST input filtered pulse width				100	ns
$V_{NF(NRST)}$	NRST input not filtered pulse width		300			ns

Note: 1. The pull-up resistor is a real resistor in series with a switchable PMOS implementation. The resistance of this PMOS/NMOS switch is very small (approximately 10%).

Circuit reference design and requirements:

Figure 4-7 Typical circuit of external reset pin



4.3.12 TIM timer characteristics

Table 4-24 TIMx characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
$t_{res(TIM)}$	Timer reference clock		1		$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72MHz	13.9		ns

F_{EXT}	Timer external clock frequency on CH1 to CH4		0	$f_{TIMxCLK}/2$	MHz
		$f_{TIMxCLK}$ = 72MHz	0	36	MHz
R_{esTIM}	Timer resolution			16	位
$t_{COUNTER}$	16-bit counter clock cycle when the internal clock is selected		1	65536	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72MHz	0.0139	910	us
t_{MAX_COUNT}	Maximum possible count			65535	$t_{TIMxCLK}$
		$f_{TIMxCLK}$ = 72MHz		59.6	s

4.3.13 I2C interface characteristics

Figure 4-8 I²C bus timing diagram

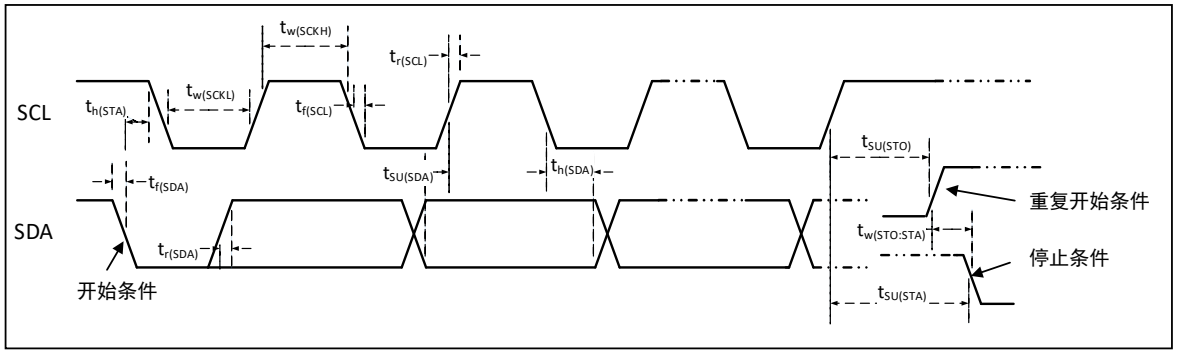


Table 4-25 I²C interface characteristics

Symbol	Parameter	Standard I²C		Fast I²C		Unit
		Min.	Max.	Min.	Max.	
$t_{w(SCKL)}$	SCL clock low time	4.7		1.2		us
$t_{w(SCKH)}$	SCL clock high time	4.0		0.6		us
$t_{SU(SDA)}$	SDA data setup time	250		100		ns
$t_{h(SDA)}$	SDA data hold time	0		0	900	ns
$t_{r(SDA)}/t_{r(SCL)}$	SDA and SCL rise time		1000	20		ns
$t_{f(SDA)}/t_{f(SCL)}$	SDA and SCL fall time		300			ns
$t_{h(STA)}$	Start condition hold time	4.0		0.6		us
$t_{SU(STA)}$	Repeated start condition setup time	4.7		0.6		us
$t_{SU(STO)}$	Stop condition setup time	4.0		0.6		us
$t_{w(STO:STA)}$	Time from stop condition to start condition (bus free)	4.7		1.2		us
C_b	Capacitive load for each bus		400		400	pF

4.3.14 SPI interface characteristics

Figure 4-9 SPI timing diagram in Master mode

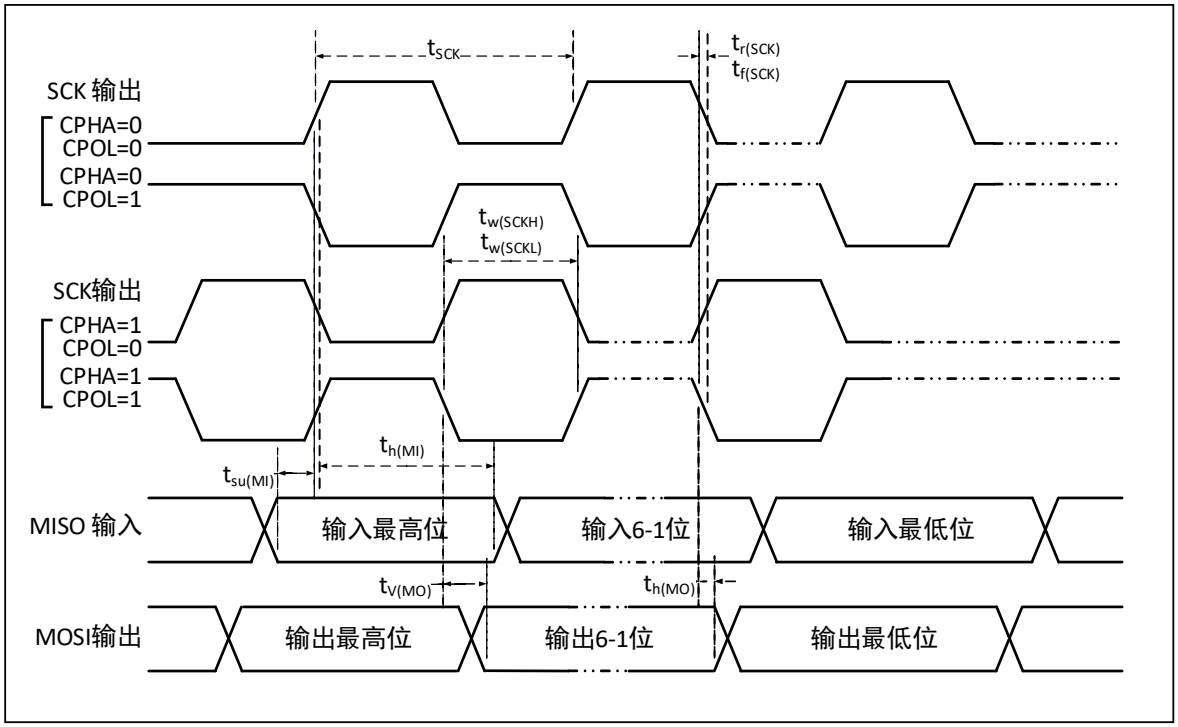


Figure 4-10 SPI timing diagram in Slave mode (CPHA=0)

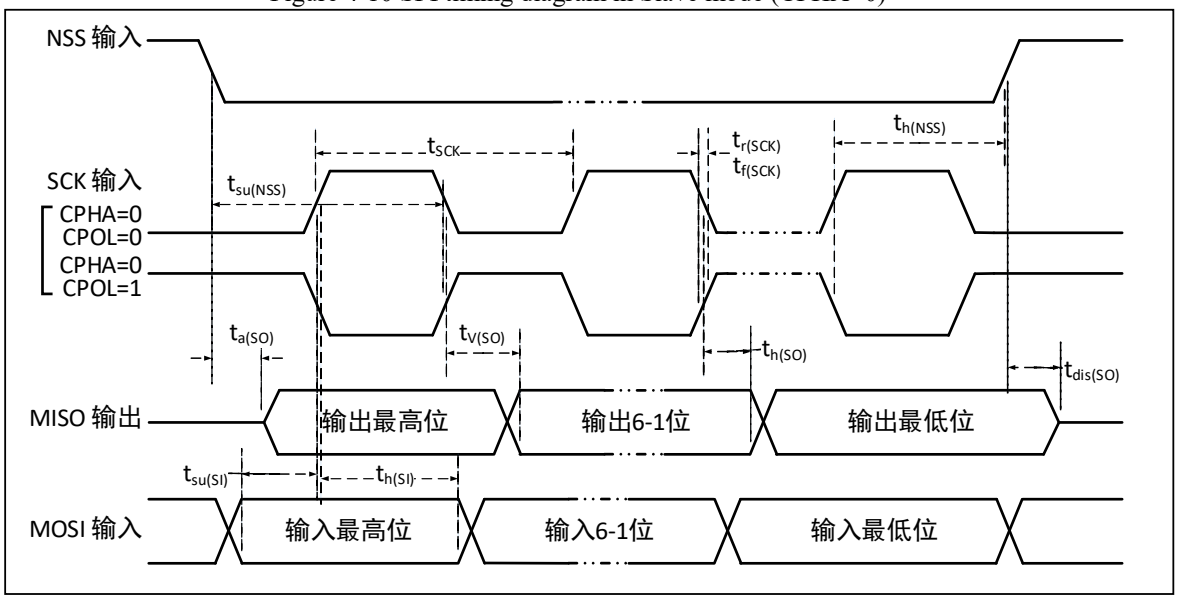


Figure 4-11 SPI timing diagram in Slave mode (CPHA=1)

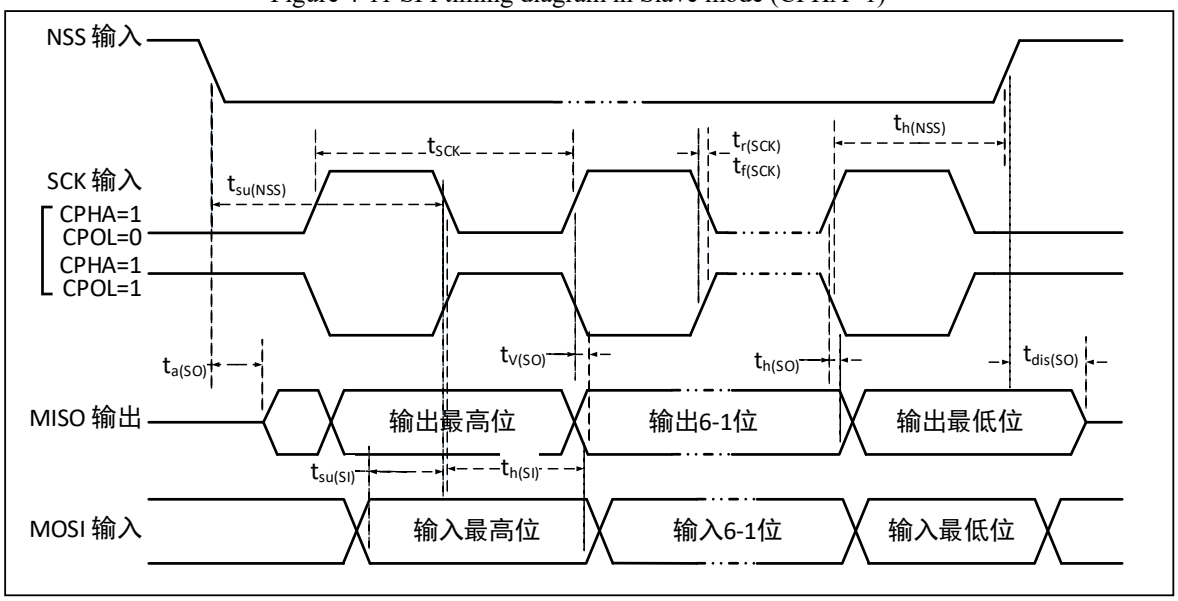


Table 4-26 SPI interface characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
f_{SCK}/t_{SCK}	SPI clock frequency	Master mode		36	MHz
		Slave mode		36	MHz
$t_{r(SCK)}/t_{f(SCK)}$	SPI clock rise and fall time	Load capacitance:C = 30pF		20	ns
$t_{SU(NSS)}$	NSS setup time	Slave mode	$2t_{PCLK}$		ns
$t_{h(NSS)}$	NSS hold time	Slave mode	$2t_{PCLK}$		ns
$t_{w(SCKH)}/t_{w(SCKL)}$	SCK high and low time	Master mode, f_{PCLK} = 36MHz, Prescaler factor = 4	40	60	ns
$t_{SU(MI)}$	Data input setup time	Master mode	5		ns
$t_{SU(SI)}$		Slave mode	5		ns
$t_{h(MI)}$	Data input hold time	Master mode	5		ns
$t_{h(SI)}$		Slave mode	4		ns
$t_{a(SO)}$	Data output access time	Slave mode, f_{PCLK} = 20MHz	0	$1t_{PCLK}$	ns
$t_{dis(SO)}$	Data output disable time	Slave mode	0	10	ns
$t_{V(SO)}$	Data output valid time	Slave mode (After enable edge)		25	ns
$t_{V(MO)}$		Master mode (After enable edge)		5	ns
$t_{h(SO)}$	Data output hold time	Slave mode (After enable edge)	15		ns
$t_{h(MO)}$		Master mode (After enable edge)	0		ns

4.3.15 I2S interface characteristics

Figure 4-12 I²S master timing diagram (Philips protocol)

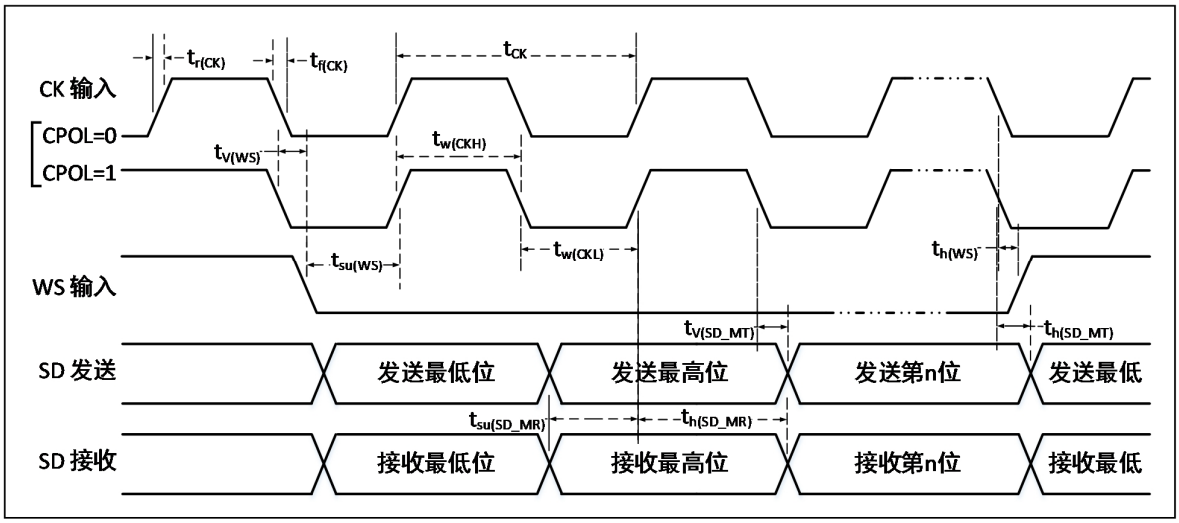


Figure 4-13 I²S slave timing diagram (Philips protocol)

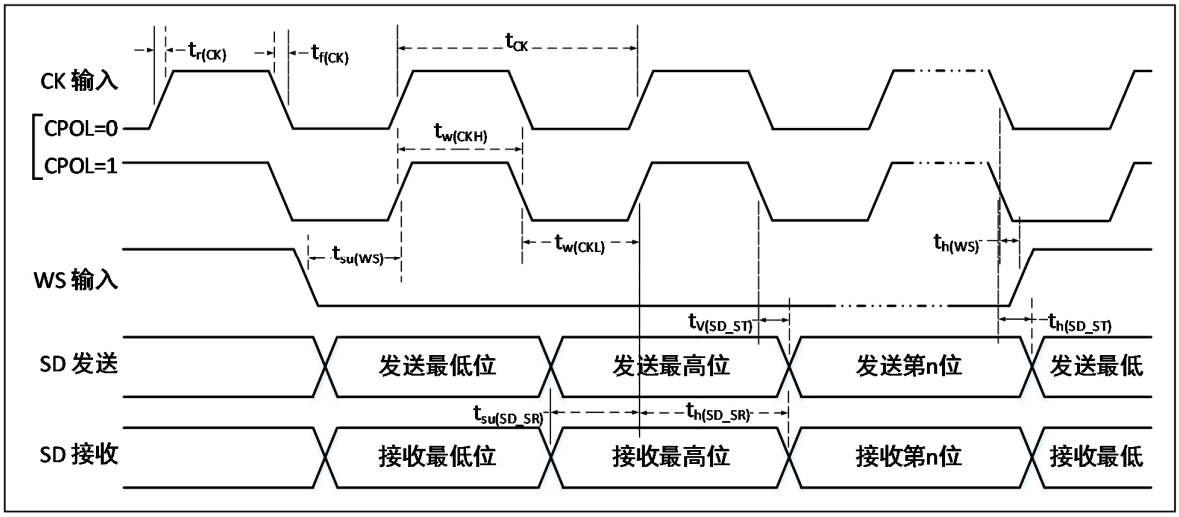


Table 4-27 I²S interface characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
f_{CK}/t_{CK}	I²S clock frequency	Master mode		8	MHz
		Slave mode		8	MHz
$t_{r(CK)}/t_{f(CK)}$	I²S clock rise and fall time	Load capacitance: C = 30pF		20	ns
$t_{V(WS)}$	WS valid time	Master mode		5	ns
$t_{SU(WS)}$	WS setup time	Slave mode	10		ns
$t_{h(WS)}$	WS hold time	Master mode	0		ns
		Slave mode	0		ns
$t_{w(CKH)}/t_{w(CKL)}$	SCK high and low time	Master mode, f_{PCLK} = 36MHz, Prescaler factor =4	40	60	%
$t_{SU(SD\_MR)}$	Data input setup time	Master mode	8		ns

$t_{SU(SD\_SR)}$		Slave mode	8		ns
$t_{h(SD\_MR)}$	Data input hold time	Master mode	5		ns
$t_{h(SD\_SR)}$		Slave mode	4		ns
$t_{h(SD\_MT)}$	Data output hold time	Master mode (After enable edge)		5	ns
$t_{h(SD\_ST)}$		Slave mode (After enable edge)		5	ns
$t_{V(SD\_MT)}$	Data output valid time	Master mode (After enable edge)		5	ns
$t_{v(SD\_ST)}$		Slave mode (After enable edge)		4	ns

4.3.16 USB interface characteristics

Table 4-28 USB characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
V_{DD}	USB operating voltage		3.0	3.6	V
V_{SE}	Single-ended receiver threshold	V_{DD} = 3.3V	1.2	1.9	V
V_{OL}	Static output low level			0.3	V
V_{OH}	Static output high level		2.8	3.6	V
V_{HSSQ}	High-speed suppression information detection threshold		100	150	mV
V_{HSDSC}	High-speed disconnection detection threshold		500	625	mV
V_{HSOI}	High-speed idle level		-10	10	mV
V_{HSOH}	High-speed data high level		360	440	mV
V_{HSOL}	High-speed data low level		-10	10	mV

4.3.17 SD/MMC interface characteristics

Figure 4-14 SD high-speed timing diagram

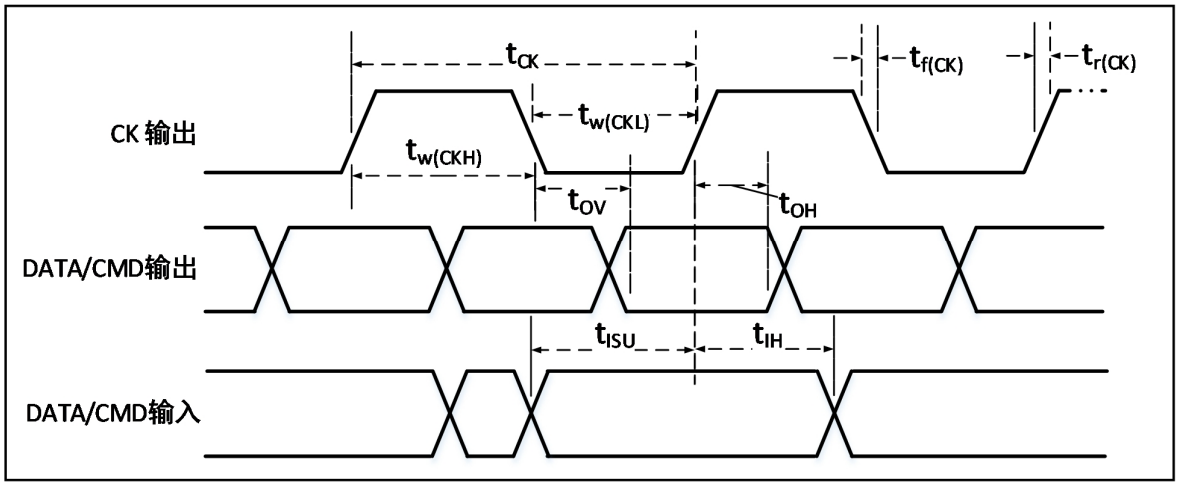


Figure 4-15 SD default timing diagram

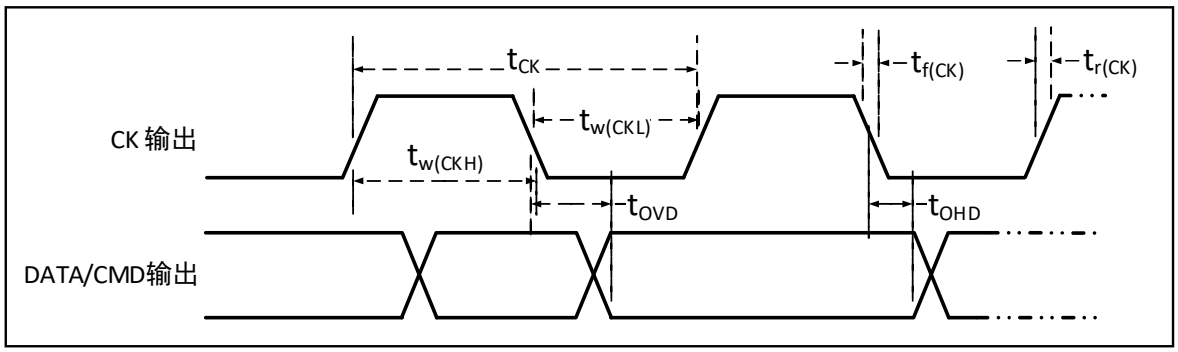


Table 4-29 SD/MMC interface characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
f_{CK}/t_{CK}	Clock frequency in data transfer mode	CL≤30pF		48	MHz
$t_{W(CKL)}$	Clock low time	CL≤30pF	6		ns
$t_{W(CKH)}$	Clock high time	CL≤30pF	6		
$t_{r(CK)}$	Rise Time	CL≤30pF		4	
$t_{f(CK)}$	Fall time	CL≤30pF		4	
CMD/DAT input (refer to CK)					
t_{ISU}	Input setup time	CL≤30pF	7		ns
t_{IH}	Input hold time	CL≤30pF	2		
CMD/DAT output in MMC and SD high-speed mode (refer to CK)					
t_{OV}	Output valid time	CL≤30pF		5	ns
t_{OH}	Output hold time	CL≤30pF	20		
CMD/DAT output in SD default mode (refer to CK)					
t_{OVD}	Output valid default time	CL≤30pF		8	ns
t_{OHD}	Output hold default time	CL≤30pF	20		

4.3.18 FSMC characteristics

Figure 4-16 Asynchronous multiplexed PSRAM/NOR read waveform

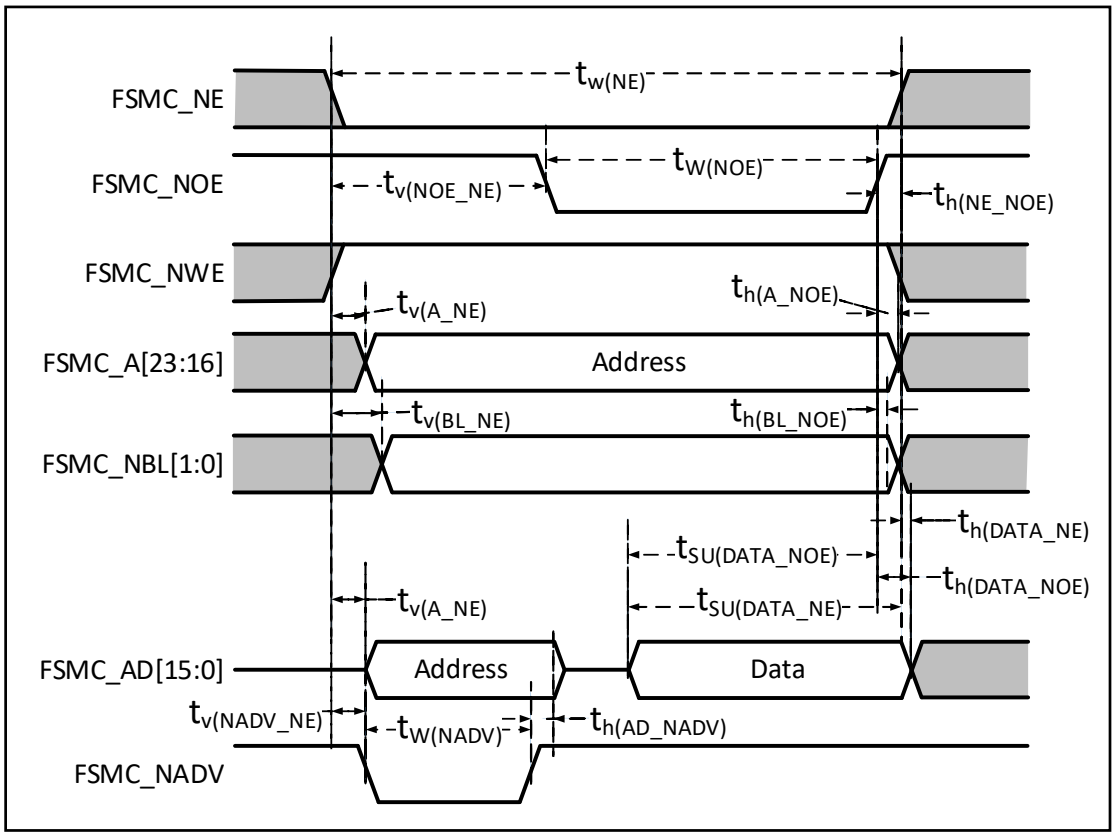


Table 4-30 Asynchronous multiplexed PSRAM/NOR read timings

Symbol	Parameter	Min.	Max.	Unit
$t_{W(NE)}$	FSMC_NE low time	$7t_{HCLK}$		ns
$t_{V(NOE\_NE)}$	FSMC_NE low to FSMC_NOE low	0		
$t_{W(NOE)}$	FSMC_NOE low time	$7t_{HCLK}$		
$t_{h(NE\_NOE)}$	FSMC_NOE high to FSMC_NE high hold time	0		
$t_{V(A\_NE)}$	FSMC_NE low to FSMC_A valid	0	5	
$t_{V(NADV\_NE)}$	FSMC_NE low to FSMC_NADV low	0	5	
$t_{W(NADV)}$	FSMC_NADV low time	t_{HCLK}		
$t_{h(AD\_NADV)}$	FSMC_AD (address) valid hold time after FSMC_NADV high	$2t_{HCLK}$		
$t_{h(A\_NOE)}$	Address hold time after FSMC_NOE high	0		
$t_{h(BL\_NOE)}$	FSMC_BL hold time after FSMC_NOE high	0		
$t_{V(BL\_NE)}$	FSMC_NE low to FSMC_BL valid	0	5	
$t_{SU(DATA\_NE)}$	Data to FSMC_NE high setup time	$3t_{HCLK}$		
$t_{SU(DATA\_NOE)}$	Data to FSMC_NOE high setup time	$3t_{HCLK}$		
$t_{h(DATA\_NE)}$	Data hold time after FSMC_NE high	0		
$t_{h(DATA\_NOE)}$	Data hold time after FSMC_NOE high	0		

Figure 4-17 Asynchronous multiplexed PARAM/NOR write waveform

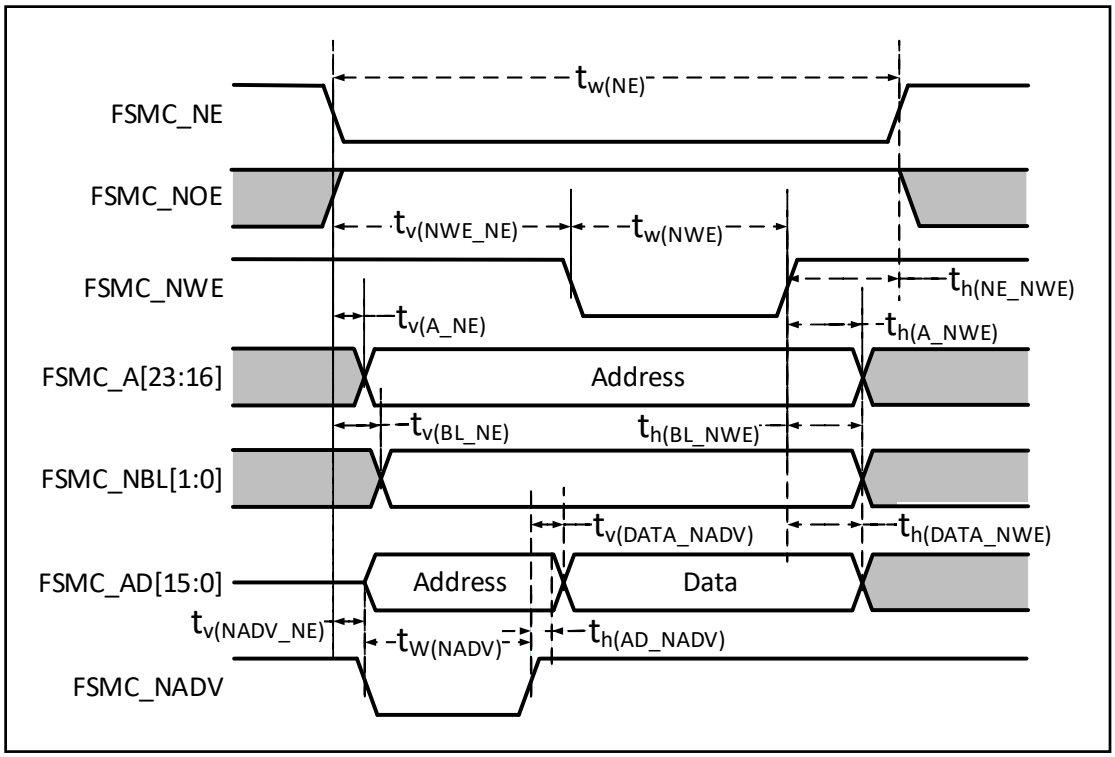


Table 4-31 Asynchronous multiplexed PARAM/NOR write timings

Symbol	Parameter	Min.	Max.	Unit
$t_{W(NE)}$	FSMC_NE low time	$5t_{HCLK}$		ns
$t_{V(NEW\_NE)}$	FSMC_NE low to FSMC_NWE low	$3t_{HCLK}$		
$t_{W(NWE)}$	FSMC_NWE low time	$2t_{HCLK}$		
$t_{h(NE\_NWE)}$	FSMC_NWE high to FSMC_NE high hold time	t_{HCLK}		
$t_{V(A\_NE)}$	FSMC_NE low to FSMC_A valid	0	5	
$t_{V(NADV\_NE)}$	FSMC_NE low to FSMC_NADV low	0	5	
$t_{W(NADV)}$	FSMC_NADV low time	t_{HCLK}		
$t_{h(AD\_NADV)}$	FSMC_AD (address) valid hold time after FSMC_NADV high	$2t_{HCLK}$		
$t_{h(A\_NWE)}$	Address hold time after FSMC_NWE high	t_{HCLK}		
$t_{V(BL\_NE)}$	FSMC_NE low to FSMC_BL valid	0	5	
$t_{h(BL\_NWE)}$	FSMC_BL hold time after FSMC_NWE high	t_{HCLK}		
$t_{V(DATA\_NADV)}$	FSMC_NADV high to data hold time	$2t_{HCLK}$		
$t_{h(DATA\_NWE)}$	Data hold time after FSMC_NWE high	t_{HCLK}		

Figure 4-18 Synchronous multiplexed NOR/PARAM read waveform

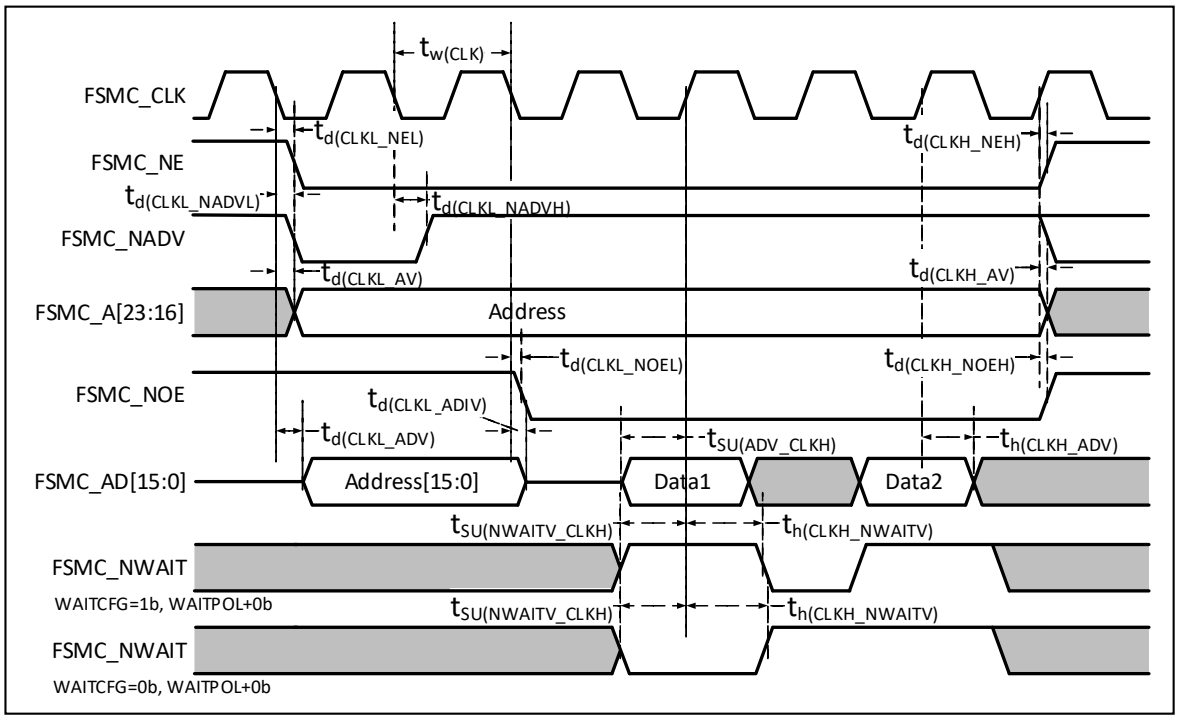


Table 4-32 Synchronous multiplexed NOR/PSRAM read timings

Symbol	Parameter	Min.	Max.	Unit
$t_{W(CLK)}$	FSMC_CLK period	$2t_{HCLK}$		ns
$t_{d(CLKL\_NEL)}$	FSMC_CLK low to FSMC_NE low	0	5	
$t_{d(CLKH\_NEH)}$	FSMC_CLK high to FSMC_NE high	$0.5t_{HCLK}$	$0.5t_{HCLK}$	
$t_{d(CLKL\_NADVL)}$	FSMC_CLK low to FSMC_NADV low	0	5	
$t_{d(CLKL\_NADVH)}$	FSMC_CLK low to FSMC_NADV high	0	5	
$t_{d(CLKL\_AV)}$	FSMC_CLK low to FSMC_Ax valid (x = 16…23)	0	5	
$t_{d(CLKH\_AIV)}$	FSMC_CLK high to FSMC_Ax invalid (x = 16…23)	0	5	
$t_{d(CLKL\_NOEL)}$	FSMC_CLK low to FSMC_NOE low	$2t_{HCLK}$		
$t_{d(CLKH\_NOEH)}$	FSMC_CLK high to FSMC_NOE high	t_{HCLK}		
$t_{d(CLKL\_ADV)}$	FSMC_CLK low to FSMC_AD[15:0] valid	0	5	
$t_{d(CLKL\_ADIV)}$	FSMC_CLK low to FSMC_AD[15:0] invalid	0	5	
$t_{SU(ADV\_CLKH)}$	FSMC_AD[15:0] valid data before FSMC_CLK high	8		
$t_{h(CLKH\_ADV)}$	FSMC_AD[15:0] valid data after FSMC_CLK high	8		
$t_{SU(NWAITV\_CLKH)}$	FSMC_NWAIT valid before FSMC_CLK high	6		
$t_{h(CLKH\_NWAITV)}$	FSMC_NWAIT valid after FSMC_CLK high	2		

Figure 4-19 Synchronous multiplexed PSRAM write waveform

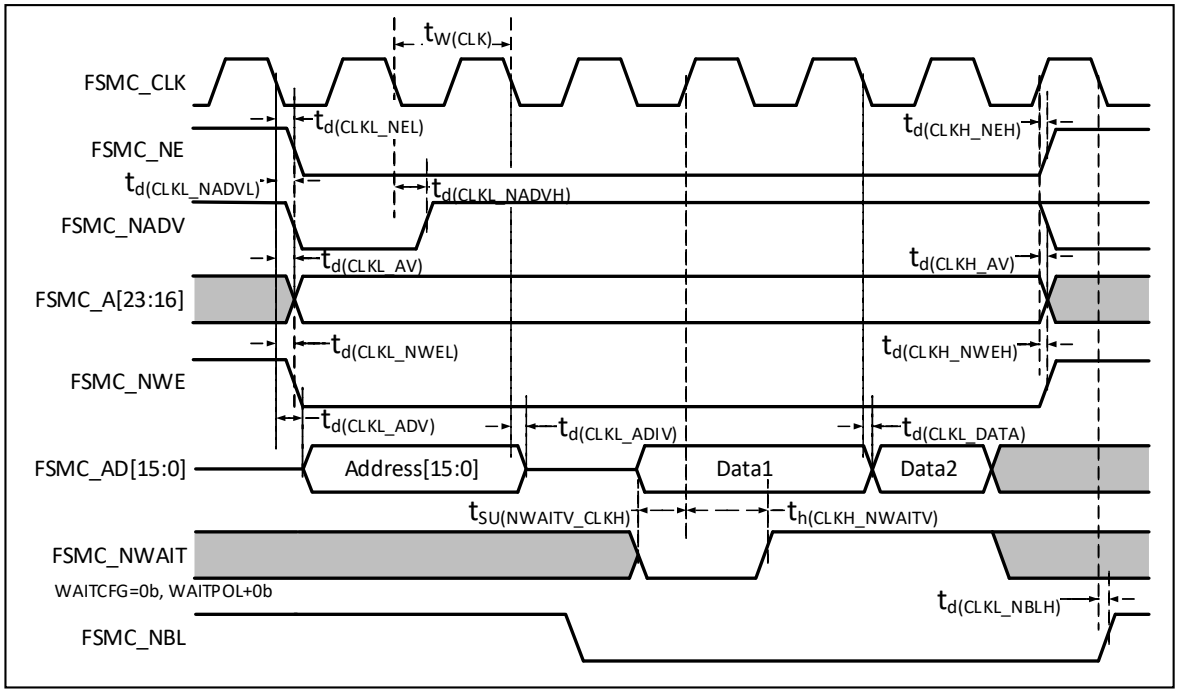


Table 4-33 Synchronous multiplexed PSRAM write timings

Symbol	Parameter	Min.	Max.	Unit
$t_{W(CLK)}$	FSMC_CLK period	$2t_{HCLK}$		ns
$t_{d(CLKL\_NEL)}$	FSMC_CLK low to FSMC_NE low	0	5	
$t_{d(CLKH\_NEH)}$	FSMC_CLK high to FSMC_NE high	$0.5t_{HCLK}$	$0.5t_{HCLK}$	
$t_{d(CLKL\_NADVL)}$	FSMC_CLK low to FSMC_NADV low	0	5	
$t_{d(CLKL\_NADVH)}$	FSMC_CLK low to FSMC_NADV high	0	5	
$t_{d(CLKL\_AV)}$	FSMC_CLK low to FSMC_Ax valid (x = 16…23)	0	5	
$t_{d(CLKH\_AIV)}$	FSMC_CLK high to FSMC_Ax invalid (x = 16…23)	0	5	
$t_{d(CLKL\_NWEL)}$	FSMC_CLK low to FSMC_NWE low	0		
$t_{d(CLKH\_NWEH)}$	FSMC_CLK high to FSMC_NWE high	0		
$t_{d(CLKL\_ADV)}$	FSMC_CLK low to FSMC_AD[15:0] valid	0	5	
$t_{d(CLKL\_ADIV)}$	FSMC_CLK low to FSMC_AD[15:0] invalid	0	5	
$t_{d(CLKL\_DATA)}$	FSMC_AD[15:0] valid after FSMC_CLK low	2		
$t_{SU(NWAITV\_CLKH)}$	FSMC_NWAIT valid before FSMC_CLK high	6		
$t_{h(CLKH\_NWAITV)}$	FSMC_NWAIT valid after FSMC_CLK high	2		
$t_{d(CLKL\_NBLH)}$	FSMC_CLK low to FSMC_NBL high	2		

NAND controller waveform and timing

Test conditions: NAND operation area, 16-bit data width is selected, ECC calculation circuit is enabled, 512-byte page size, other timing configurations are setting registers FSMC_PCR2=0x0002005E, FSMC_PMEM2=0x01020301, FSMC_PATT2=0x01020301.

Figure 4-20 NAND controller read waveform

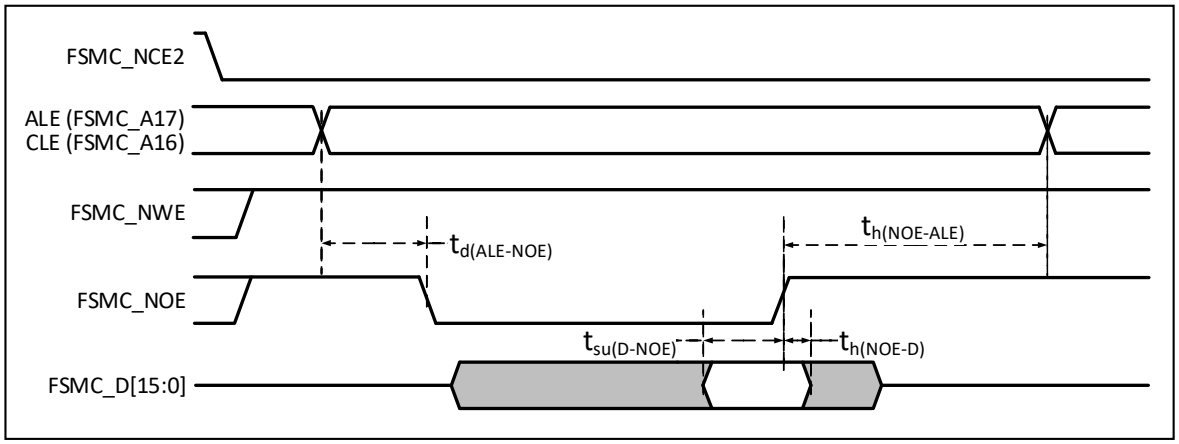


Figure 4-21 NAND controller write waveform

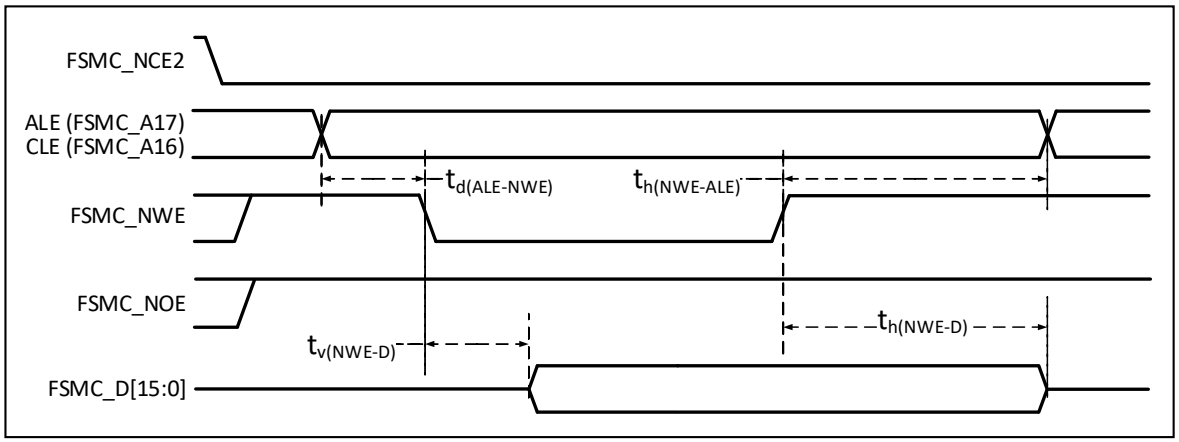


Figure 4-22 NAND controller read waveform in general storage space

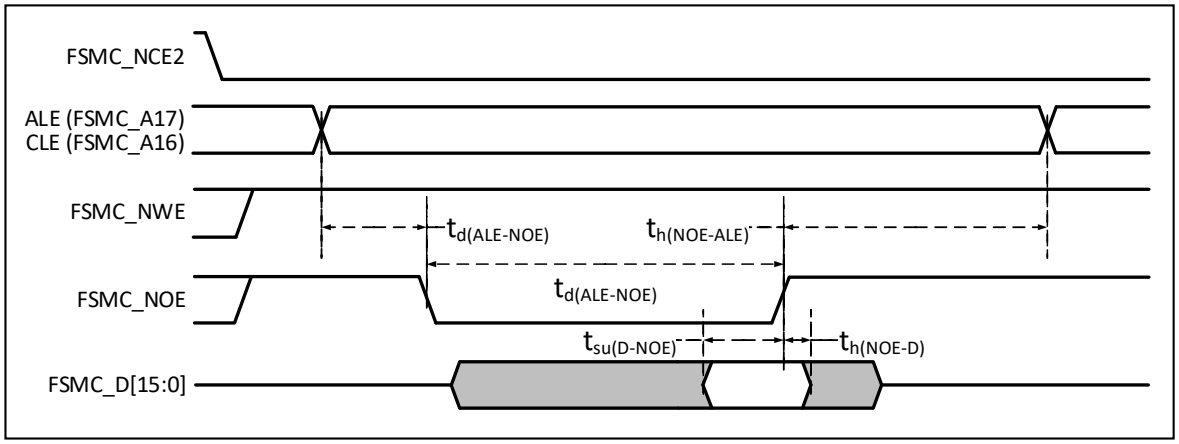


Figure 4-23 NAND controller write waveform in general storage space

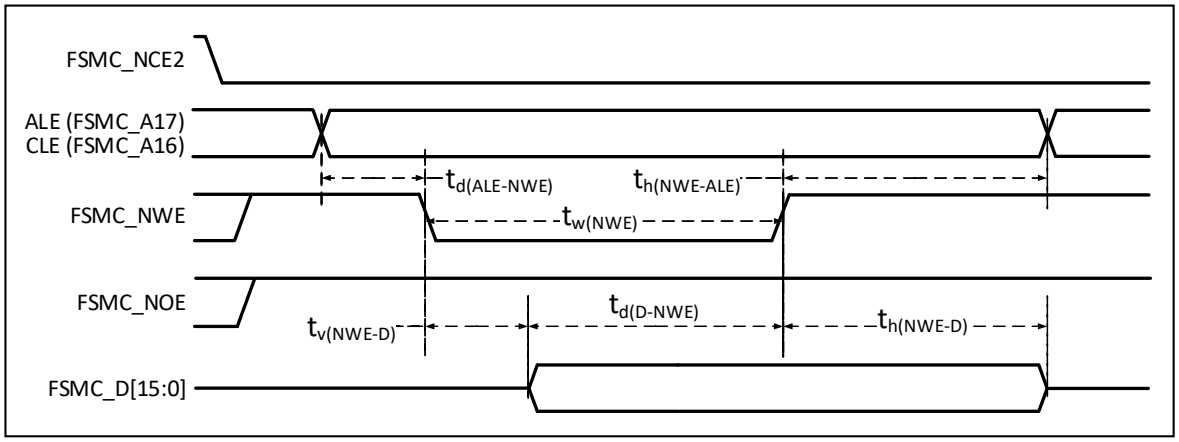


Table 4-34 Timing characteristics of NAND Flash read and write cycles

Symbol	Parameter	Min.	Max.	Unit
$t_{d(D-NWE)}$	Before FSMC_NWE high to FSMC_D[15:0] data valid	$4t_{HCLK}$		ns
$t_{w(NOE)}$	FSMC_NOE low time	$4t_{HCLK}$		
$t_{su(D-NOE)}$	Before FSMC_NOE high to FSMC_D[15:0] data valid	20		
$t_{h(NOE-D)}$	After FSMC_NOE high to FSMC_D[15:0] data valid	15		
$t_{w(NWE)}$	FSMC_NWE low time	$4t_{HCLK}$		
$t_{v(NWE-D)}$	FSMC_NWE low to FSMC_D[15:0] data valid	0		
$t_{h(NWE-D)}$	FSMC_NWE high to FSMC_D[15:0] data invalid	$2t_{HCLK}$		
$t_{d(ALE-NWE)}$	Before FSMC_NWE low to FSMC_ALE valid	$2t_{HCLK}$		
$t_{h(NWE-ALE)}$	FSMC_NWE high to FSMC_ALE invalid	$2t_{HCLK}$		
$t_{d(ALE-NOE)}$	Before FSMC_NOE low to FSMC_ALE valid	$2t_{HCLK}$		
$t_{h(NOE-ALE)}$	FSMC_NOE high to FSMC_ALE invalid	$4t_{HCLK}$		

4.3.19 DVP interface characteristics

Figure 4-24 DVP timing waveform

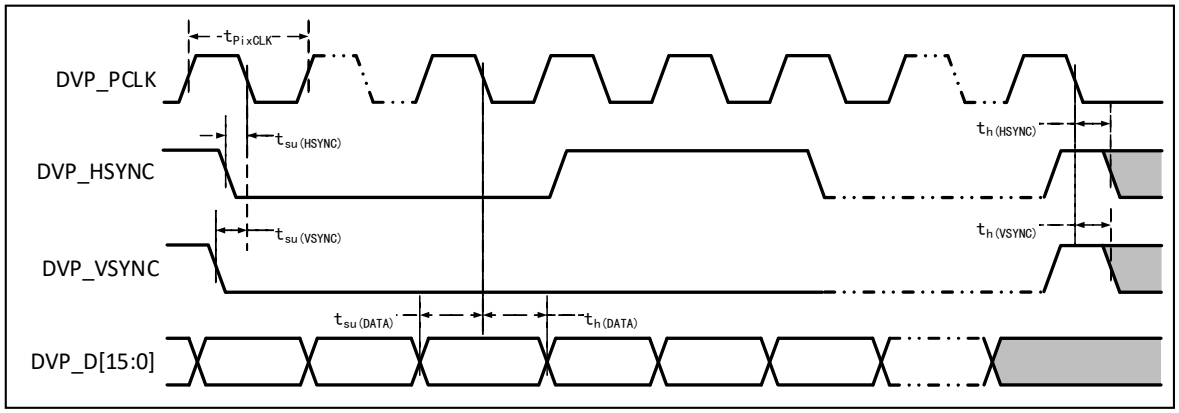


Table 4-35 DVP characteristics

Symbol	Parameter	Min.	Max.	Unit
f_{PixCLK}/t_{PixCLK}	Pixel clock input frequency		144	MHz

$DuCy_{(PixCLK)}$	Pixel clock duty cycle	15		%
$t_{su(DATA)}$	Data setup time	2		ns
$t_{h(DATA)}$	Data hold time	1		
$t_{su(HSYNC)}/t_{su(VSYNC)}$	HSYNC/VSYNC signal input setup time	2		
$t_{h(HSYNC)}/t_{h(VSYNC)}$	HSYNC/VSYNC signal input hold time	1		

4.3.20 Gigabit Ethernet interface characteristics

Figure 4-25 ETH-SMI timing waveform

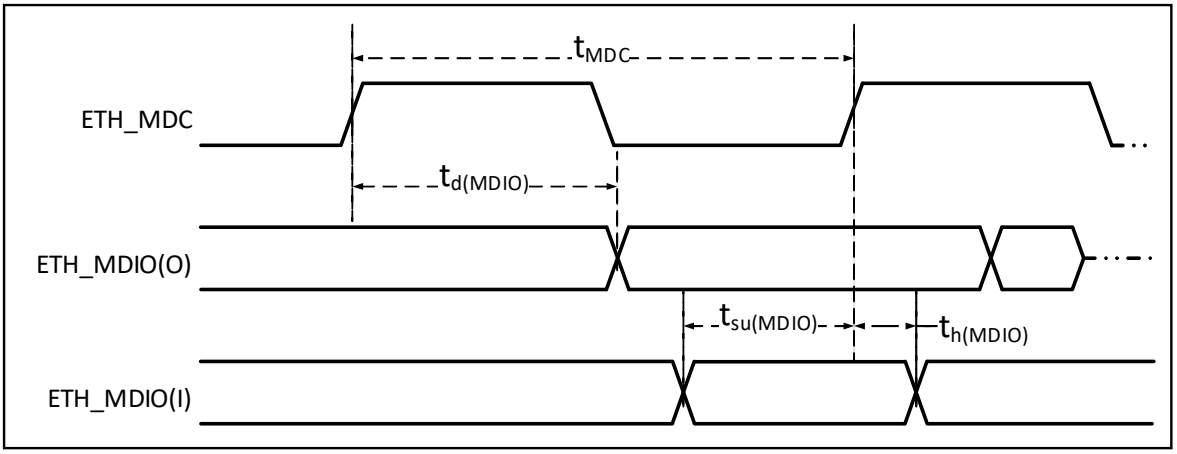


Table 4-36 SMI signal characteristics of Ethernet MAC

Symbol	Parameter	Min.	Typ.	Max.	Unit
f_{MDC}/t_{MDC}	MDC clock frequency			2.5	MHz
$t_{d(MDIO)}$	MDIO write data valid time	0		300	ns
$t_{su(MDIO)}$	Read data setup time	10			
$t_{h(MDIO)}$	Read data hold time	10			

Figure 4-26 ETH-RMII signal timing waveform

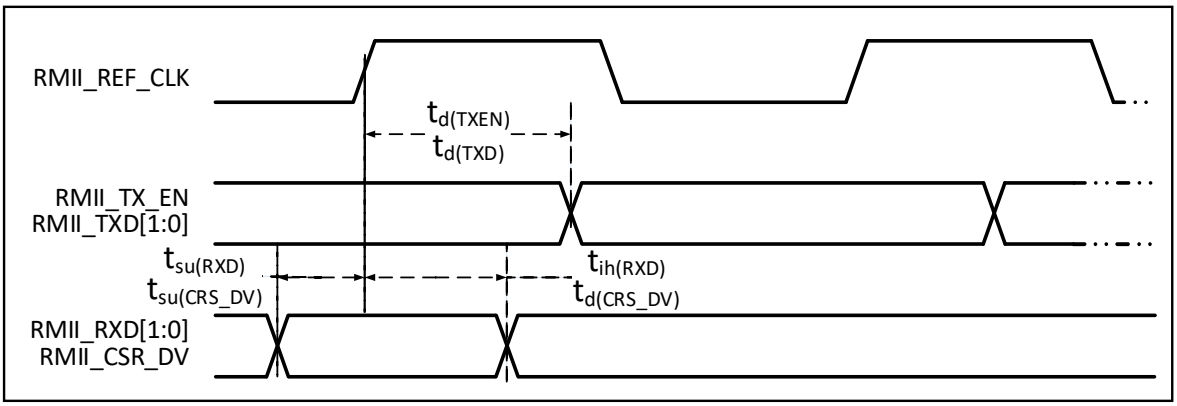


Table 4-37 RMII signal characteristics of Ethernet MAC

Symbol	Parameter	Min.	Typ.	Max.	Unit
$t_{su(RXD)}$	Setup time of received data	4			ns

$t_{ih(RXD)}$	Hold time of received data	2			
$t_{su(CRS\_DV)}$	Carrier detect signal setup time	4			
$t_{ih(CRS\_DV)}$	Carrier detect signal hold time	2			
$t_{d(TXEN)}$	Transmission enable effective delay time			16	
$t_{d(TXD)}$	Data transmission effective delay time			16	

Figure 4-27 ETH-MII signal timing waveform

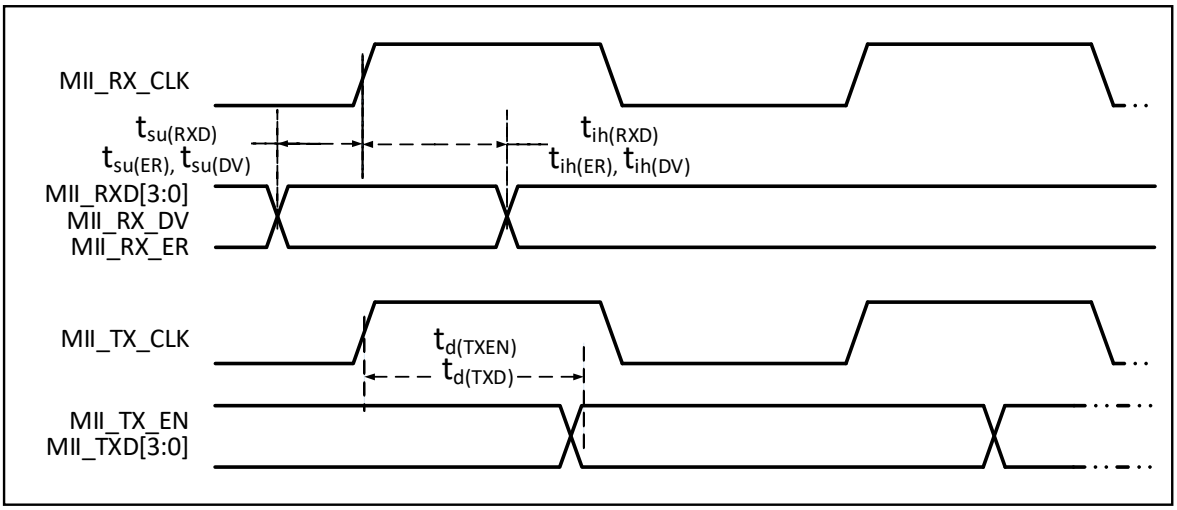


Table 4-38 MII signal characteristics of Ethernet MAC

Symbol	Parameter	Min.	Typ.	Max.	Unit
$t_{su(RXD)}$	Setup time of received data	10			ns
$t_{ih(RXD)}$	Hold time of received data	10			
$t_{su(DV)}$	Data valid signal setup time	10			
$t_{ih(DV)}$	Data valid signal hold time	10			
$t_{su(ER)}$	Error signal setup time	10			
$t_{ih(ER)}$	Error signal hold time	10			
$t_{d(TXEN)}$	Transmission enable effective delay time			16	
$t_{d(TXD)}$	Data transmission effective delay time			16	

Figure 4-28 ETH-RGMII signal timing waveform

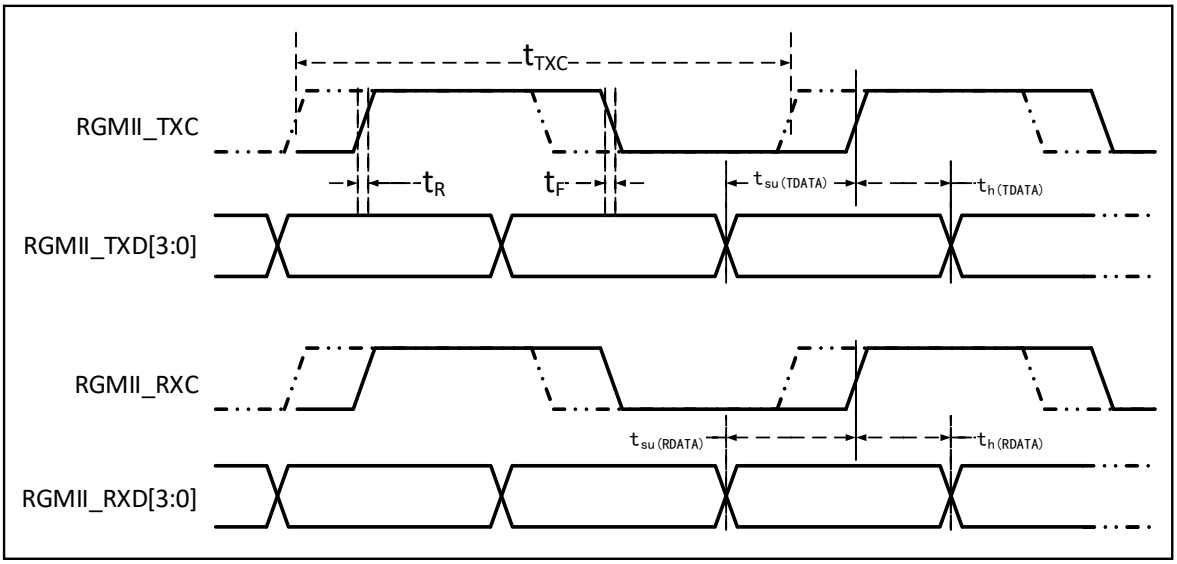


Table 4-39 RGMII signal characteristics of Ethernet MAC

Symbol	Parameter	Min.	Typ.	Max.	Unit
f_{TXC}/t_{TXC}	TXC/RXC clock frequency	7.2	8	8.8	ns
t_R	TXC/RXC rise time			2.0	
t_F	TXC/RXC fall time			2.0	
$t_{su(TDATA)}$	Transmit data setup time	1.2	2.0		
$t_{h(TDATA)}$	Transmit data hold time	1.2	2.0		
$t_{su(RDATA)}$	Input data setup time	1.2	2.0		
$t_{h(RDATA)}$	Input data hold time	1.2	2.0		

4.3.21 12- bit ADC characteristics

Table 4-40 ADC characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{DDA}	Supply voltage		2.4		3.6	V
V_{REF+}	Positive reference voltage	V_{REF+} cannot be more than V_{DDA}	2.4		V_{DDA}	V
I_{VREF}	Reference current			160	220	uA
I_{DDA}	Supply current			480	530	uA
f_{ADC}	ADC clock frequency				14	MHz
f_S	Sampling rate		0.05		1	MHz
f_{TRIG}	External trigger frequency				16	$1/f_{ADC}$
V_{AIN}	Conversion voltage range		0		V_{REF+}	V
R_{AIN}	External input impedance				50	kΩ
R_{ADC}	Sampling switch resistance			0.6	1	kΩ
C_{ADC}	Internal sample and hold capacitor			8		pF

t_{CAL}	Calibration time	applied for V203		100		$1/f_{ADC}$
		Others		40		
t_{Iat}	Injected trigger conversion latency				2	$1/f_{ADC}$
t_{Iatr}	Regular trigger conversion latency				2	$1/f_{ADC}$
t_s	Sampling time		1.5		239.5	$1/f_{ADC}$
t_{STAB}	Power-on time				1	us
t_{CONV}	Total conversion time (including sampling time)		14		252	$1/f_{ADC}$

Note: Above parameters are guaranteed by design.

Formula: Maximum R_{AIN}

$$R_{AIN} < \frac{Ts}{f_{ADC} \times C_{ADC} \times \ln 2^{N+2}} - R_{ADC}$$

The above formula is used to determine the maximum external impedance so that the error can be less than 1/4 LSB. Where N=12 (representing 12-bit resolution).

Table 4-41 Maximum R_{AIN} when f_{ADC} = 14MHz

T_S(cycle)	t_S (us)	Maximum R_{AIN}(kΩ)
1.5	0.11	0.4
7.5	0.54	5.9
13.5	0.96	11.4
28.5	2.04	25.2
41.5	2.96	37.2
55.5	3.96	50
71.5	5.11	Invalid
239.5	17.1	Invalid

Table 4-42 ADC error

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
EO	Offset error	f_{PCLK2} = 56 MHz, f_{ADC} = 14 MHz, R_{AIN} < 10 kΩ, V_{DDA} = 3.3V		±2		LSB
ED	Differential nonlinearity error			±0.5	±3	
EL	Integral nonlinearity error			±1	±4	

C_p represents the parasitic capacitance on the PCB and the pad (about 5pF), which may be related to the quality of the pad and PCB layout. A larger C_p value will reduce the conversion accuracy, the solution is to reduce the f_{ADC} value.

Figure 4-29 ADC typical connection diagram

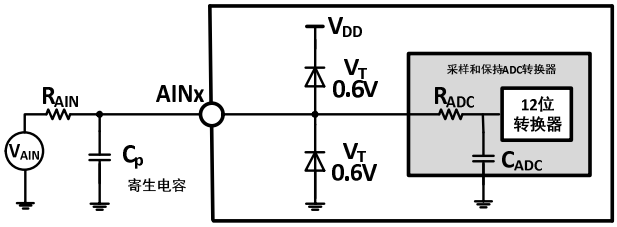
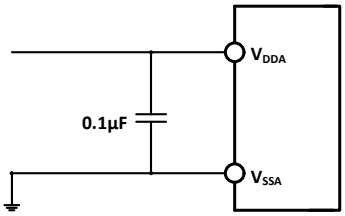


Figure 4-30 Analog power supply and decoupling circuit reference



4.3.22 Temperature sensor characteristics

Table 4-43 Temperature sensor characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
R_{TS}	Measurement range of temperature sensor		-40		85	℃
A_{TSC}	Measurement range of temperature sensor after software calibration			±12		℃
Avg_Slope	Average slope (negative temperature coefficient)		3.8	4.3	4.7	mV/℃
V_{25}	Voltage at 25℃		1.34	1.40	1.46	V
T_{S_temp}	ADC sampling time when reading temperature	f_{ADC} = 14MHz			17.1	us

4.3.23 DAC characteristics

Table 4-44 DAC characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{DDA}	Supply voltage		2.4	3.3	3.6	V
V_{REF+}	Positive reference voltage	V_{REF+} cannot be more than V_{DDA}	2.4	3.3	3.6	V
R_L(1)	Load resistance when the buffer is on		5			kΩ
C_L(1)	Load capacitance when the buffer is on				50	pF
V_{OUT_MIN}(1)	12-bit DAC conversion when the buffer is on		3			mV
V_{OUT_MAX}(1)					V_{REF+}-0.01	V
V_{OUT_MIN}(1)	12-bit DAC conversion when the buffer is off			0.1		mV
V_{OUT_MAX}(1)					V_{REF+}-1LSB	V
I_{VREF+}(1)	No load			60		uA
	No load, when V_{REF+}=3.6V, the input value is 0xF1C			202		
I_{DDA}(1)	No load, input value 0x800			211		uA
	No load, when V_{REF+}=3.6V, the input value is 0xF1C			193		
DNL	Differential nonlinearity error			±2		LSB
INL	Integral nonlinearity error	After calibration of offset error and gain error		±4		LSB

Offset	Offset error				±8	mV
		V_{REF+}=3.6V			±10	LSB
Gain error		DAC is configured as 12 bits		±0.4		%
Amplifier gain(1)	Amplifier gain in open loop	5kΩ load (max)	80	85		dB
$t_{SETTLING}$	Setting time (full range: input codes change from minimum to maximum value, DAC_OUT reaches final value ±1 LSB)	C_{LOAD}≤50pF R_{LOAD}≥5kΩ		3	4	us
Update rate	When the input code has a small change (the value changes from i to i+1LSB), the maximum frequency of the correct DAC_OUT is obtained	C_{LOAD}≤50pF R_{LOAD}≥5kΩ			1	MS/s
t_{WAKEUP}	Time to wake up from off state (PDV18 changes from 1 to 0)	C_{LOAD}≤50pF, R_{LOAD}≥5kΩ, input codes between the minimum and maximum possible values		6.5	10	us
PSRR+(1)	Power supply rejection ratio (relative to V_{DDA}) (static DC measurement)	No R_{LOAD}, C_{LOAD}≤50pF		-100	-75	dB

Note: 1. The values are guaranteed by design, not tested in production.

4.3.24 OPA characteristics

Table 4-45 OPA characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{DDA}	Supply voltage		2.4	3.3	3.6	V
C_{MIR}	Common mode input voltage		0		V_{DDA}-0.9	V
$V_{IOFFSET}$	Input offset voltage			1.5	6	mV
I_{LOAD}	Drive current				600	uA
$I_{DDOPAMP}$	Current consumption	No load, static mode		195		uA
C_{MRR}(1)	Common mode rejection ratio	@1kHz		96		dB
P_{SRR}(1)	Power supply rejection ratio	@1kHz		86		dB
A_V(1)	Open loop gain	C_{LOAD}=5pF		136		dB
G_{BW}(1)	Unit gain bandwidth	C_{LOAD}=5pF		19		MHz
P_M(1)	Phase margin	C_{LOAD}=5pF		93		
S_R(1)	Slew rate limited	C_{LOAD}=5pF		8		V/us
t_{WAKUP}(1)	Setup time from shutdown to wake up, 0.1%	Input V_{DDA}/2, C_{LOAD}=5pF,R_{LOAD}=4kΩ			368	ns
R_{LOAD}	Resistive load		4			kΩ
C_{LOAD}	Capacitive load				50	pF

V_{OHSAT}(2)	High saturation output voltage	R_{LOAD}=4kΩ, input V_{DDA}	V_{DDA}-45			mV
		R_{LOAD}=20kΩ, input V_{DDA}	V_{DDA}-10			
V_{OLSAT}(2)	Low saturation output voltage	R_{LOAD}=4kΩ, input 0			0.5	mV
		R_{LOAD}=20kΩ, input 0			0.5	
EN(1)	Equivalent input voltage noise	R_{LOAD}=4kΩ,@1kHz		83		$\frac{nv}{\sqrt{Hz}}$
		R_{LOAD}=4kΩ,@10kHz		42		

Note: 1. Above parameters are guaranteed by design.

2. The load current limits the saturated output voltage.

Chapter 5 Package and ordering information

Packages

Part No.	Package	Body size	Lead pitch	Description	Packing type
CH32V203F6P6	TSSOP20	4.4*6.5mm	0.65mm	Thin shrink small outline 20-pin patch	Tube
CH32V203G6U6	QFN28X4	4*4mm	0.4mm	Quad no-lead 28-pin	Tray
CH32V203K6T6	LQFP32	7*7mm	0.8mm	LQFP32 (7*7) patch	Tray
CH32V203K8T6	LQFP32	7*7mm	0.8mm	LQFP32 (7*7) patch	Tray
CH32V203C6T6	LQFP48	7*7mm	0.5mm	LQFP48 (7*7) patch	Tray
CH32V203C8T6	LQFP48	7*7mm	0.5mm	LQFP48 (7*7) patch	Tray
CH32V203C8U6	QFN48X7	7*7mm	0.5mm	Quad no-lead 48-pin	Tray
CH32V203RBT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V303CBT6	LQFP48	7*7mm	0.5mm	LQFP48 (7*7) patch	Tray
CH32V303RBT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V303RCT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V303VCT6	LQFP100	14*14mm	0.5mm	LQFP100 (14*14) patch	Tray
CH32V305FBP6	TSSOP20	4.4*6.5mm	0.65mm	Thin shrink small outline 20-pin patch	Tube
CH32V305RBT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V307RCT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V307WCU6	QFN68X8	8*8mm	0.4mm	Quad no-lead 68-pin	Tray
CH32V307VCT6	LQFP100	14*14mm	0.5mm	LQFP100 (14*14) patch	Tray
CH32V208GBU6	QFN28X4	4*4mm	0.4mm	Quad no-lead 28-pin	Tray
CH32V208CBU6	QFN48X5	5*5mm	0.35mm	Quad no-lead 48-pin	Tray
CH32V208RBT6	LQFP64M	10*10mm	0.5mm	LQFP64M (10*10) patch	Tray
CH32V208WBU6	QFN68X8	8*8mm	0.4mm	Quad no-lead 68-pin	Tray

Note: 1. The packing type of QFP/QFN is usually tray. Please confirm with the packaging factory for specific part number.

2. Size of tray: The size of Tray is generally a uniform size (322.6*135.9*7.62). There are differences in the size of the restriction holes for different package types, and there are differences between different packaging factories for tubes, please confirm with the manufacturer for details.

Note: All dimensions are in millimeters. The pin center spacing values are nominal values, with no error. And the error of other dimensions is not more than ±0.2mm or 10%.

Figure 5-1 TSSOP20 outline

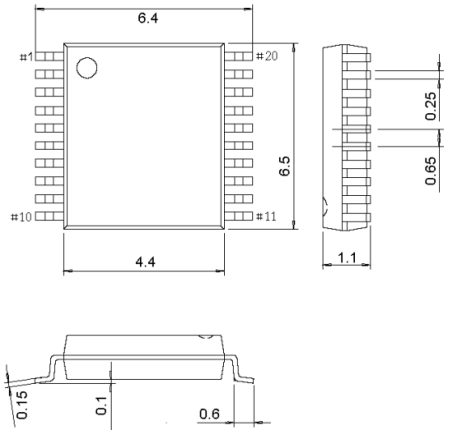


Figure 5-2 QFN28X4 outline

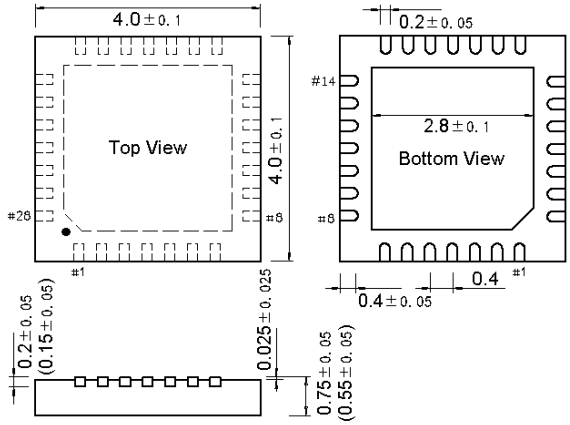


Figure 5-3 QFN48X5 outline

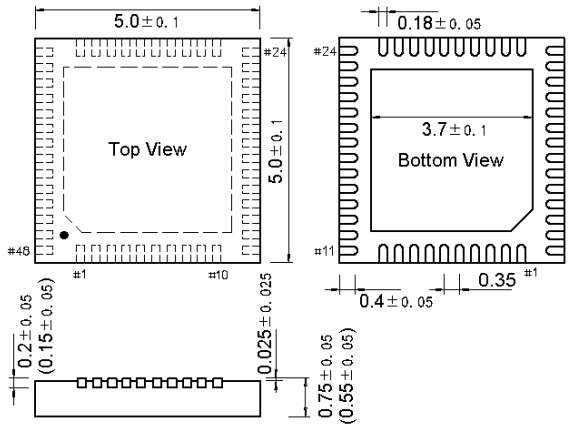


Figure 5-4 QFN48X7 outline

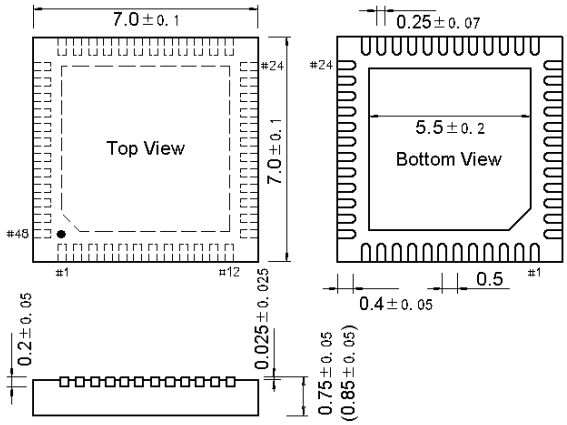


Figure 5-5 QFN68X8 outline

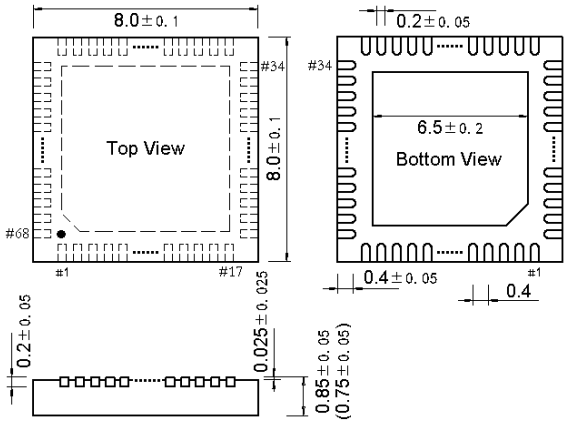


Figure 5-6 LQFP32 outline

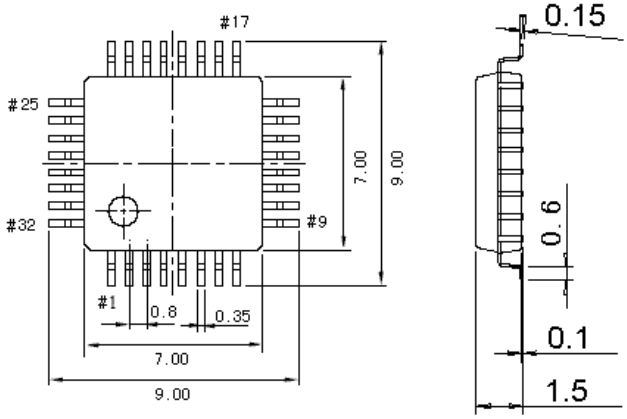


Figure 5-7 LQFP48 outline

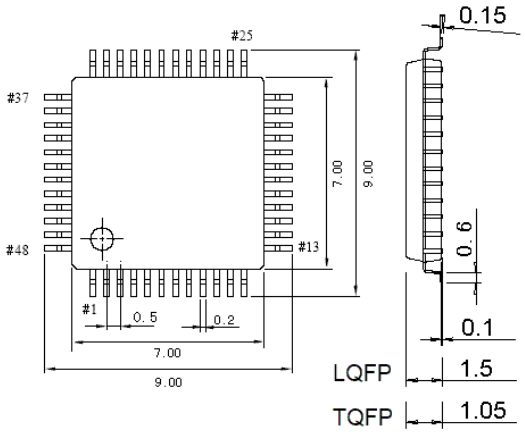


Figure 5-8 LQFP64M outline

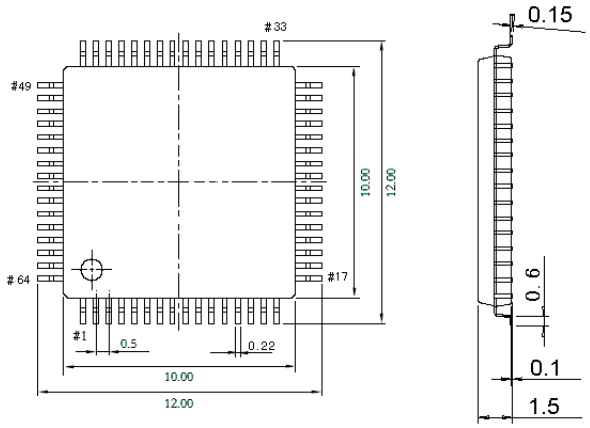
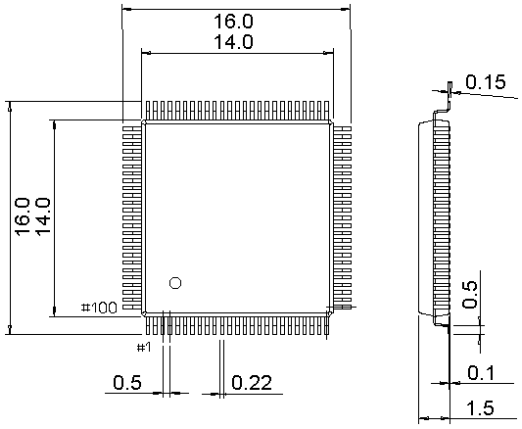


Figure 5-9 LQFP100 outline



Ordering information

Example: CH32 V 3 03 R 8 T 6

Device family

F = ARM-based

V = RISC-V-based

Product type

0 = V2 core

1 = M3/V3A core, clock speed @72M

2 = M3/V4B_C core, clock speed @144M

3 = V4F floating-point core, clock speed @144M

Device subfamily

03 = General purpose

05 = Connectivity (USB high speed, SDIO, dual CAN)

07 = Interconnectivity (USB high speed, dual CAN, Ethernet, DVP, SDIO, FSMC)

08 = Wireless (BLE5.3, CAN, USB, Ethernet)

Pin count

G = 28 pins K = 32 pins F = 20 pins

T = 36 pins C = 48 pins

R = 64 pins W = 68 pins

V = 100 pins Z = 144 pins

Flash memory size

6 = 32 Kbytes of flash memory

8 = 64 Kbytes of flash memory

B = 128 Kbytes of flash memory

C = 256 Kbytes of flash memory

Package

T = LQFP

U = QFN

P = TSSOP

Temperature range

6 = -40℃～85℃ (industrial-grade)

7 = -40℃～105℃ (automotive-grade 2)

3 = -40℃～125℃ (automotive-grade 1)

D = -40℃～150℃ (automotive-grade 0)